

# Overview IMST

Rüdiger Follmann



# Profile



**legal  
founded  
area**

GmbH (Ltd.)  
September 1992  
Research +  
Development  
→ ComTech solutions  
→ RF Sensor  
→ MultiMedia  
→ EMC-techniques  
→ Wireless  
technologies

**IMST is industry's center  
of competence**



# Headquarters

- 10.000 sqm site area
- 4.500 sqm overall space
- 1.500 sqm laboratories
- 300 sqm hybrid technologies



# Organisation IMST

**Prof. Dr. Ingo  
Wolff**

**Dr. Peter Waldow**

- Marketing
- Technology Transfer
- MultiMedia & Layout
- Quality Assurance
- Controlling
- EDV-Administration
- Central Services

**G. Seidel  
Systems**

**Dr. Matthias  
Rittweger  
Circuits**

**Dr. M. Geissler  
Antennas & EM**

**J. J. Borkes  
Test Centre**




- > 100 Researchers    11 Administration
- 19 PhDs            20 Students, e.t.c
- 79 Engineers

# Products and services

## Services

- System Design
- Circuit & Antenna Design
- Integrated Circuit Design
- Active & Passive Device Modeling
- RF & Antenna Measurements
- Channel Sounder Measurements
- EMC - Tests
- Mobile Phone Tests
- Technical Consulting and [seminars](#)

## Products

-  Coplanar Design Library  
Add-On to Agilent EEsof's ADS
-  Advanced 3D EM Simulation Software
-  State-of-the-art HEMT, MESFET, LDMOS models and Parameter Extraction
- **MultiLib**<sup>TM</sup> Design Library for LTCC/PCB multi-layered circuits  
Add-On to Agilent EEsof's ADS

# Measurements, models and extractions

Rüdiger Follmann



# Contents

- Models
- Linear part
- Nonlinear part
- Current measurements
- S-parameter measurements
- Power measurements
- Noise
- Verification



# Ways of modeling

- **Physical models:** Particle models or semiconductor equations
- **Table based models:** Bias dependent S-parameters are saved in a table
- **Mathematical models:** Transfer behavior is described by mathematical functions
- **Equivalent circuits:** Physical behavior is emulated by lumped elements





# Ways of modeling

## Linear models

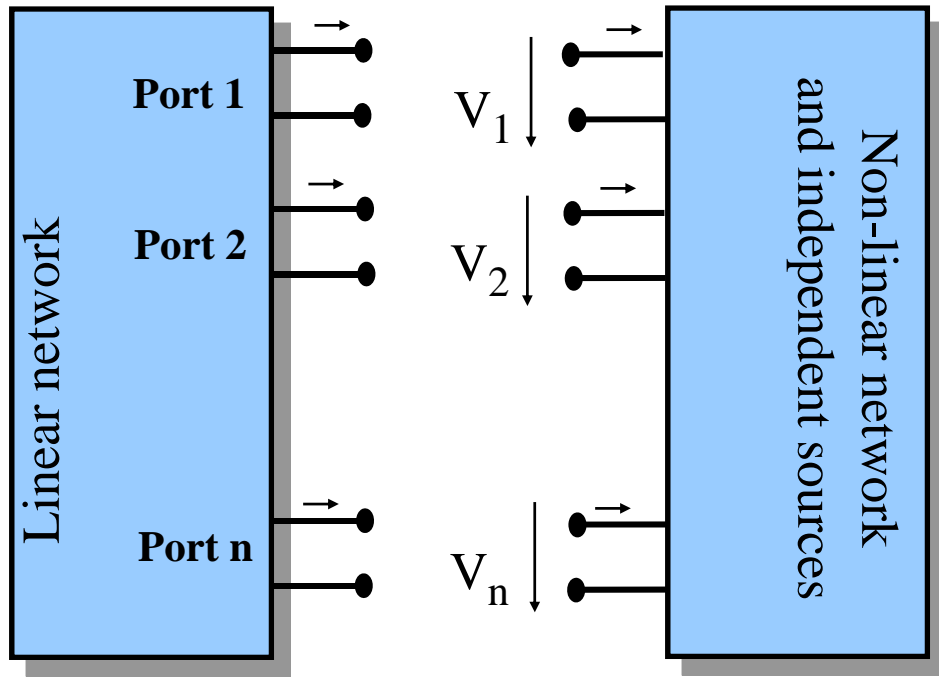
- Description of DC behavior
- Description of RF behavior, e.g. in dependence of bias point. Only small signal amplitudes close to bias point are allowed

## Non-linear models

- Large signal amplitudes and change of bias point (Harmonic balance).



# Harmonic balance



Only linear elements

Only non-linear elements

HB is a hybrid between time- and frequency domain calculations.

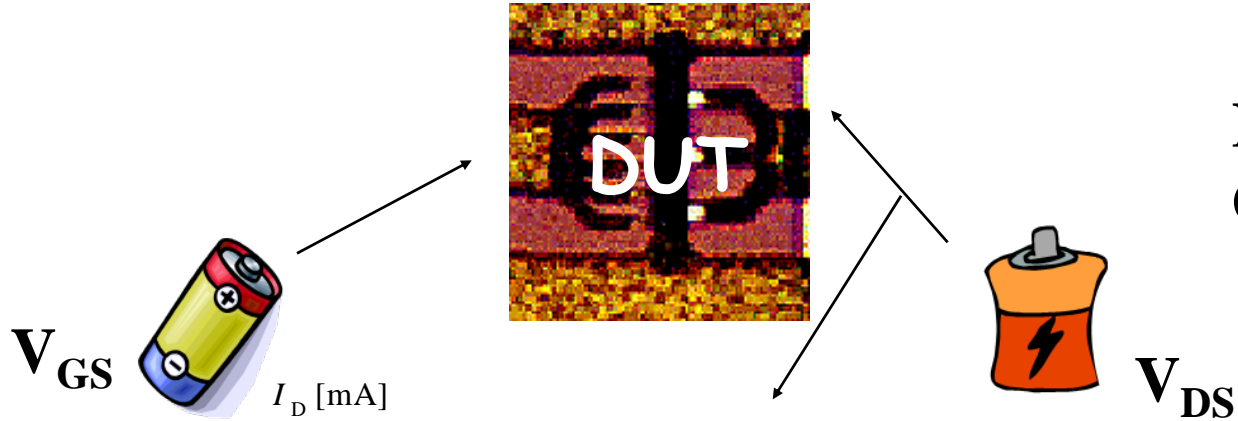
Non-linear part is calculated in time domain, linearer part in frequency domain

Voltages and currents at each port are balanced, until they are equal for both part of network.



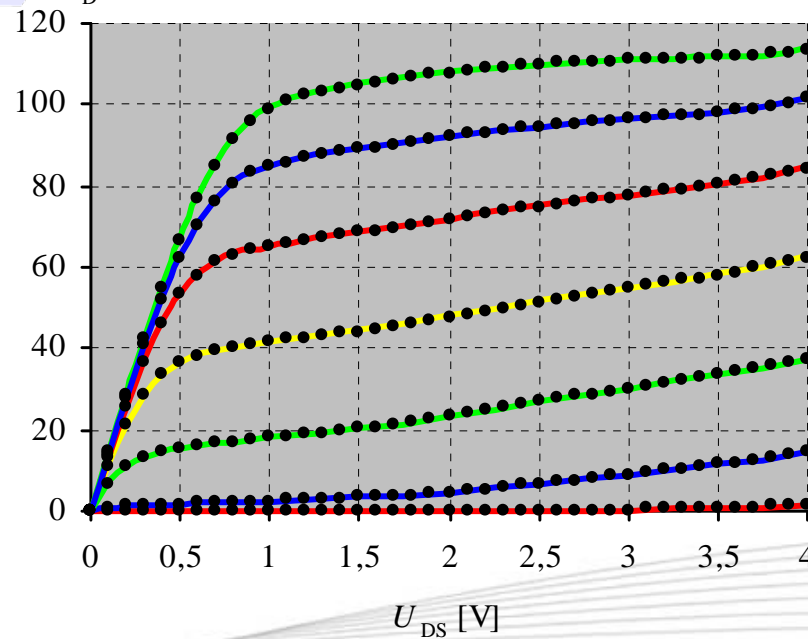
# DC measurements

Port 1  
Input



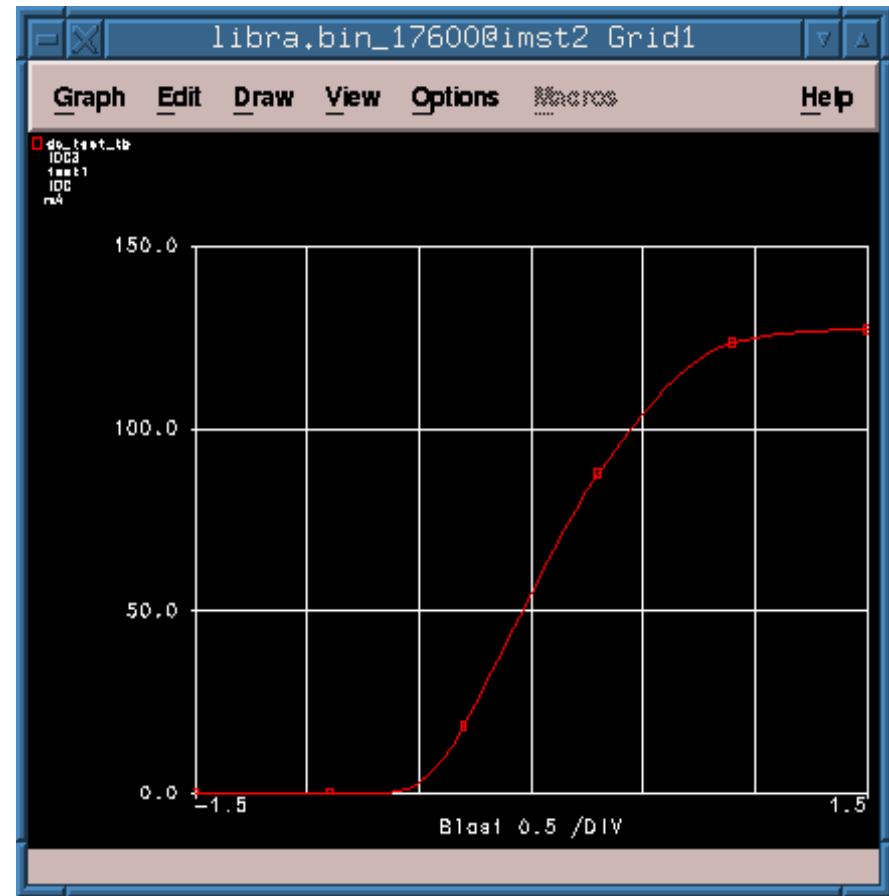
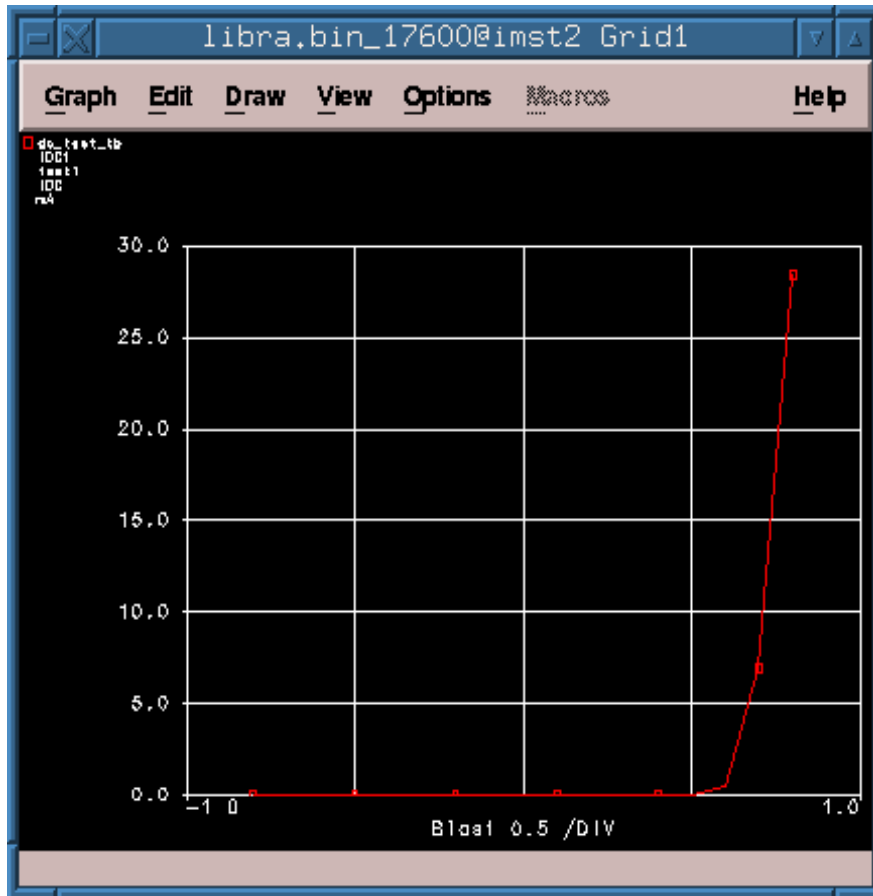
Port 2  
Output

DC IV-  
curves



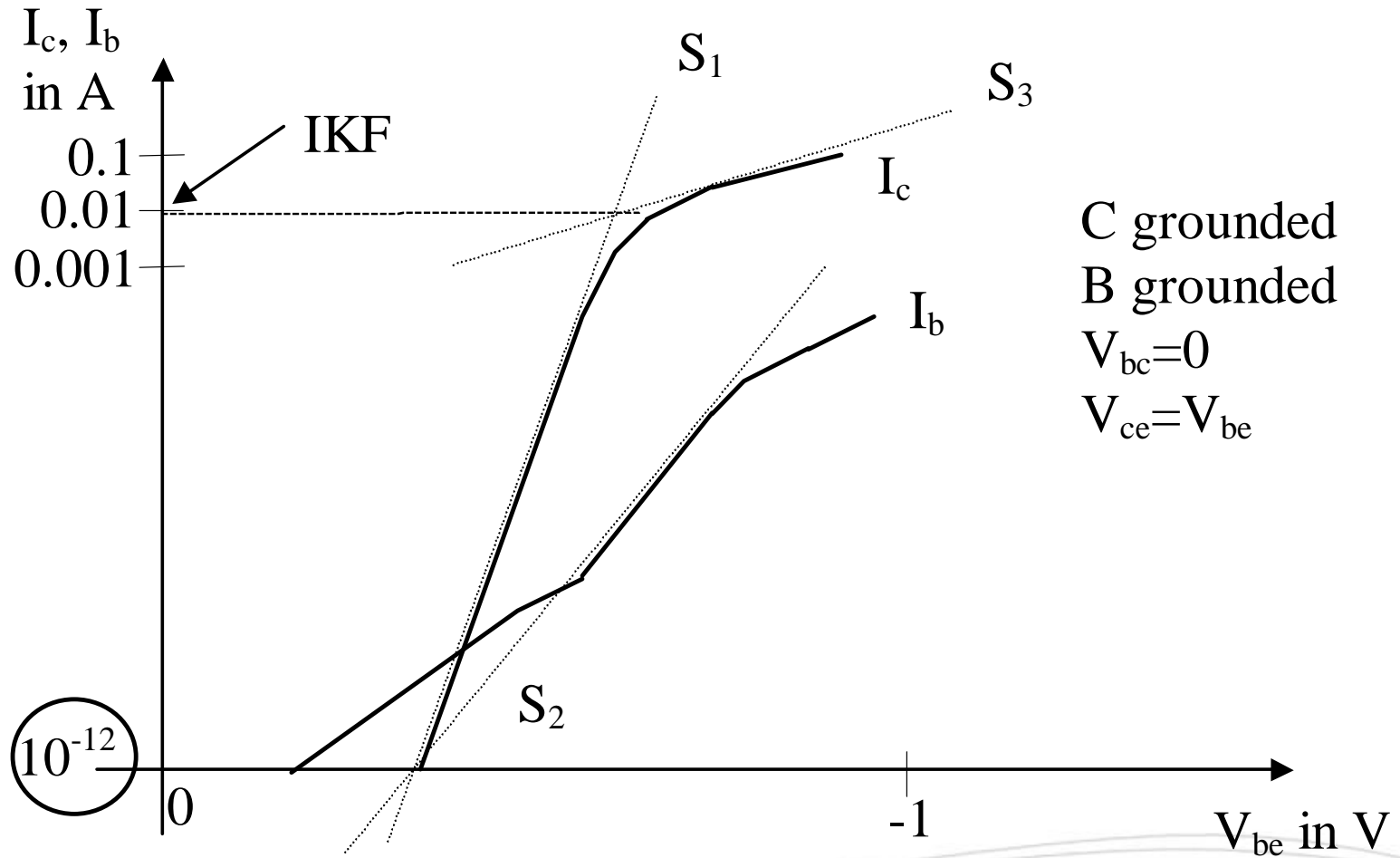


# Transistor transfer curves





# Gummel-Plots



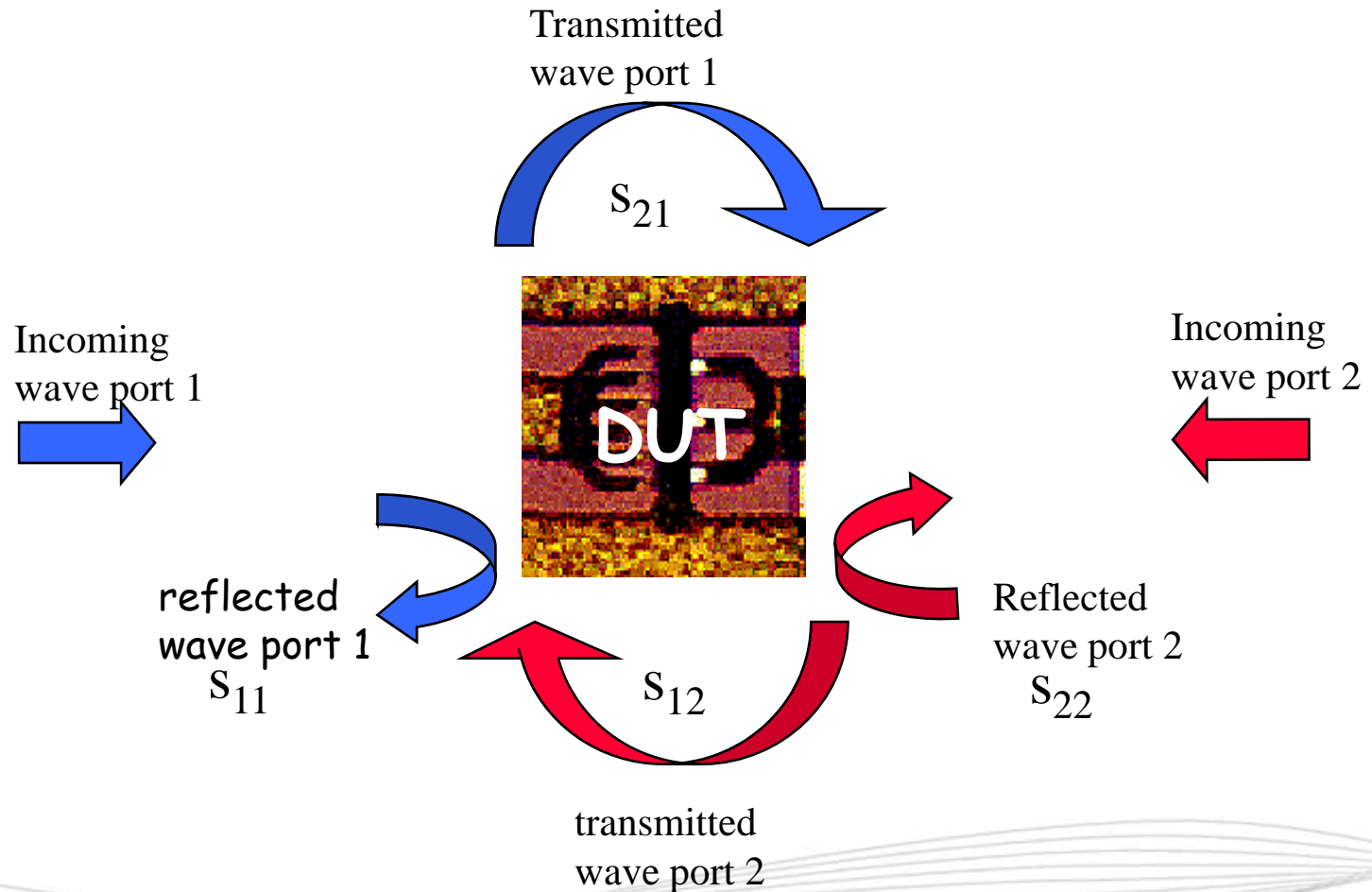
C grounded  
B grounded  
 $V_{bc} = 0$   
 $V_{ce} = V_{be}$





# RF measurements

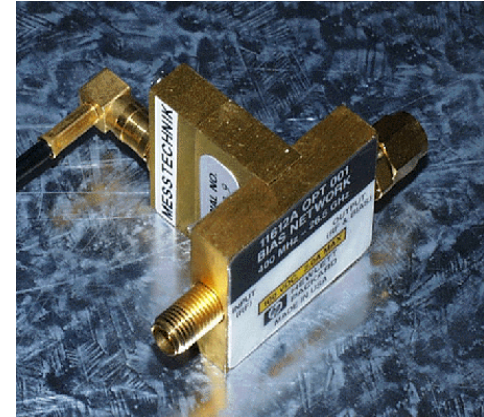
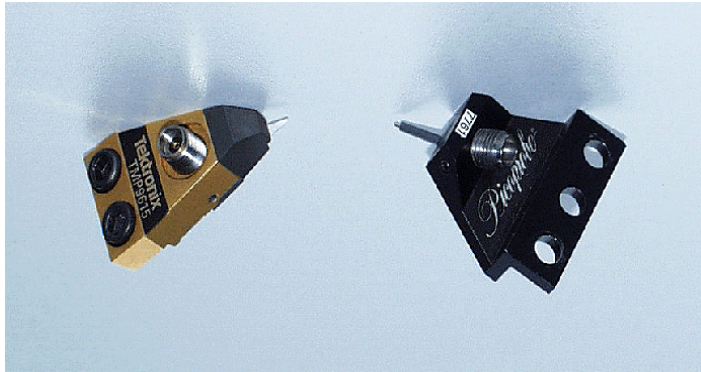
## S-parameter measurements





# RF measurements

## S-parameter measurements





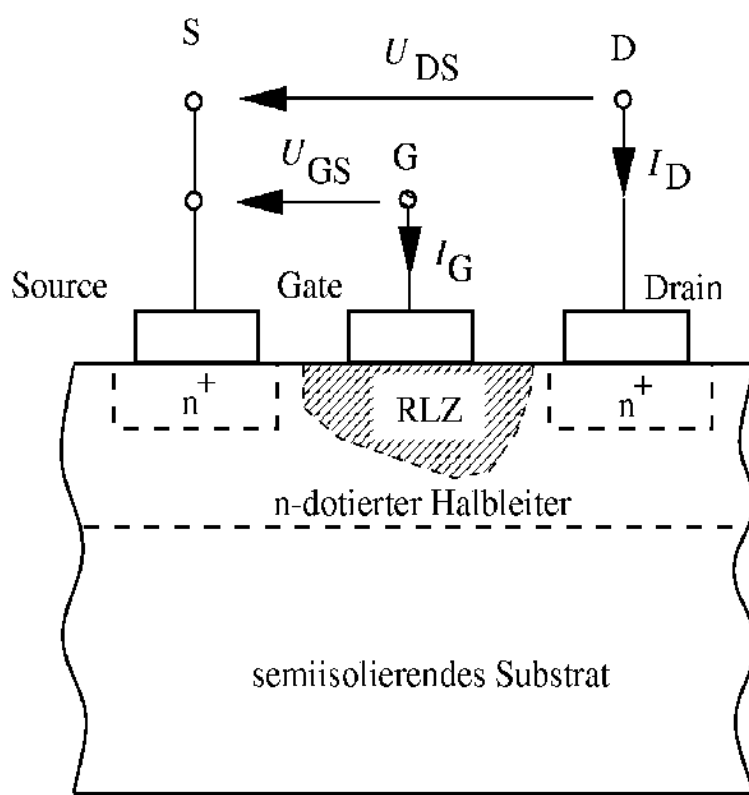
# Qualification

- Pinch-off of transistor device
- Enhancement or depletion mode
- Slope and IV curves
- Gate diode current
- amplification  $s_{21}$  and attenuation
- Compression behavior
- Other s-parameters  $< 0$  dB



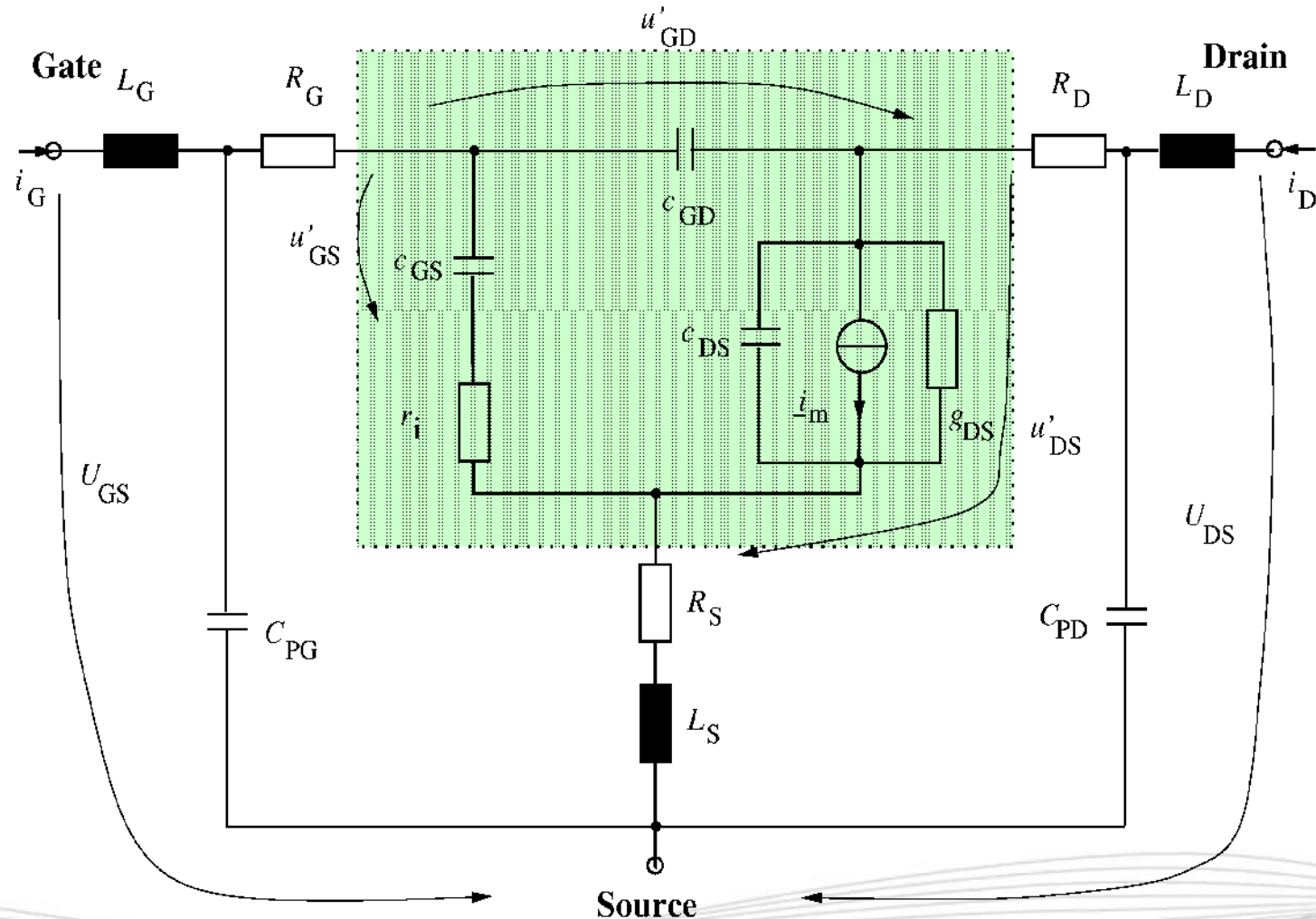


# Composition FET und equivalent circuit

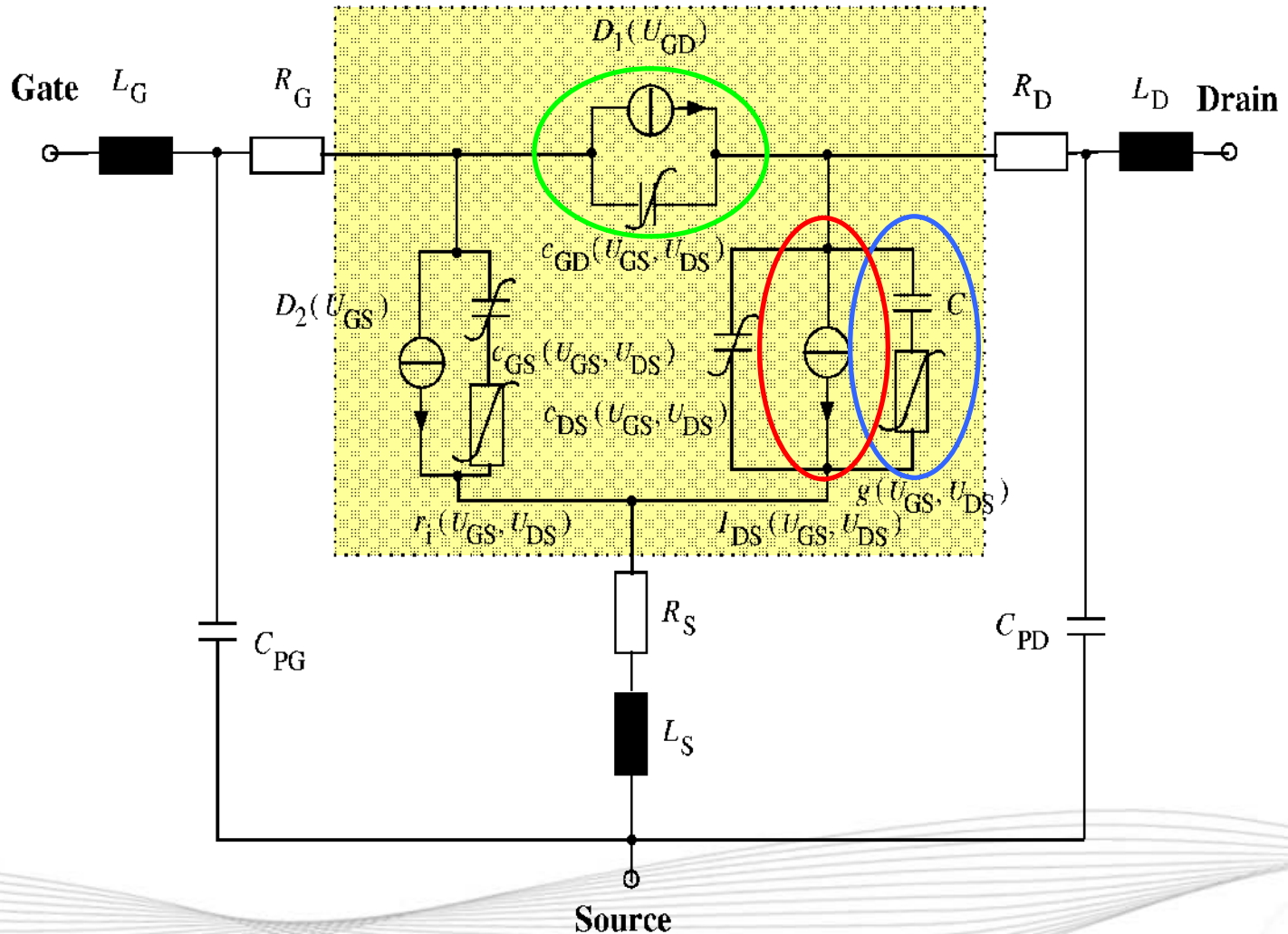


Das Bild kann nicht angezeigt werden. Dieser Computer verfügt möglicherweise über zu wenig Arbeitsspeicher, um das Bild zu öffnen, oder das Bild ist beschädigt. Starten Sie den Computer neu, und öffnen Sie dann erneut die Datei. Wenn weiterhin das rote x angezeigt wird, müssen Sie das Bild möglicherweise löschen und dann erneut einfügen.

# Small signal equivalent circuit

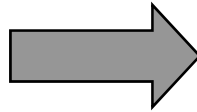


# Enhanced small signal equivalent circuit



# Parameter extraction

S-Parameter  
IV curves



Extrinsic  
elements

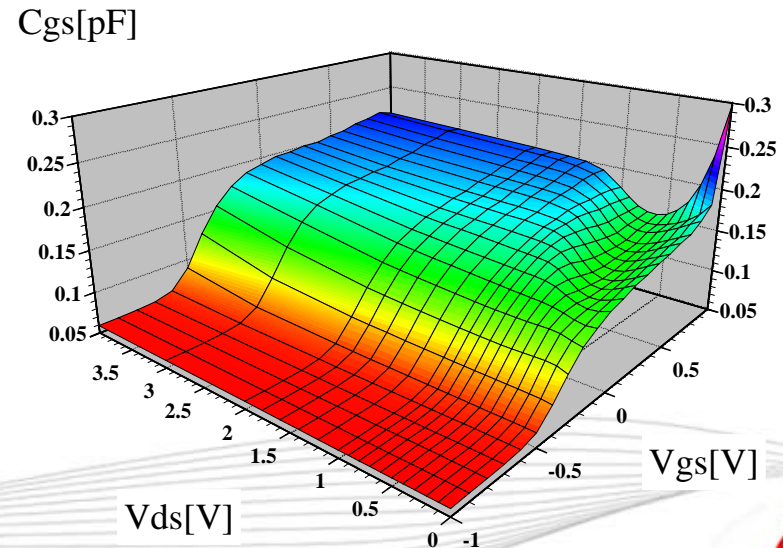
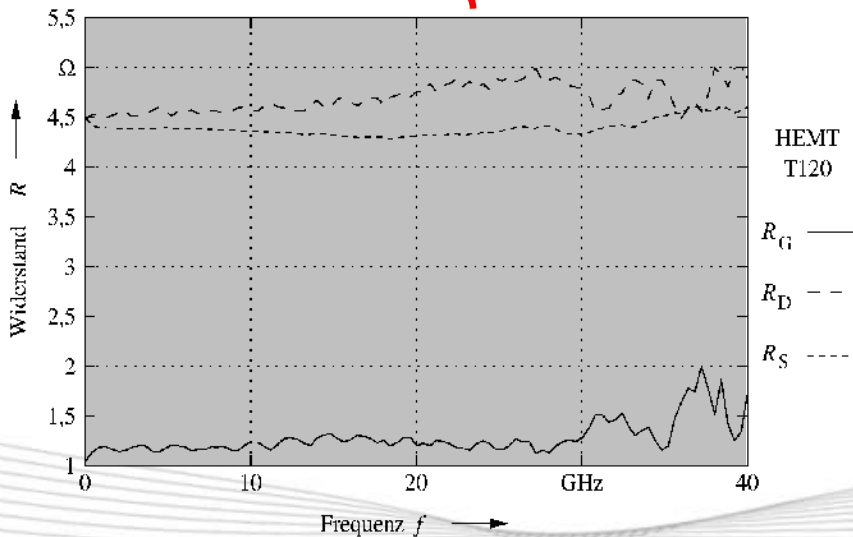


Intrinsic  
elements



$$R_S = \text{Re}\{z_{12}\}$$

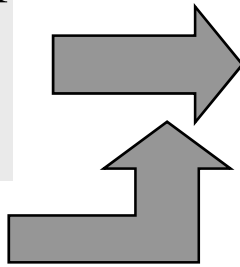
$$C_{GS}(V_{GS}, V_{DS}) = \sum_{f=f_1}^{f_2} \frac{1}{\omega} \left( \text{Im}\{y_{11}(V_{GS}, V_{DS})\} + \text{Im}\{y_{12}(V_{GS}, V_{DS})\} \right) / (n_{f2} - n_{f1})$$



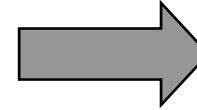


# Parameter extraction

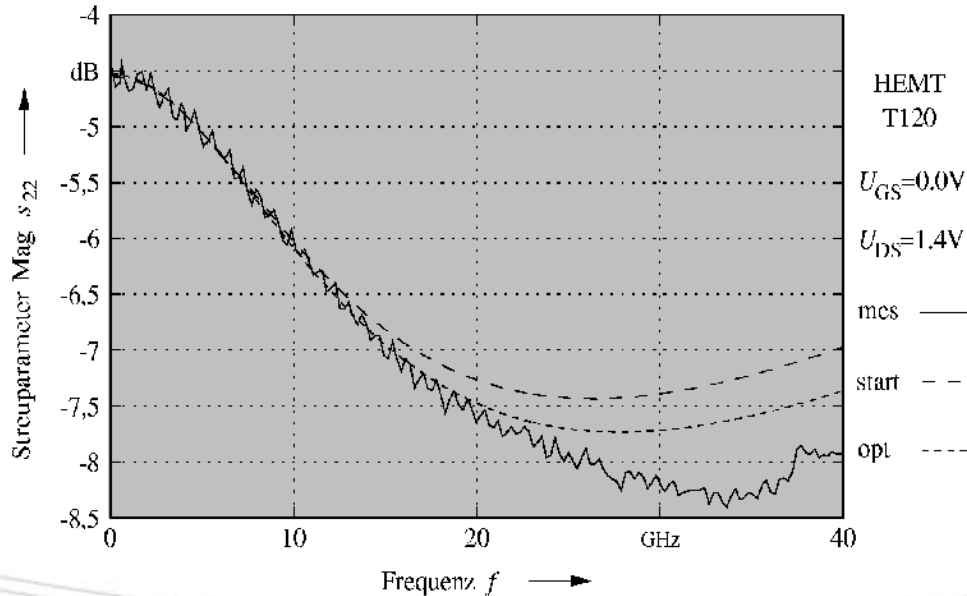
Optimization of  
intrinsic  
elements



Calculation of  
conductance  $g$



De-embedding  
of  
voltages



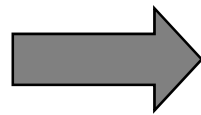
$$V'_{GS} = V_{GS} - I_{DS} R_S$$

$$V'_{DS} = V_{DS} - I_{DS} (R_D + R_S)$$



# Parameterextraktion

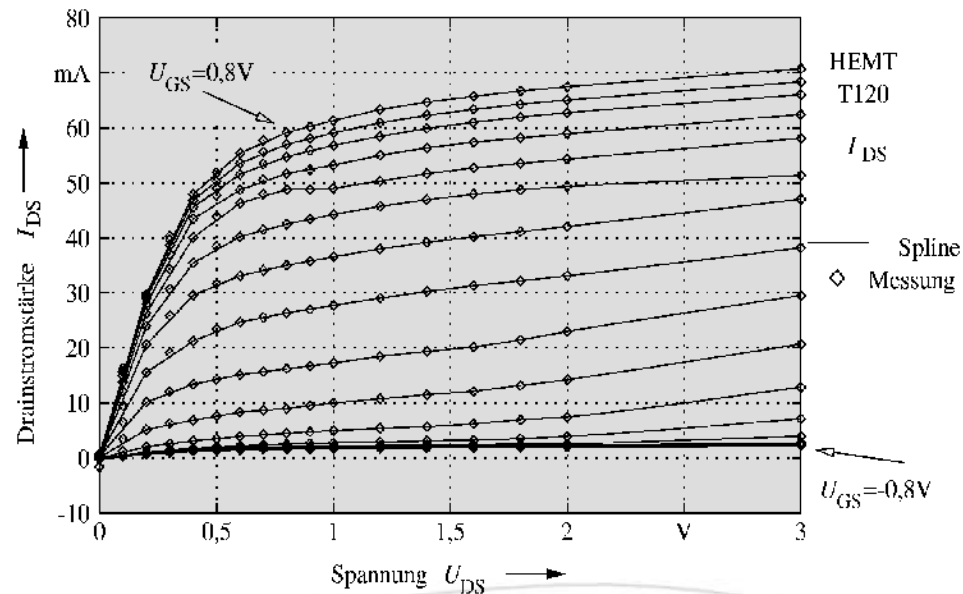
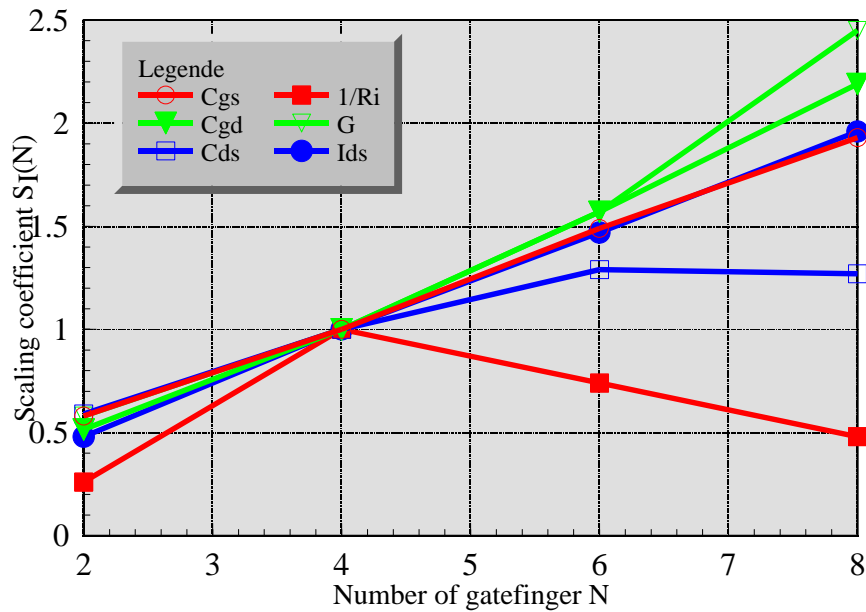
Calculation of scaling and noise parameters



Description of intrinsic elements



Store the Simulation file



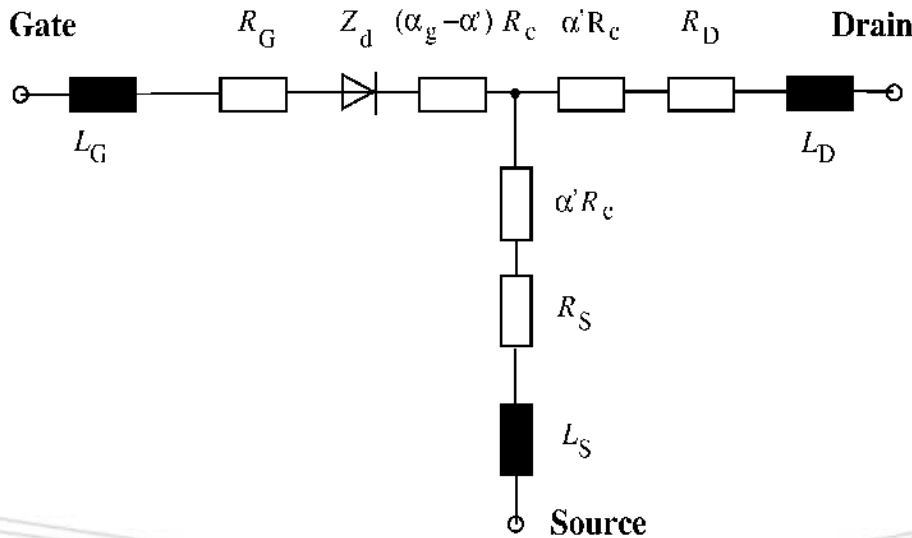
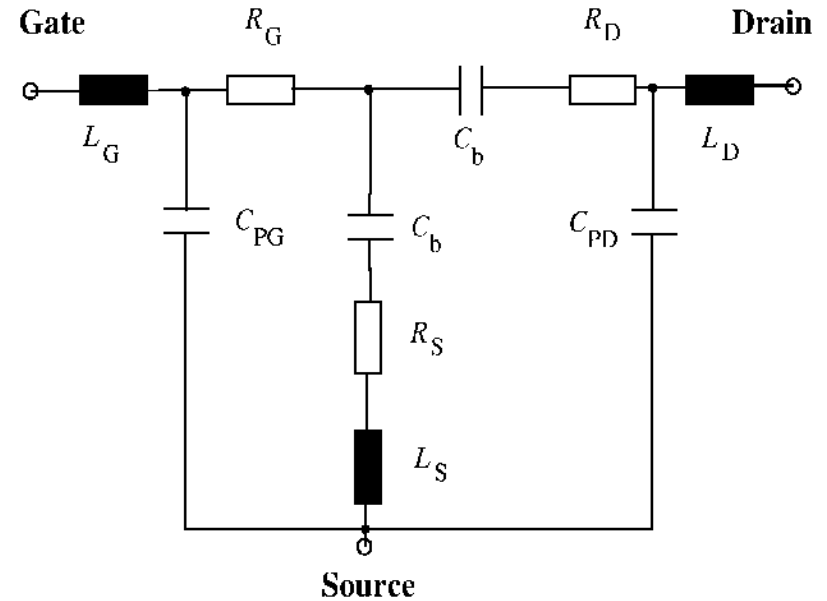
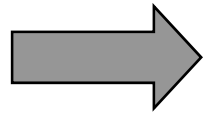


# Extraction of extrinsic elements

## Extraction of capacitances

$$V_{GS} < V_p$$

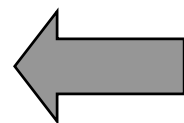
$$V_{DS} = 0 \text{ V}$$



## Extraction of inductances and resistors

$$V_{GS} > 0 \text{ V}$$

$$V_{DS} = 0 \text{ V}$$



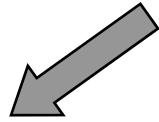


# Extraction of intrinsic elements

$$\underline{S} \rightarrow \underline{Z}$$



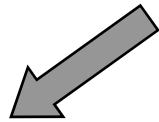
$$\begin{pmatrix} \underline{z}_{11} - j\omega L_G & \underline{z}_{12} \\ \underline{z}_{21} & \underline{z}_{22} - j\omega L_D \end{pmatrix}$$



$$\underline{Z} \rightarrow \underline{Y}$$



$$\begin{pmatrix} \underline{y}_{11} - j\omega C_{PG} & \underline{y}_{12} \\ \underline{y}_{21} & \underline{y}_{22} - j\omega C_{PD} \end{pmatrix}$$



$$\underline{Y} \rightarrow \underline{Z}$$



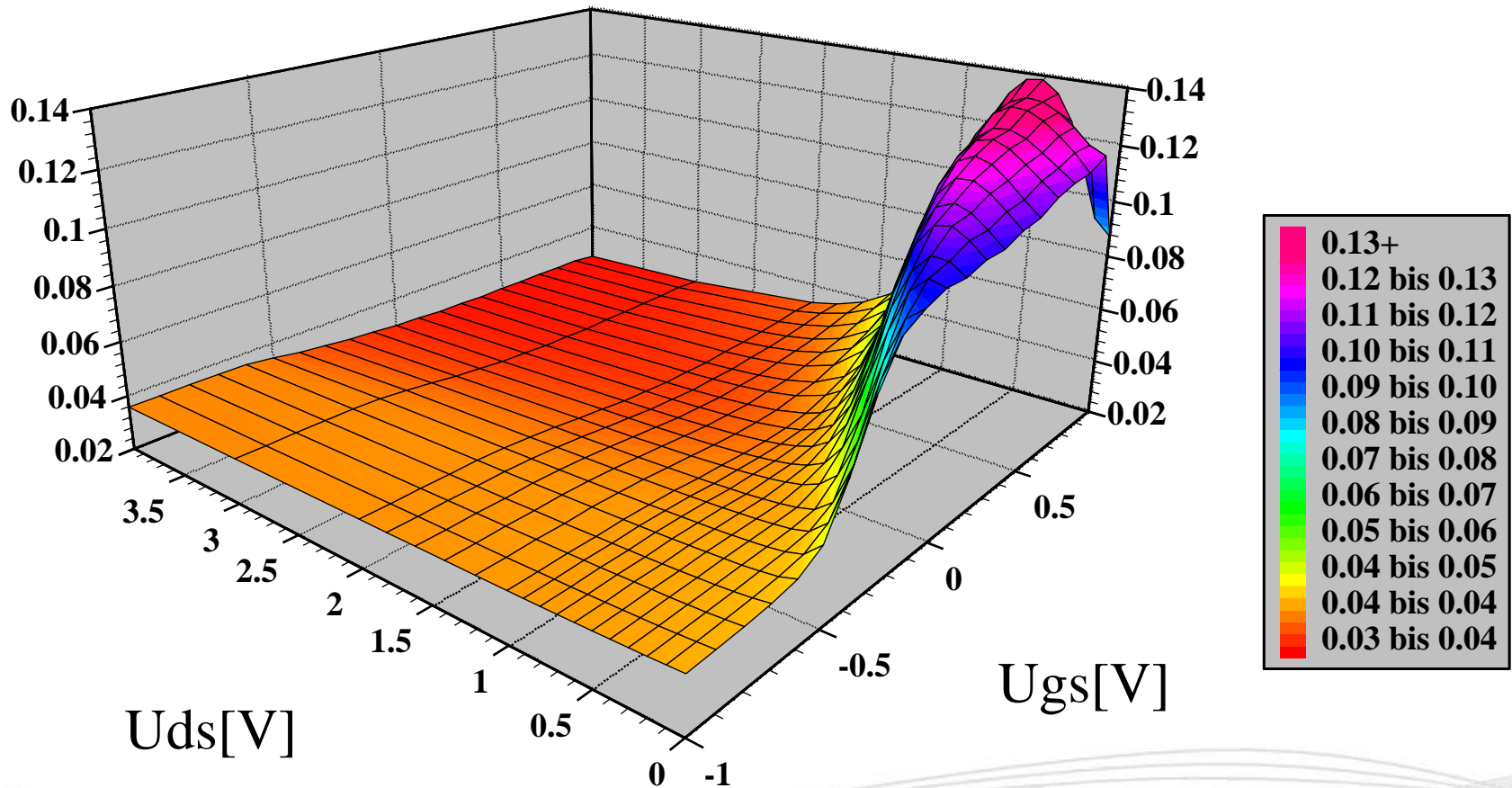
$$\begin{pmatrix} \underline{z}_{11} - R_S - R_G - j\omega L_S & \underline{z}_{12} - R_S - j\omega L_S \\ \underline{z}_{21} - R_S - j\omega L_S & \underline{z}_{22} - R_S - R_D - j\omega L_S \end{pmatrix}$$





# Extraction of intrinsic elements

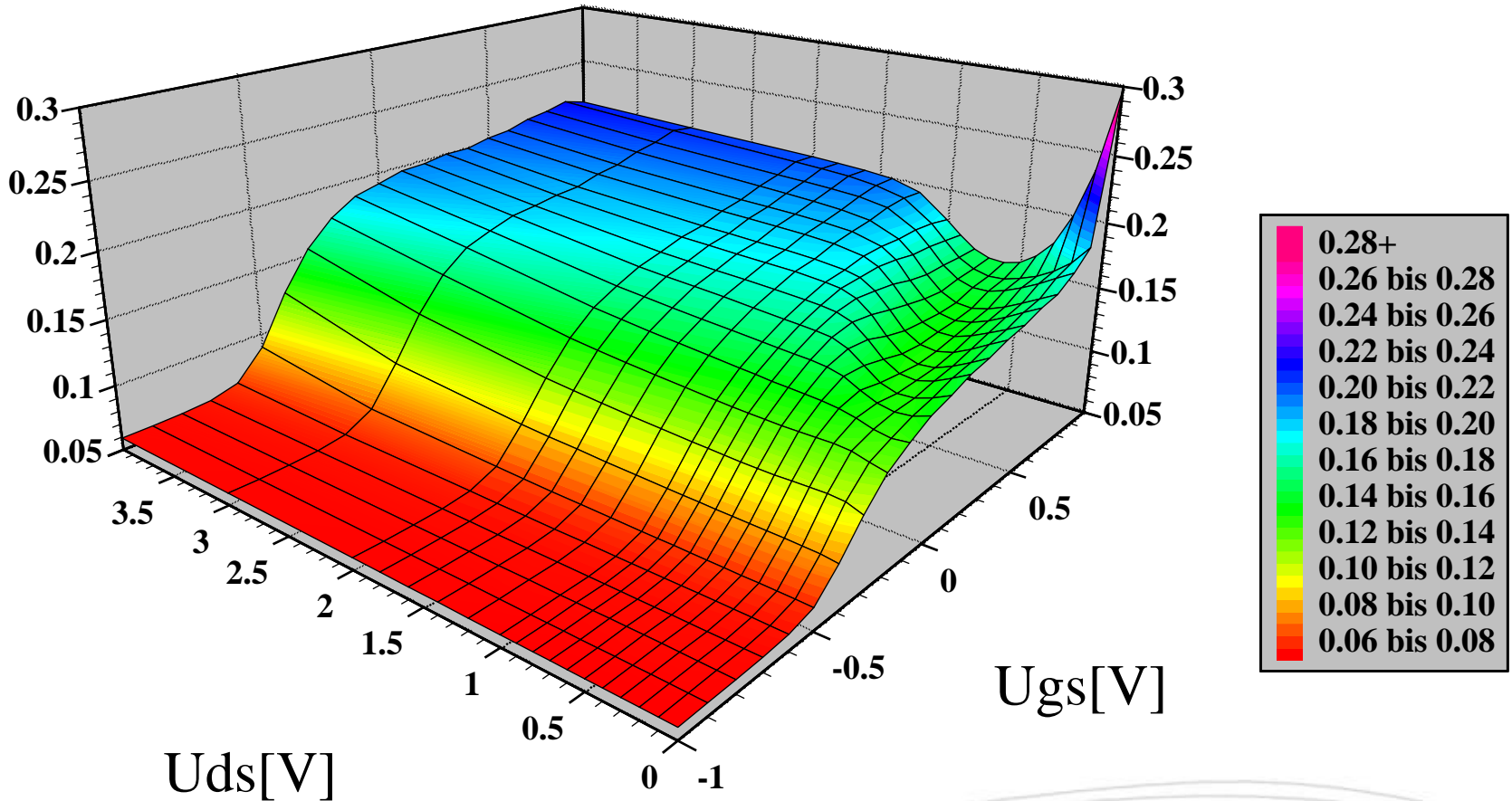
$C_{gd}[\text{pF}]$





# Extraction of intrinsic elements

$C_{gs}$ [pF]

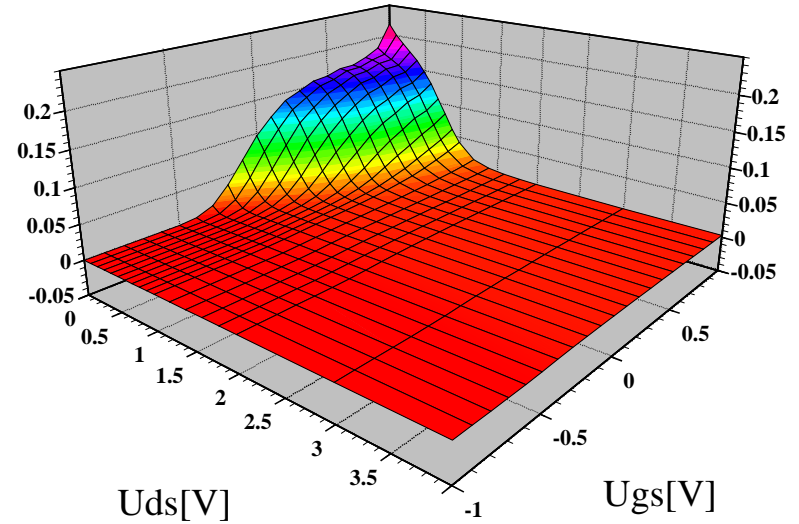




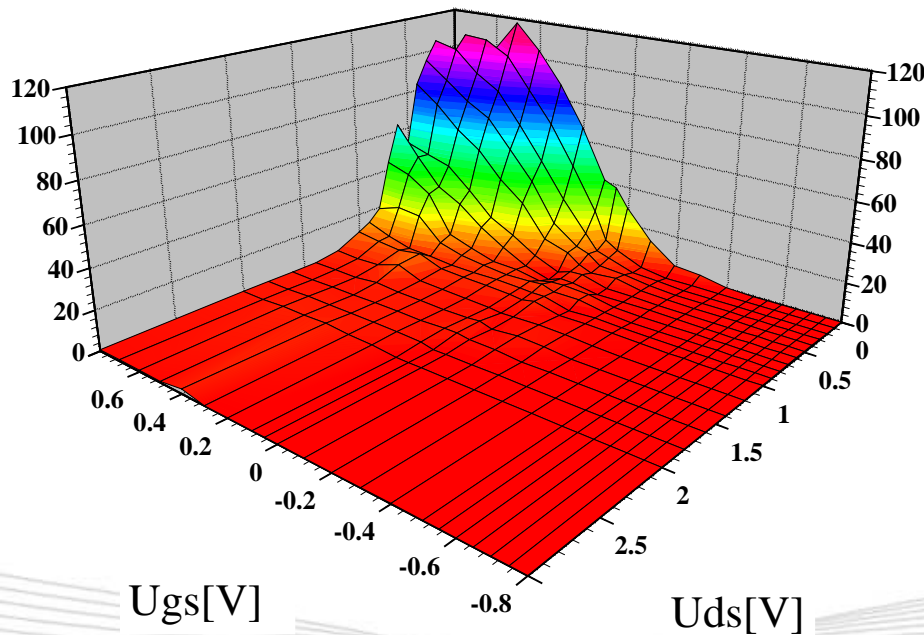
# Calculation of output conductance

## Extraction of output conductance $g$ using optimizing process

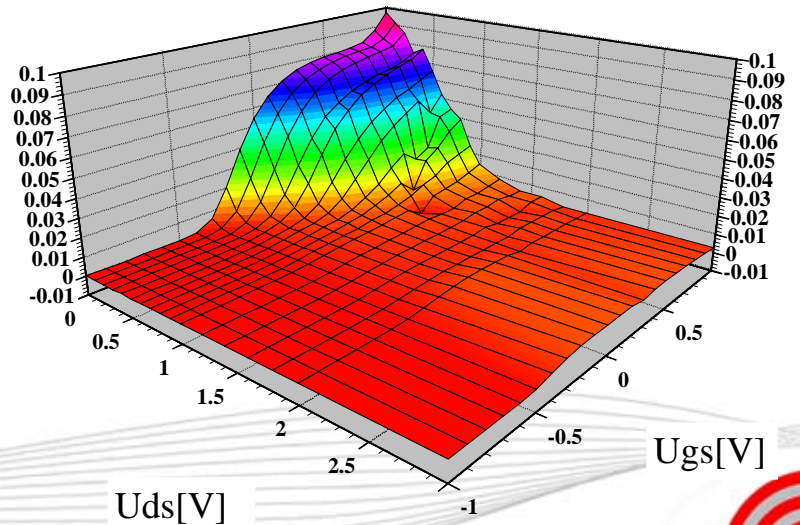
$g_d$  (HF) [S]



$g$  [mS]



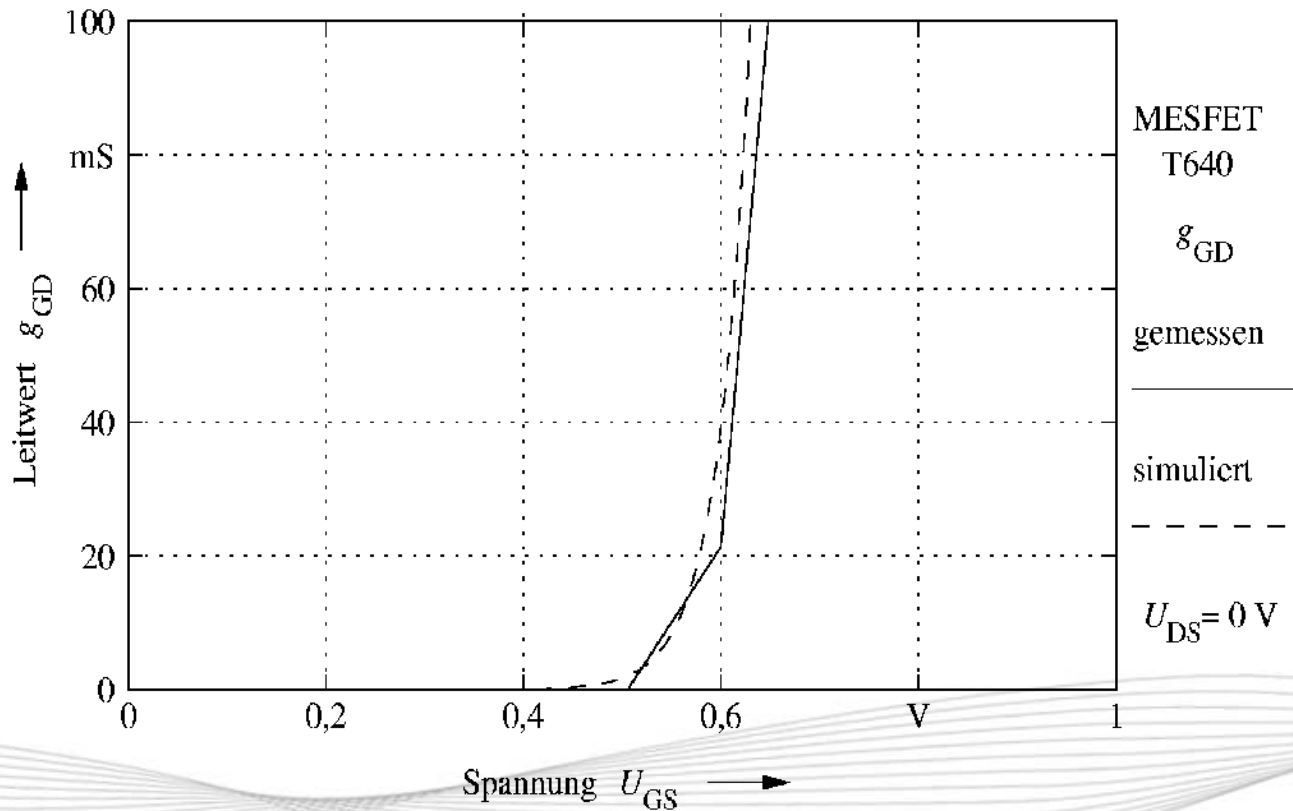
$g_d$  (DC) [S]





# Extraction of $I_S$ and $n$

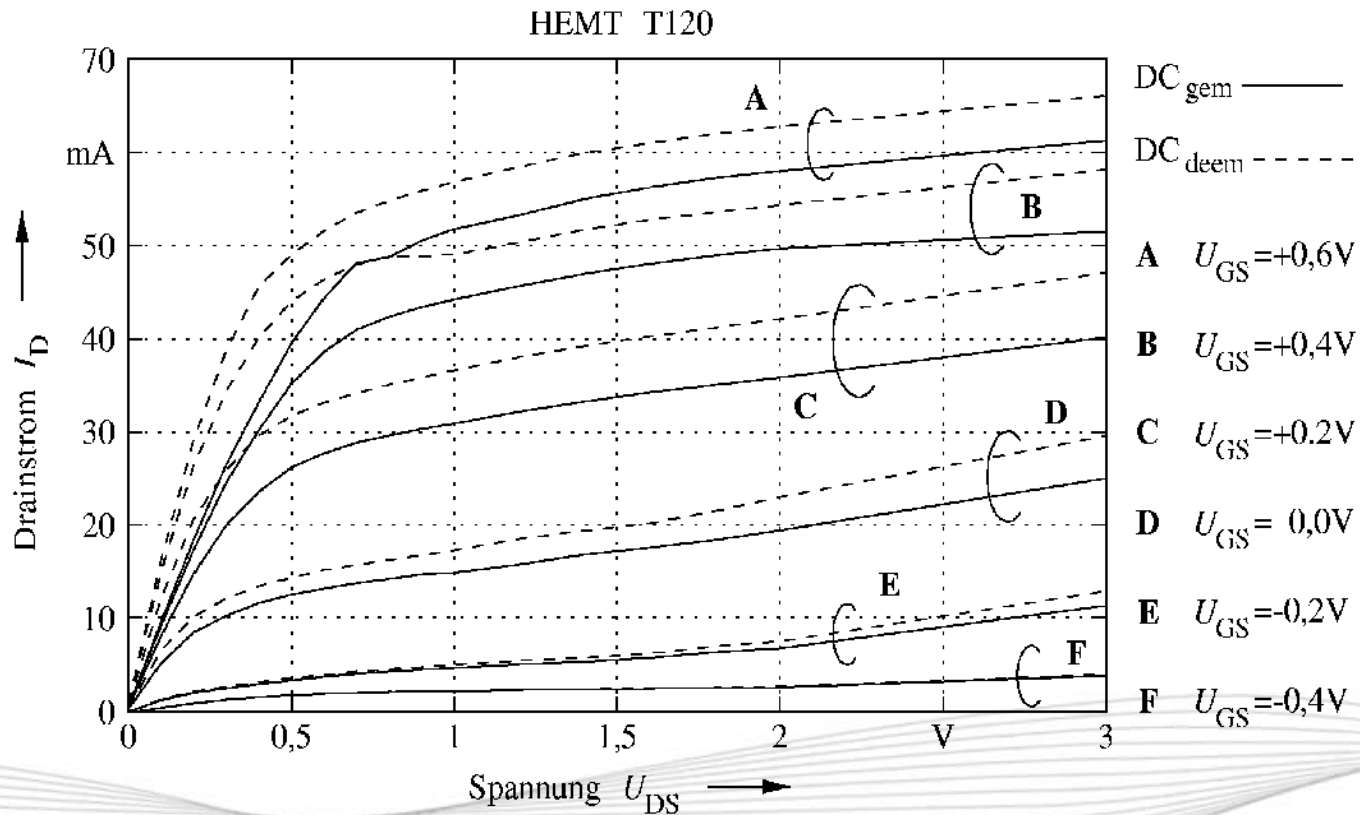
$$\operatorname{Re} \left\{ \underline{y}_{12} \right\} = - \frac{dI_{d1}}{dU_{GD}} = - \frac{I_S}{nU_t} \exp\left( \frac{U_{GD}}{nU_t} \right)$$



# Outer and inner voltages

$$V'_{GS} = V_{GS} - I_{DS} R_S$$

$$V'_{DS} = V_{DS} - I_{DS} (R_D + R_S)$$



# Description of intrinsic elements

$$c_{GS} = \begin{cases} k_h + k_g U_{DS} + x_{20} & U_{DS} > 0 \\ k_h + x_{20} & \text{sonst} \end{cases}$$

$$k_a = \begin{cases} x_0 (U_{GS} - x_1)^2 & U_{GS} \geq x_1 \\ 0 & \text{sonst} \end{cases}$$

$$k_h = k_a (\exp(k_b (U_{DS} - k_c)^2)) + k_d (\tanh(k_e (U_{DS} - k_f)) + 1)$$

$$k_b = x_2 (\tanh(x_3 (U_{GS} - x_{17})) + 1)$$

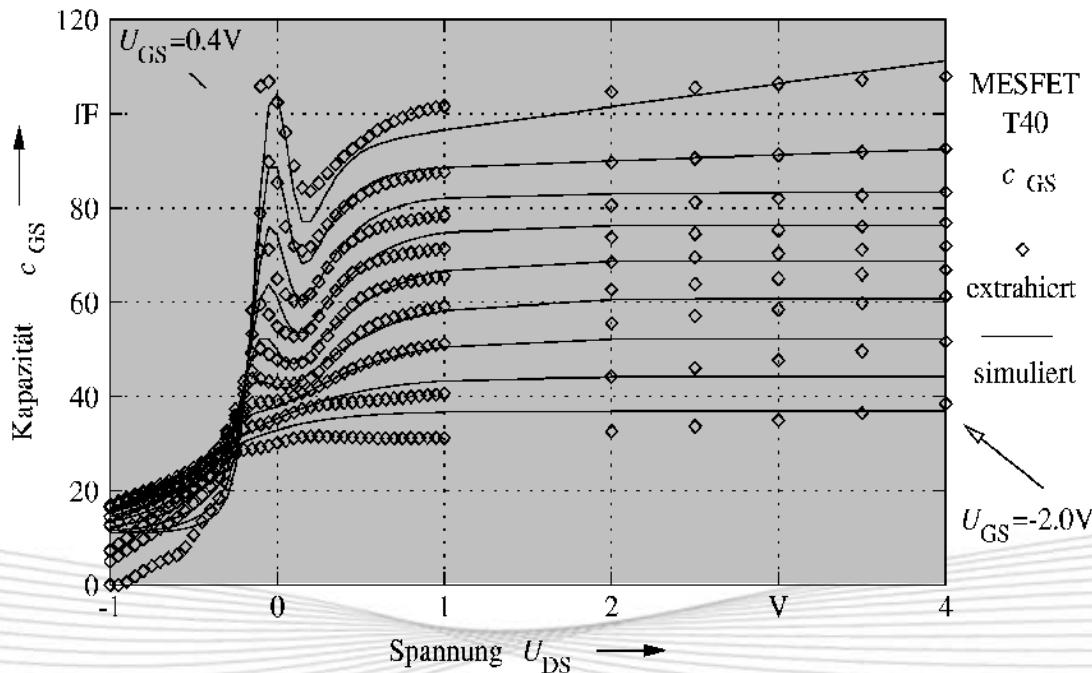
$$k_c = x_4 \exp(x_5 (U_{GS} - x_6)^2)$$

$$k_d = x_7 (\tanh(x_{21} (U_{GS} - x_8)) + 1)$$

$$k_e = x_9 (U_{GS} - x_{10})^2 + x_{11}$$

$$k_f = x_{12} \exp(x_{13} (U_{GS} - x_{14})^2) + x_{18}$$

$$k_g = x_{15} \exp(x_{16} (U_{GS} - x_{19})^2)$$





# Large signal simulation

$$Q_1(u_1) = \int_{u_{10}}^{u_1} c(\tilde{u}_1) d\tilde{u}_1$$

$$\Delta Q = \oint_{\partial\Omega} c(\tilde{u}_1) d\tilde{u}_1 = 0$$

$$Q_2(u_1, u_2) = \int_{u_{10}}^{u_1} c(\tilde{u}_1, u_2) d\tilde{u}_1 + Q'_1(u_2)$$

**Defined charge cycle**

**Trans elements**

$$C(u_1, u_2) = \sum_{i=0}^n c_i(u_1) T_i(u_2)$$

**Complete gate current**

$$i_G = i_{GS} + i_{GD}$$

$$u_{GS} = U_{GS} + u_{GS\sim} \Rightarrow \frac{du_{GS}}{dt} = \frac{du_{GS\sim}}{dt}$$

**GS-part of gate current**

$$i_{GS} = \frac{dQ_{GS}}{dt} = C'_{GS}(u_{GS}, u_{DS}) \frac{du_{GS}}{dt}$$





# Large signal simulation

$$i_{GS} = C'_{GS}(U_{GS} + u_{GS\sim}, U_{DS} + u_{DS\sim}) \frac{du_{GS\sim}}{dt}$$

**Taylor-series**

$$\begin{aligned} C'_{GS}(U_{GS} + u_{GS\sim}, U_{DS} + u_{DS\sim}) &= C'_{GS}(U_{GS}, U_{DS}) \\ &+ \left. \frac{\partial C'_{GS}(u_{GS}, u_{DS})}{\partial u_{GS}} \right|_{\substack{u_{GS}=U_{GS} \\ u_{DS}=U_{DS}}} u_{GS\sim} \\ &+ \left. \frac{\partial C'_{GS}(u_{GS}, u_{DS})}{\partial u_{DS}} \right|_{\substack{u_{GS}=U_{GS} \\ u_{DS}=U_{DS}}} u_{DS\sim} + \dots \end{aligned}$$

**GS-part of gate current**

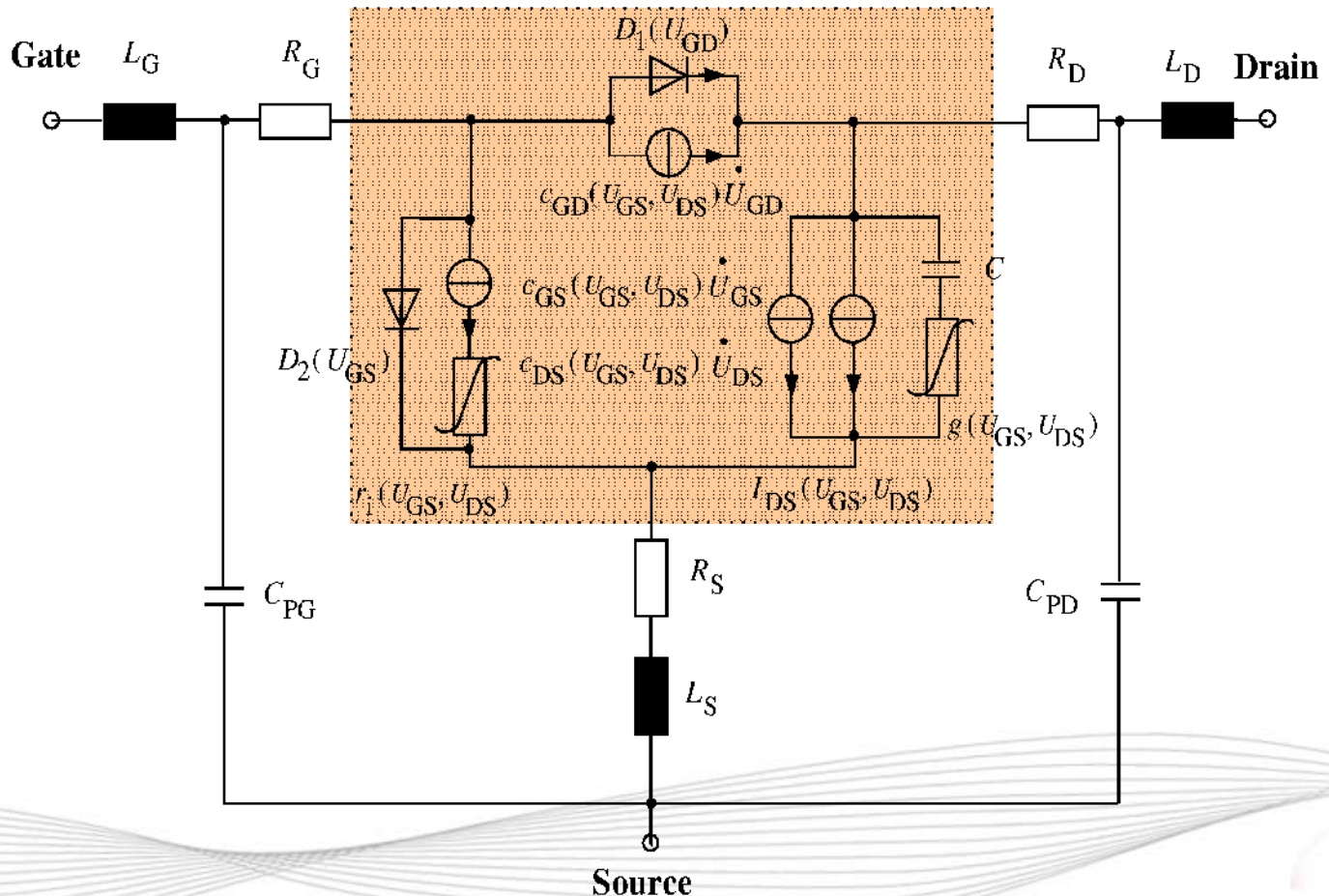
$$i_{GS} = c_{GS}(U_{GS}, U_{DS}) \frac{du_{GS}}{dt}$$





# Large signal simulation

$$i_G = \frac{dQ(u_{GS}, u_{DS})}{dt} = \frac{\partial Q(u_{GS}, u_{GD})}{\partial u_{GS}} \frac{du_{GS}}{dt} + \frac{\partial Q(u_{GS}, u_{GD})}{\partial u_{GD}} \frac{du_{GD}}{dt}$$





# Large signal simulation

Due to designation of 2 voltages of  $V_{gs}$ ,  $V_{ds}$  and  $V_{gd}$ , the third voltage is always defined!

## Case 1: Gate charge is known

$$Q_G = au_{GS}^2 + bu_{GS}u_{DS} + au_{DS}^2$$

$$i_G = \frac{dQ(u_{GS}, u_{DS})}{dt} = \frac{\partial Q_G(u_{GS}, u_{GD})}{\partial u_{GS}} \frac{du_{GS}}{dt} + \frac{\partial Q_G(u_{GS}, u_{GD})}{\partial u_{GD}} \frac{du_{GD}}{dt}$$

$$u_{DS} = f \cos(\omega t) \quad u_{GS} = e \sin(\omega t)$$

$$i_G = \omega(A \sin(2\omega t) + B \cos(2\omega t))$$

$$A = ae^2 - cf^2$$

$$B = bef$$

**Pure capacitive gate current, no DC part**



# Large signal simulation

## Case 2: The capacitances are known

$$c_{DS}(u_{GS}, u_{DS}) = \left. \frac{\partial Q_G}{\partial u_{DS}} \right|_{u_{GS}=\text{const.}} = bu_{GS} + 2cu_{DS}$$

$$c_{GS}(u_{GS}, u_{DS}) = \left. \frac{\partial Q_G}{\partial u_{GS}} \right|_{u_{DS}=\text{const.}} = 2au_{GS} + bu_{DS}$$

$$i_{GS} = \omega(C + D \sin(2\omega t) + C \cos(2\omega t))$$

$$C = 0,5bef$$

$$D = ae^2$$

$$i_{GD} = \omega(-C + E \sin(2\omega t) + C \cos(2\omega t))$$

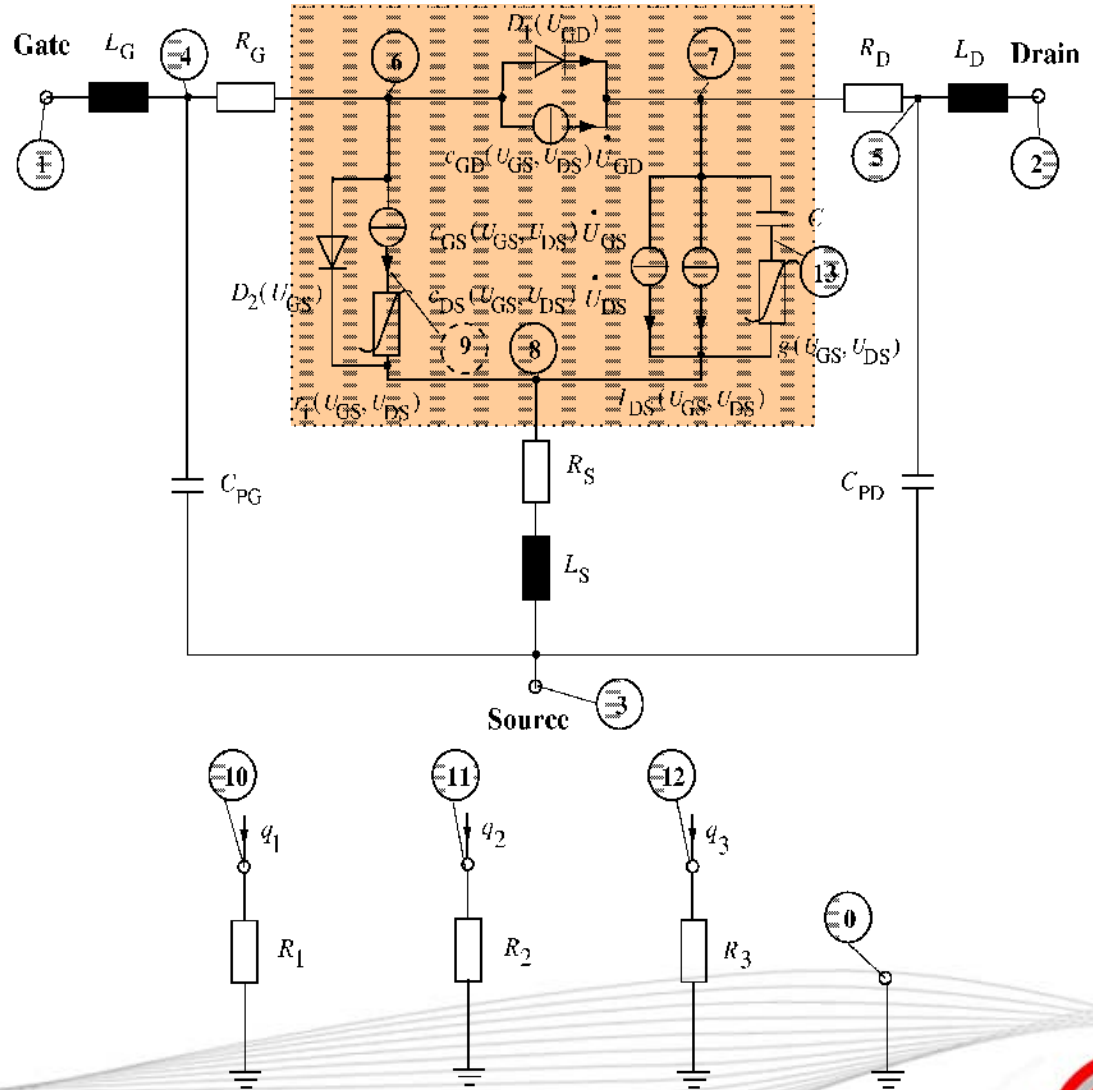
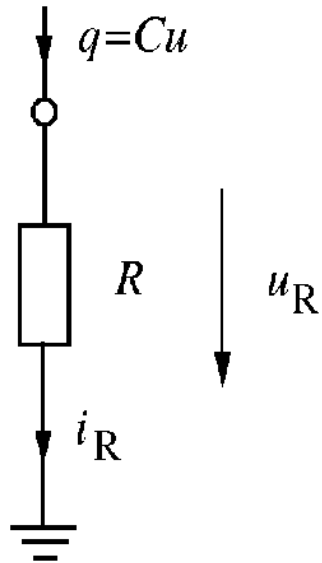
$$E = -cf^2$$

**DC current parts, which compensate each other**

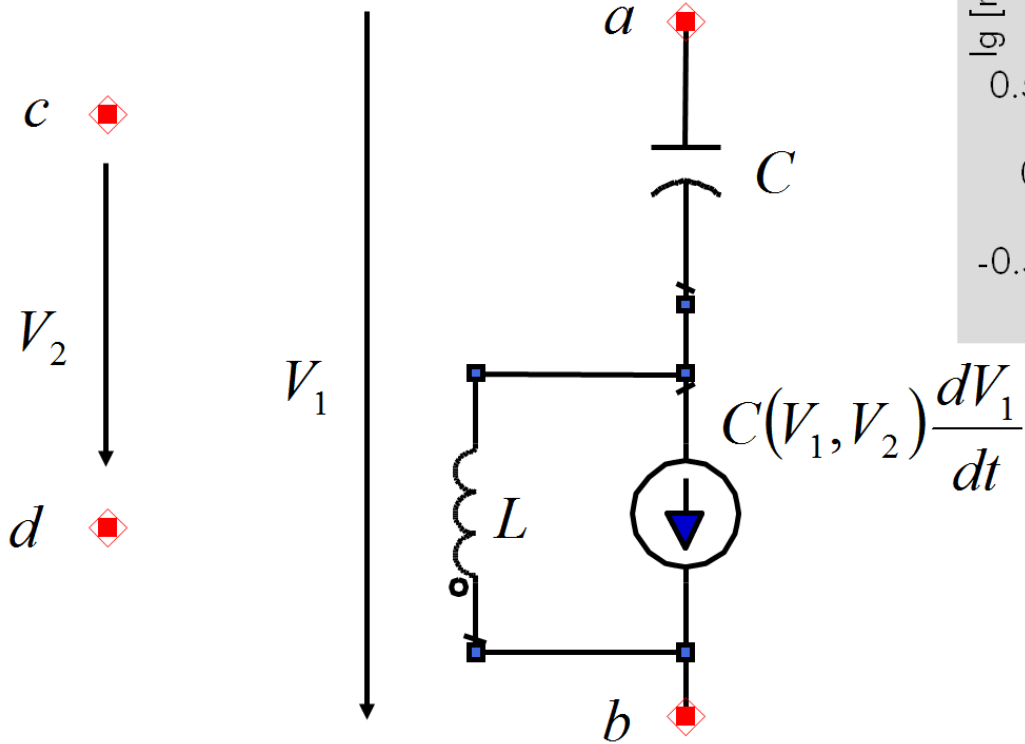
# Large signal simulation

$$i_R = \dot{q} = C \cdot \dot{V}$$

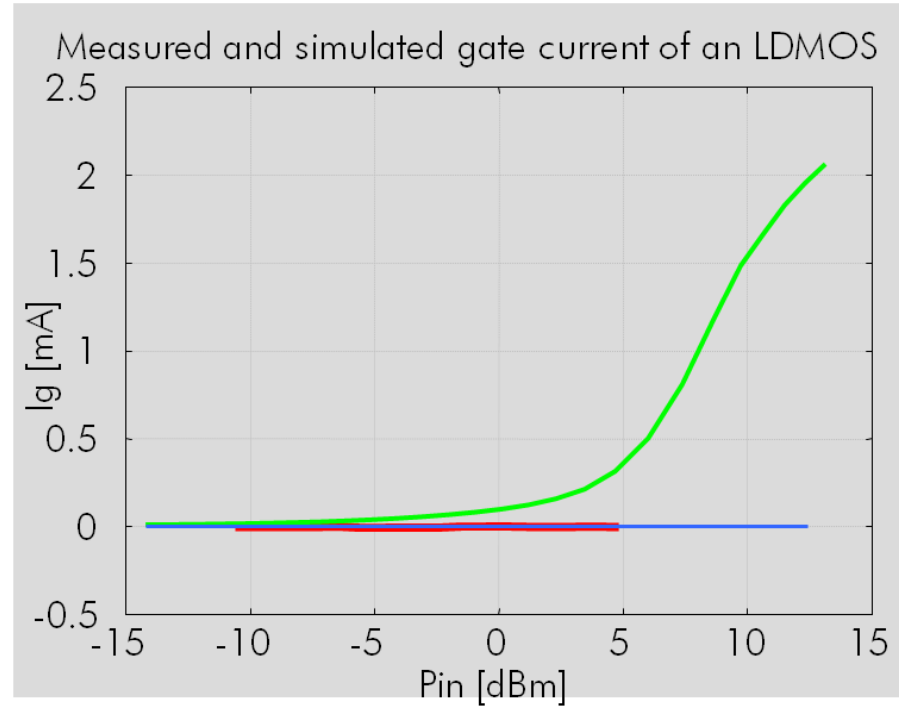
$$V_R = i_R R = CR \cdot \dot{V}$$



# Example

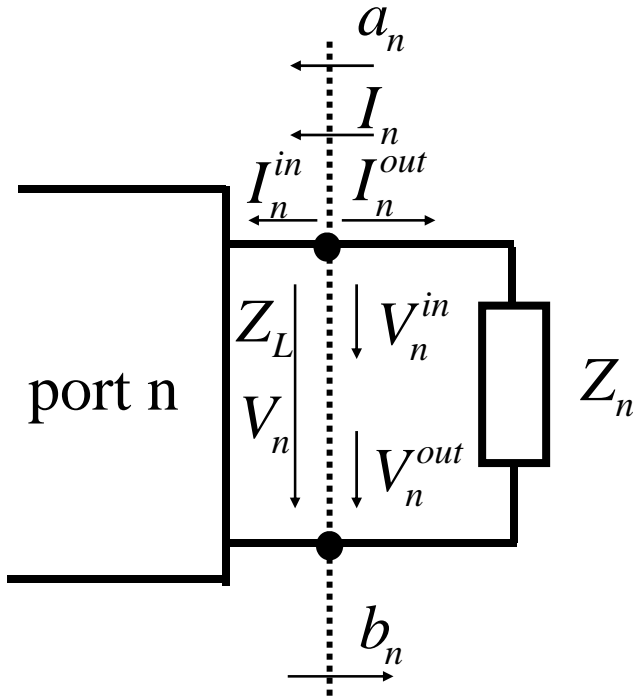


$L, C$  large



# Consistent implementation

Calculation of S-parameters using currents and voltages



Waves in an out of port n

$$a_n = \frac{V_n^{in}}{\sqrt{Z_{Ln}}} = I_n^{in} \sqrt{Z_{Ln}}$$

$$b_n = \frac{V_n^{out}}{\sqrt{Z_{Ln}}} = I_n^{out} \sqrt{Z_{Ln}}$$

Voltages and currents on the line

$$u_n = \frac{V_n}{\sqrt{Z_{Ln}}} = \frac{V_n^{in} + V_n^{out}}{\sqrt{Z_{Ln}}} = a_n + b_n$$

$$i_n = I_n \sqrt{Z_{Ln}} = (I_n^{in} - I_n^{out}) \sqrt{Z_{Ln}} = a_n - b_n$$

$$\Rightarrow \begin{cases} a_n = \frac{1}{2}(u_n + i_n) \\ b_n = \frac{1}{2}(u_n - i_n) \end{cases} \Rightarrow$$

S-Matrix

$$\|b\| = \|s\| \cdot \|a\|$$

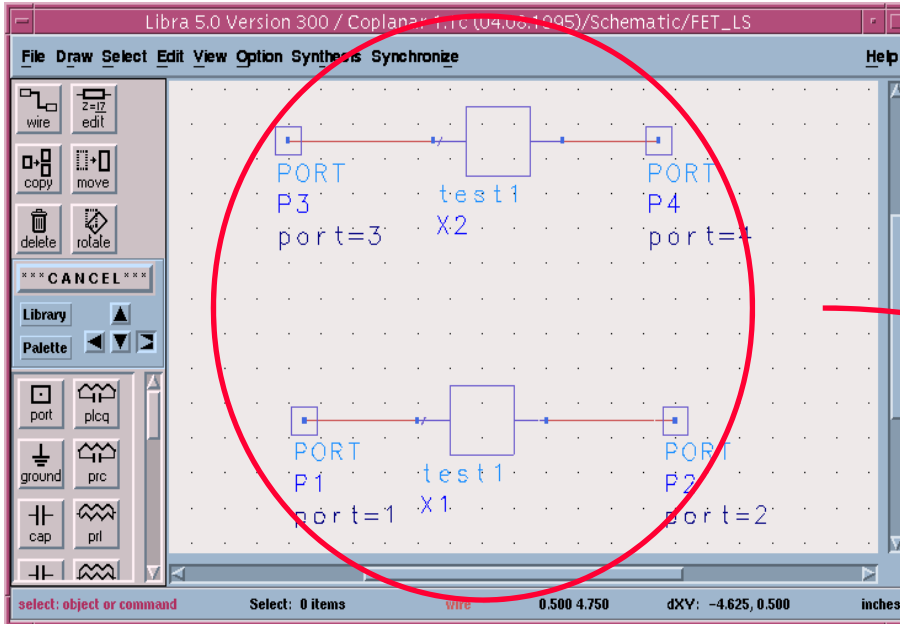
Example

$$s_{11} = \left. \frac{b_1}{a_1} \right|_{a_2=0}$$

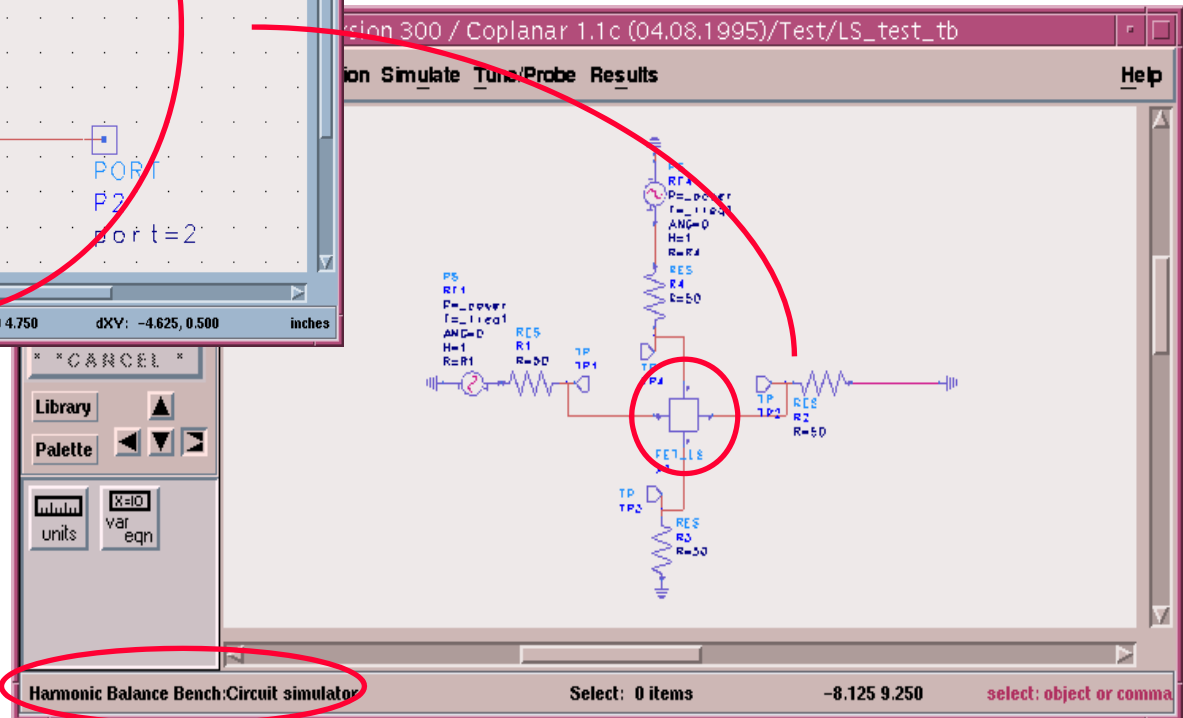
$$s_{11,dB} = 20 \cdot \log \frac{u_1 - i_1}{u_1 + i_1}$$

# Consistent implementation

Calculation of small signal s-parameters  
Using a harmonic balance large signal testbench



Harmonic balance testbench



# Consistent implementation

OUTPUT

EQUATION  
\_OUTEON

```

a11=VFC1/7.07+IFC1*7.07*1e-3
a22=VFC4/7.07+IFC4*7.07*1e-3
b11=VFC1/7.07-IFC1*7.07*1e-3
b22=VFC4/7.07-IFC4*7.07*1e-3
b21=VFC2/7.07-IFC2*7.07*1e-3
b12=VFC3/7.07-IFC3*7.07*1e-3
s11=20*log(b11/a11)
s11_ang=b11/a11
s22=20*log(b22/a22)
s22_ang=b22/a22
s21=20*log(b21/a11)
s21_ang=b21/a11
s12=20*log(b12/a22)
s12_ang=b12/a22
    
```

VFC1	IFC1	VFC2	IFC2	VFC3	IFC3
TP1 ID=TP1	ELEM=R1	TP1 ID=TP2	ELEM=R2	TP1 ID=TP3	ELEM=R3
TP2 ID=gnd	PIN=1	TP2 ID=gnd	PIN=1	TP2 ID=gnd	PIN=1
H1=1	H1=1	H1=1	H1=1	H1=1	H1=1
H2=0	H2=0	H2=0	H2=0	H2=0	H2=0
H3=0	H3=0	H3=0	H3=0	H3=0	H3=0

VFC4	IFC4
TP1 ID=TP4	ELEM=R4
TP2 ID=gnd	PIN=1
H1=1	H1=1
H2=0	H2=0
H3=0	H3=0

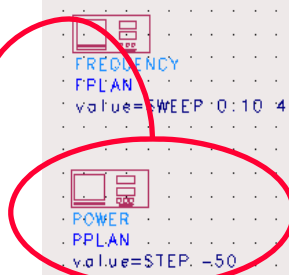
  

NH	Pout_RF	PIn	PSPEC
NH	TP1 ID=TP2	TP1 ID=TP1	PSPEC1
VALUE=5	TP2 ID=gnd	TP2 ID=gnd	TP1 ID=TP2
	ELEM=R2	ELEM=R1	TP2 ID=gnd
	H1=1	H1=1	ELEM=R2
	H2=0	H2=0	
	H3=0	H3=0	

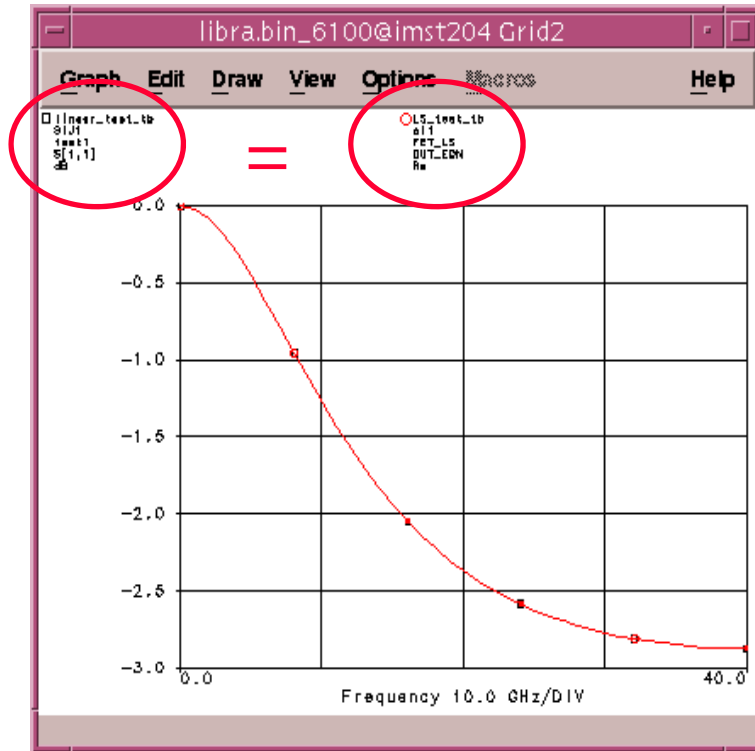
FREQUENCY	B1AS1	B1AS2	
FPLAN	B1PLAN	B2PLAN	
value=SWEEP:0:10:40:1	value=STEP:0	value=STEP:2	

Small signal  
-50 dBm



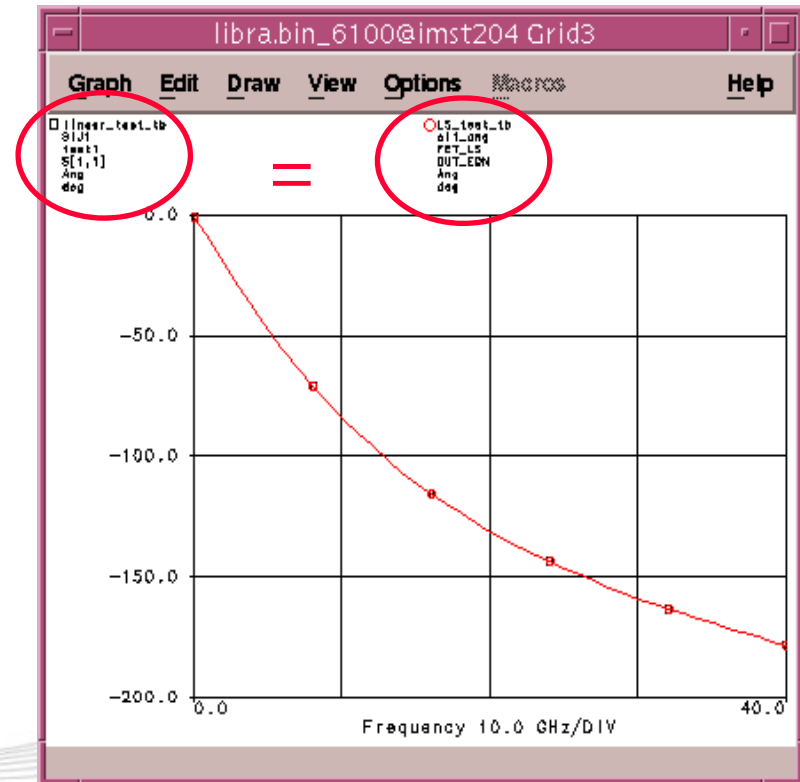


# Consistent implementation



Mag( $s_{11}$ ), simulated using  
Small signal and HB  
testbench for very low  
input power (-50 dBm)

Phase( $s_{11}$ ), simulated using  
Small signal and HB  
testbench for very low  
input power (-50 dBm)





# Needful things

Linearize exp functions

$$f(x) = \begin{cases} \exp(x) & x \leq x_0 \\ mx + b & x > x_0 \end{cases}$$

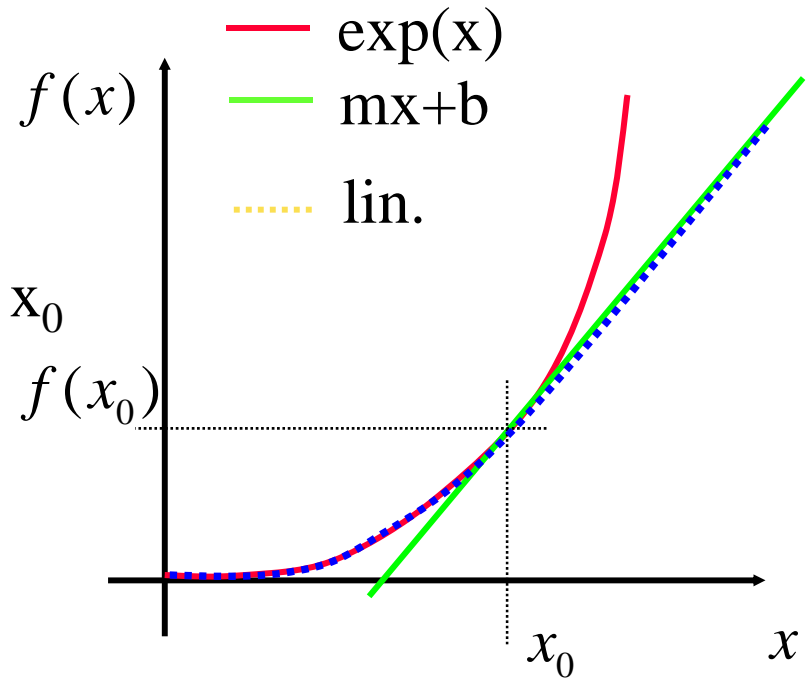
Function must be continuous at  $x_0$

$$f_1(x_0) = f_2(x_0) \quad \left. \frac{df_1}{dx} \right|_{x_0} = \left. \frac{df_2}{dx} \right|_{x_0}$$

$$\Rightarrow \exp(x_0) = mx_0 + b$$

$$m = \exp(x_0)$$

$$\Rightarrow b = \exp(x_0)(1 - x_0) \Rightarrow f_2(x) = \exp(x_0)(x + 1 - x_0)$$





# Noise sources

Thermal noise

$$\langle i_{th}^2 \rangle = \frac{4kT_0}{R} \Delta f$$

Popcorn (burst)-  
noise

$$\langle i_{burst}^2 \rangle = KB \frac{I_D^{CF}}{1 + \left( \frac{f}{f_{CF}} \right)^2} \Delta f$$

Shot-  
noise

$$\langle i_{shot}^2 \rangle = 2qI_D \Delta f$$

Channel noise

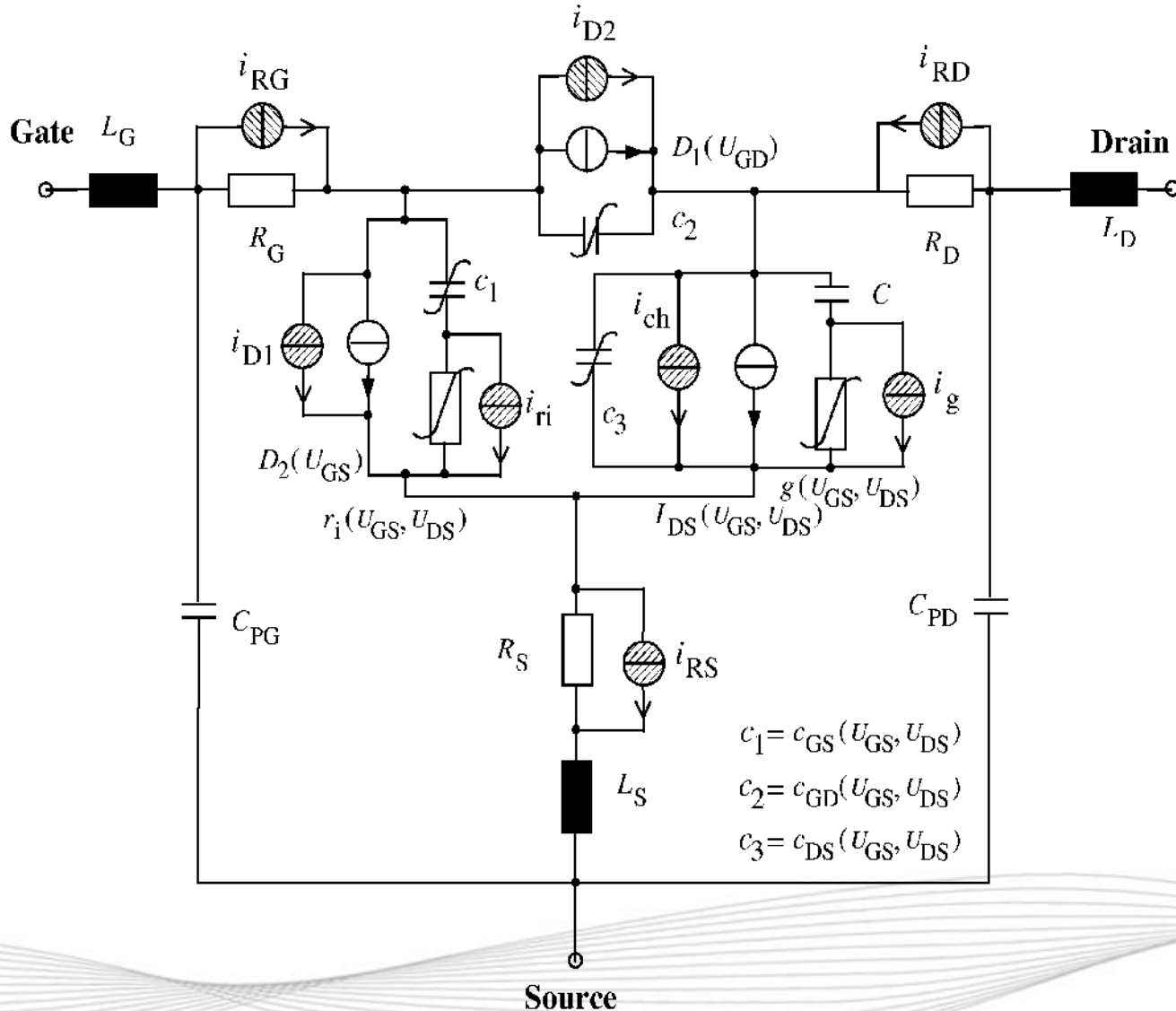
$$\langle i_c^2 \rangle = \frac{8kTg_m}{3} \Delta f$$

1/f (flicker)-  
noise

$$\langle i_{1/f}^2 \rangle = KF \frac{I_D^{AF}}{f^{FFE}} \Delta f$$



# Noise equivalent circuit





# Noisy 2-ports

## Transformation matrix

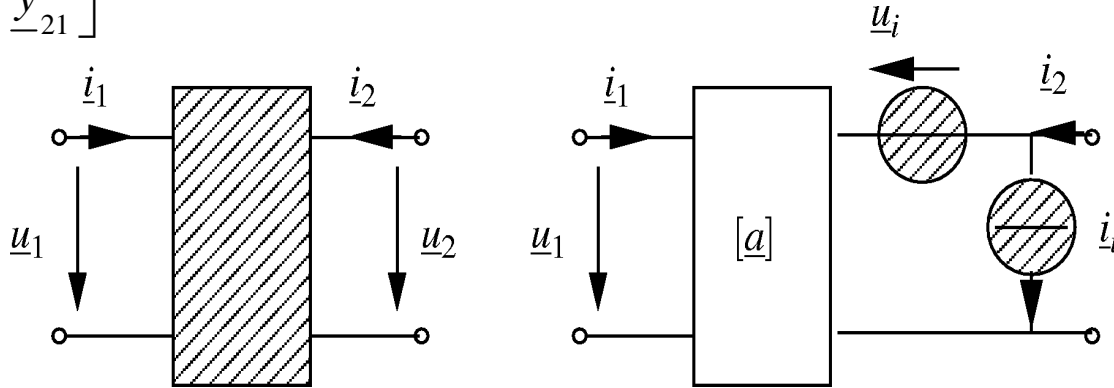
$$[T]^{(y \rightarrow a)} = \begin{bmatrix} 0 & -\frac{1}{y_{21}} \\ 1 & -\frac{y_{11}}{y_{21}} \end{bmatrix}$$

## Noise matrix

$$\begin{bmatrix} v_i^{(a)} \\ i_o^{(a)} \end{bmatrix} = [T]^{(y \rightarrow a)} \begin{bmatrix} i_i^{(y)} \\ i_o^{(y)} \end{bmatrix}$$

input (green circle)  
output (blue circle)

Transformation of noise sources.

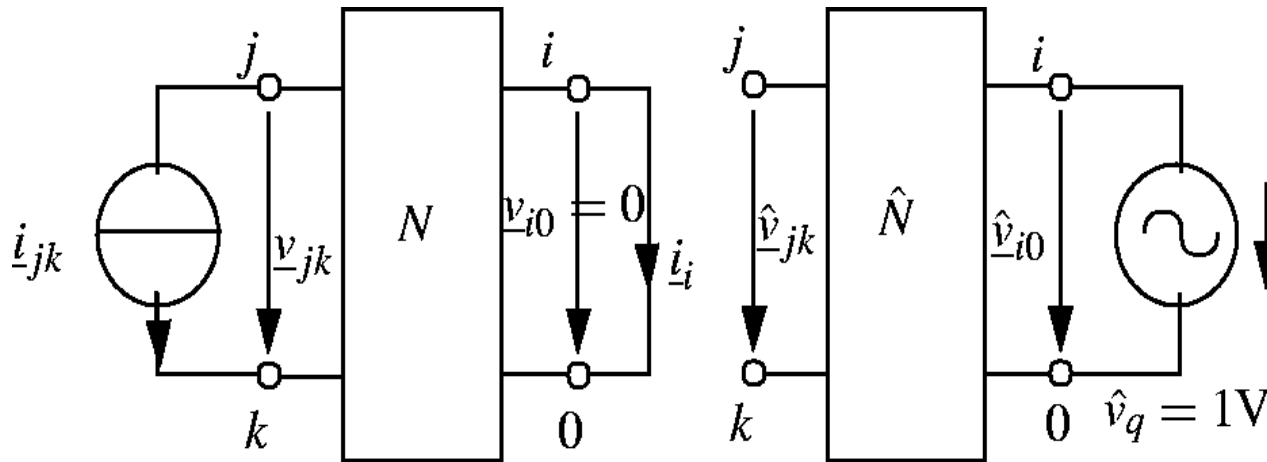


## Correlation matrix, calculation of noise power

$$[C]^{(a)} = \frac{1}{4kT\Delta f} \left( \begin{bmatrix} v_i \\ i_i \end{bmatrix} \begin{bmatrix} v_i^* & i_i^* \end{bmatrix} \right)$$



# Separation of noise sources



Calculation of transformation function

**Network N**  
**Y-Matrix**

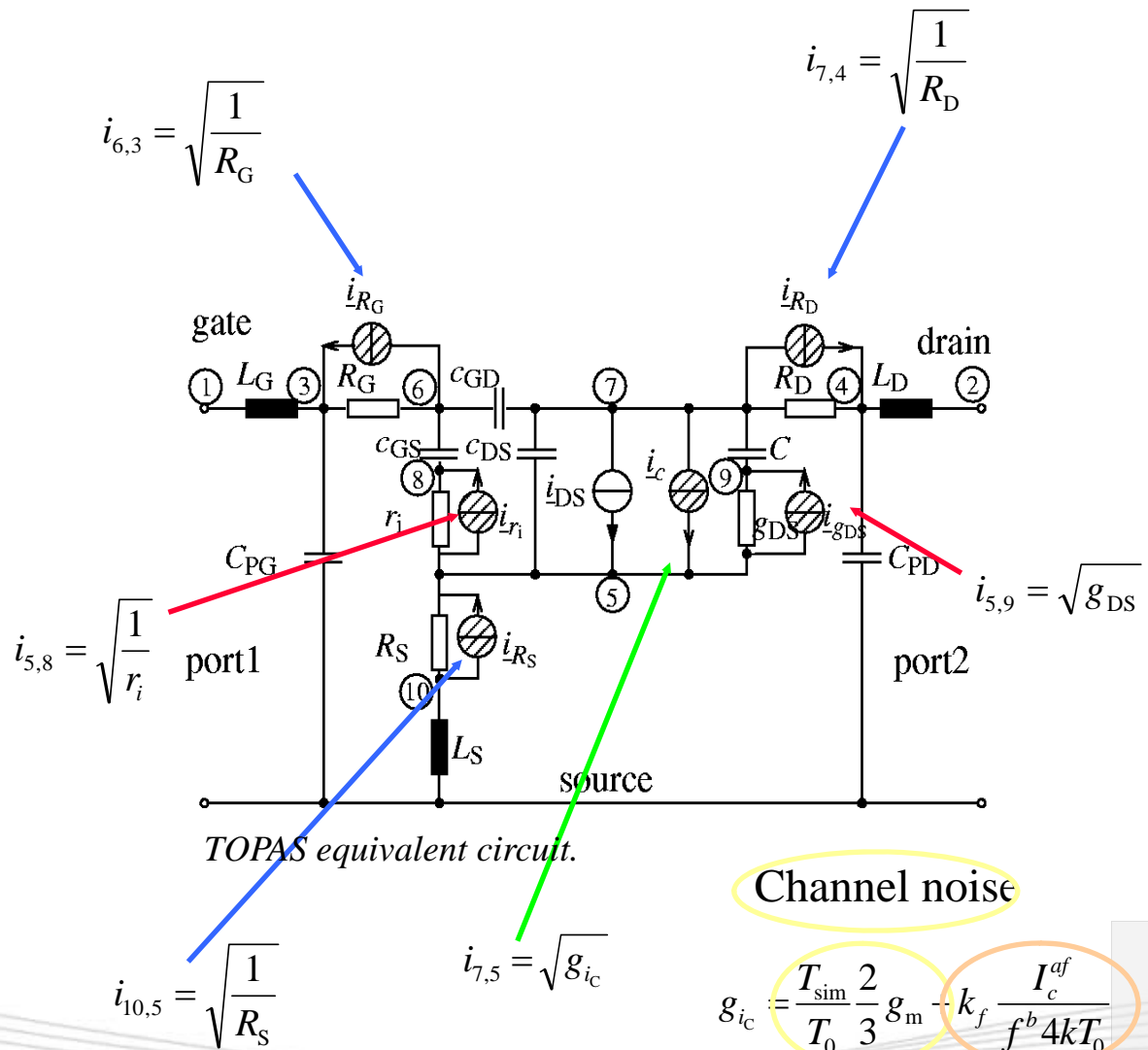
**Adjoint network**  
**transposed Y-Matrix**

**Current transforming function**

$$\alpha_{i,jk} = \frac{i_i}{i_{jk}} = -\frac{\hat{v}_{jk}}{\hat{v}_q}$$



# FET example



## Noise current matrix

$$[i_N] = \sqrt{4kT\Delta f} \cdot \begin{pmatrix} 0 & 0 & 0 & 0 & 0 & 0 & 0 & 0 & 0 & 0 \\ 0 & 0 & 0 & 0 & 0 & 0 & 0 & 0 & 0 & 0 \\ 0 & 0 & 0 & 0 & 0 & 0 & 0 & 0 & 0 & 0 \\ 0 & 0 & 0 & 0 & 0 & 0 & 0 & 0 & 0 & 0 \\ 0 & 0 & 0 & 0 & 0 & 0 & 0 & 0 & i_{5,8} & i_{5,9} & 0 \\ 0 & 0 & i_{6,3} & 0 & 0 & 0 & 0 & 0 & 0 & 0 & 0 \\ 0 & 0 & 0 & i_{7,4} & i_{7,5} & 0 & 0 & 0 & 0 & 0 & 0 \\ 0 & 0 & 0 & 0 & 0 & 0 & 0 & 0 & 0 & 0 & 0 \\ 0 & 0 & 0 & 0 & 0 & 0 & 0 & 0 & 0 & 0 & 0 \\ 0 & 0 & 0 & 0 & i_{10,5} & 0 & 0 & 0 & 0 & 0 & 0 \end{pmatrix}$$

Channel noise

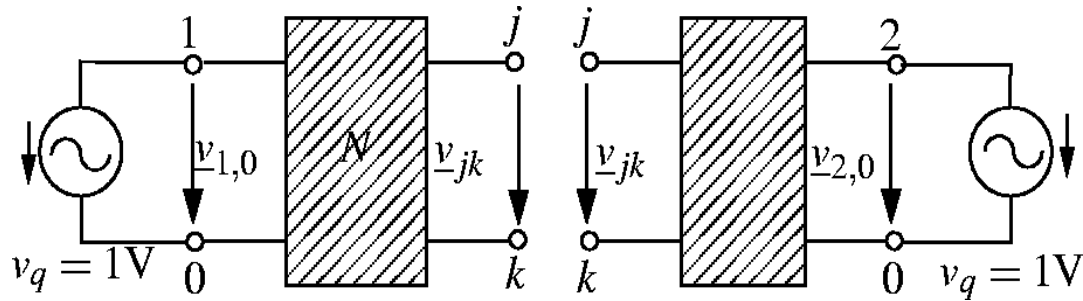
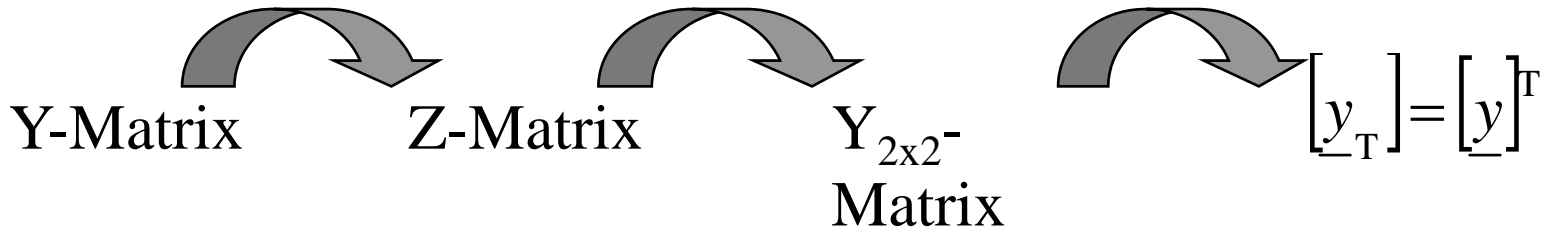
$$g_{ic} = \frac{T_{sim}}{T_0} \frac{2}{3} g_m + k_f \frac{I_c^{af}}{f^b 4kT_0}$$

1/f-noise





# Tellegen Thoerem



*Tellegen Theorem for noisy n-ports*

Adjoined network for calculation of transformation function

$$i_{Q_1} = v_q \cdot \underline{y}_{T,2 \times 2_{1,1}} \quad \text{and} \quad i_{Q_2} = v_q \cdot \underline{y}_{T,2 \times 2_{2,2}}$$

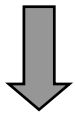




# Tellegen Theorem

$$\begin{bmatrix} i_{Q1} \\ \vdots \\ i_{Q10} \end{bmatrix} = \begin{bmatrix} y_{T1,1} & \cdots & y_{T1,10} \\ \vdots & \ddots & \vdots \\ y_{T10,1} & \cdots & y_{T10,10} \end{bmatrix} \begin{bmatrix} v_1 \\ \vdots \\ v_{10} \end{bmatrix}$$

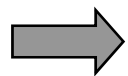
Solving the equation system for the voltages using the Gaussian algorithm



Voltage transformation factor



One single noise source at Eingang, one at output



$$[T]^{(y \rightarrow a)} = \begin{bmatrix} 0 & -\frac{1}{y_{2 \times 2_{21}}} \\ 1 & -\frac{y_{2 \times 2_{11}}}{y_{2 \times 2_{21}}} \end{bmatrix}$$



1 current source, 1 voltage source at output





# Correlation matrix

$$F = 1 - \frac{T_{\text{sim}}}{T_0} \frac{|y_{\underline{G}}|^2 C_{11}^{(a)} + C_{22}^{(a)} + 2\Re\{y_{\underline{G}} C_{12}^a\}}{g_G}$$

$$R_n = \frac{T_{\text{sim}}}{T_0} C_{11}^a$$

Korrelationsmatrix

$$[\underline{C}]^{(a)} = [\underline{T}]^{(y \rightarrow a)} [\underline{C}]^{(y)} [\underline{T}]^{(y \rightarrow a)+}$$

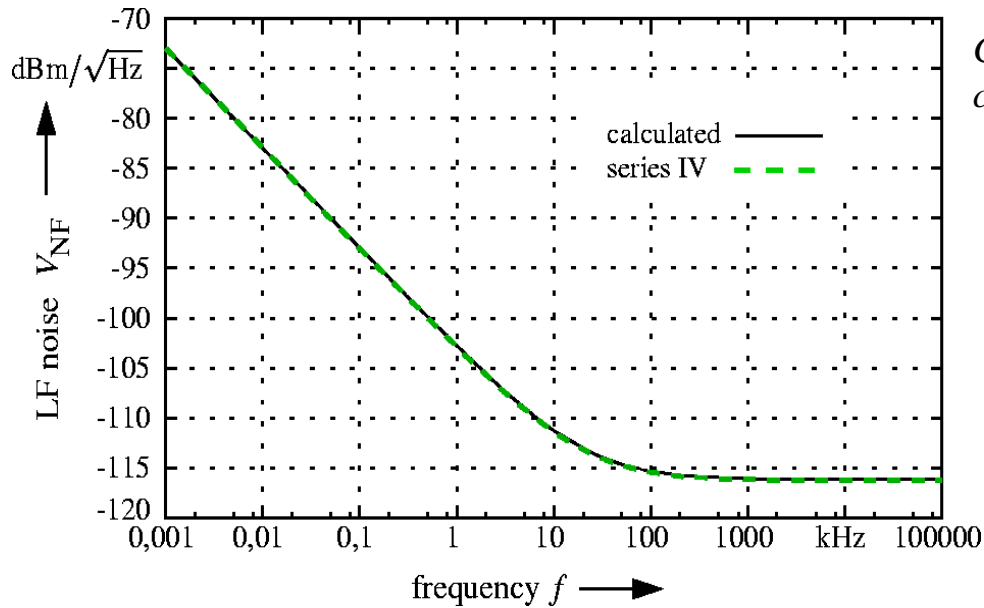
$$V_{\text{NF}} [\text{dBm}/\sqrt{\text{Hz}}] =$$

$$20 \log \left( \sqrt{\frac{T_{\text{sim}}}{T_0} \cdot i_0 i_0^* \frac{50\Omega}{50\Omega \Re(y_{\underline{2} \times \underline{2}22}) + 1}} \cdot 1000 \right)$$

$$\Gamma_{G_{\text{opt}}} = \frac{1 - y_{\underline{G}_{\text{opt}}} Z_0}{1 + y_{\underline{G}_{\text{opt}}} Z_0}$$

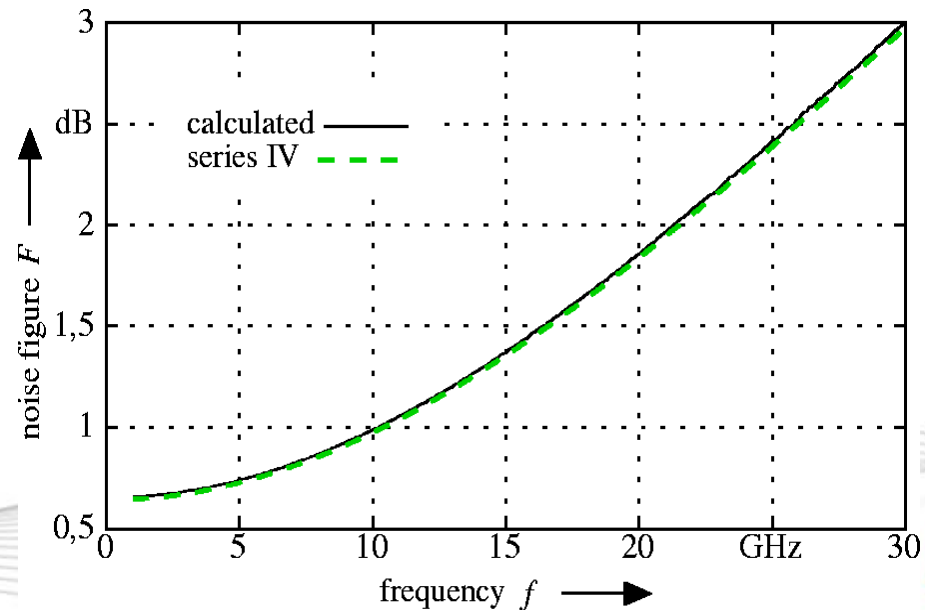


# Verifications

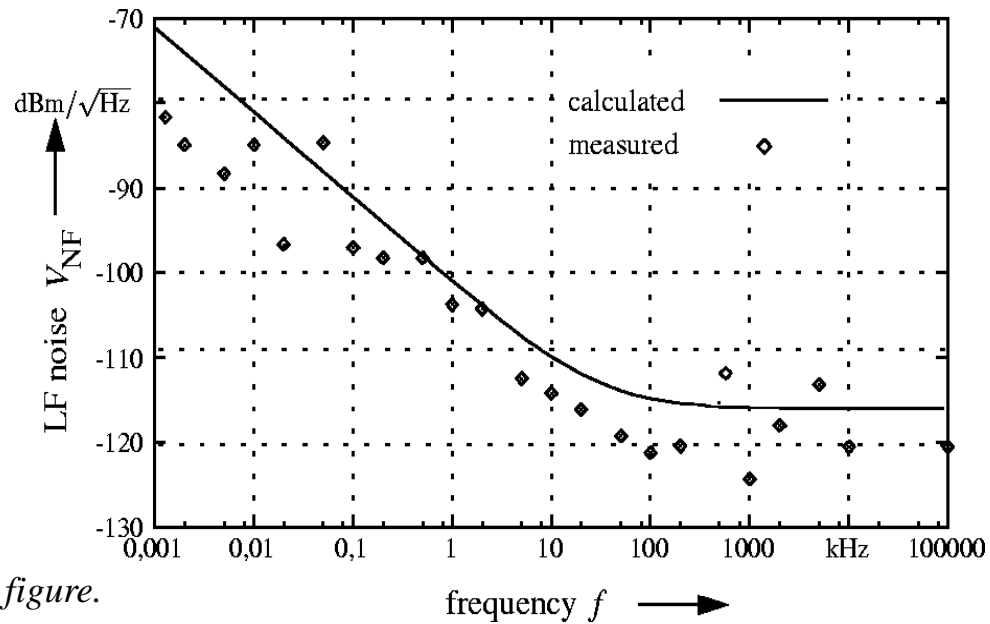


*Calculation of 1/f noise..Simulation in comparison to calculation using the proposed algorithm.*

*Calculation of noise figure NF. Comparison of simulation and calculation.*

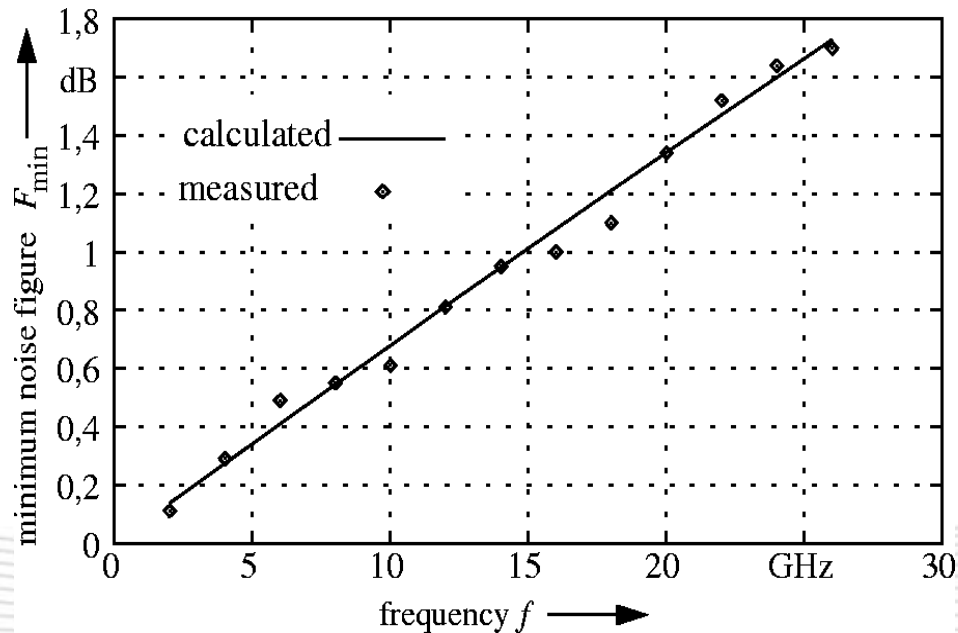


# Verifications



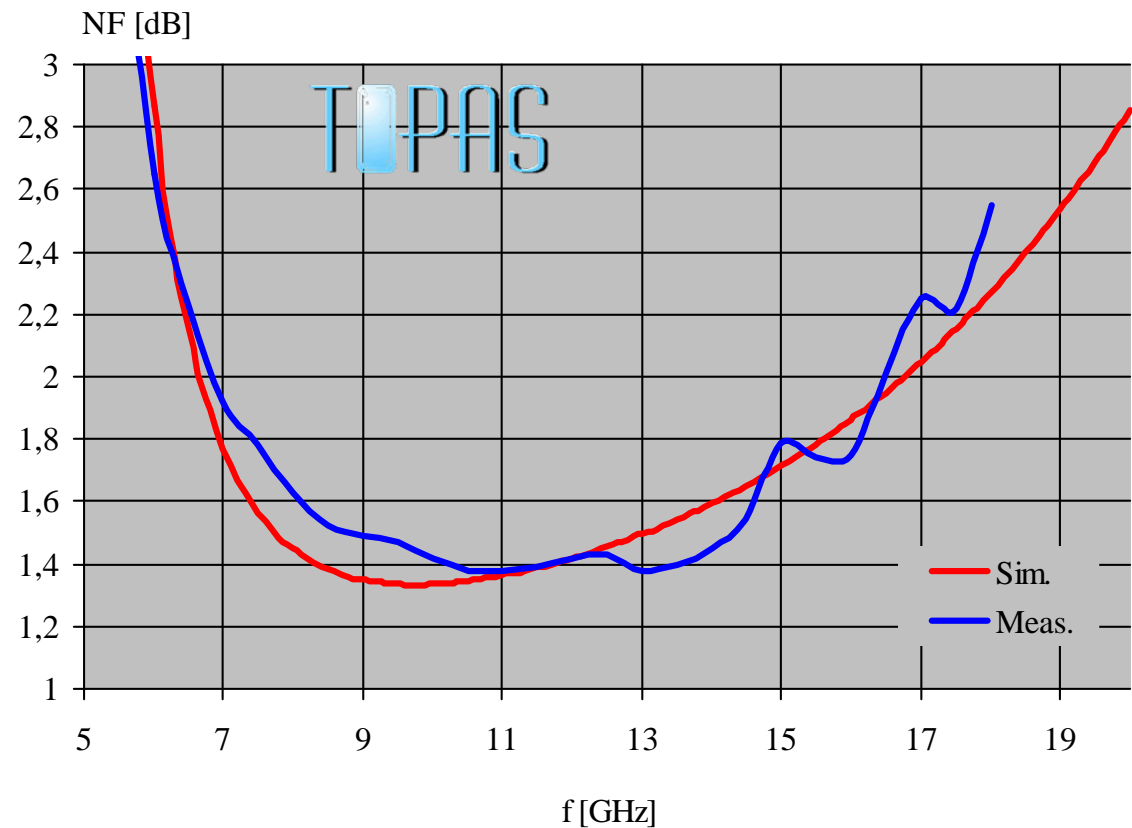
*Simulation and measurement of minimum noise figure.*

*Simulation and measurement of 1/noise.*



# Verifications

Realized LNA

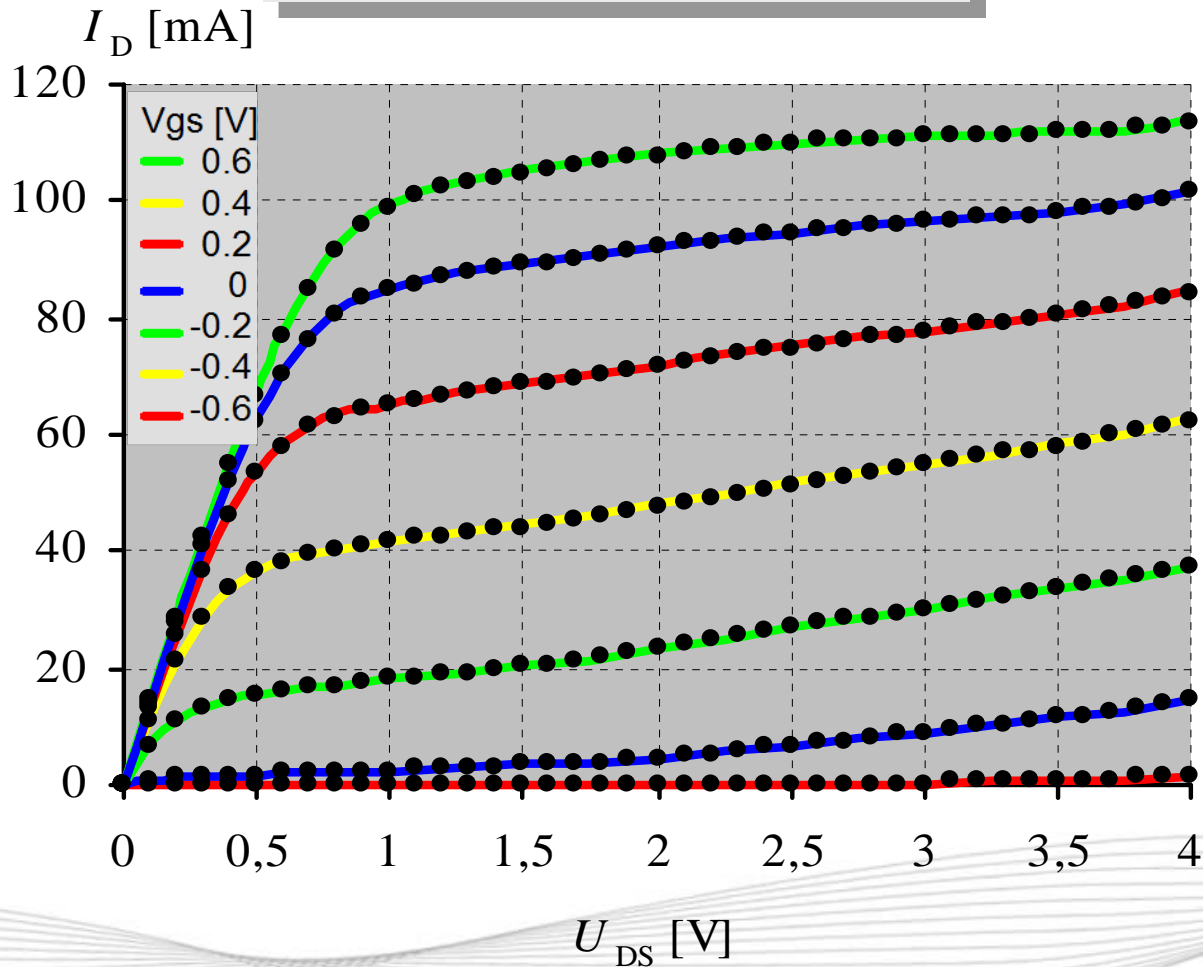


Minimum noise figure, simulation versus measurement.



# Verifications

UMS 4x50  $\mu\text{m}$   
HEMT



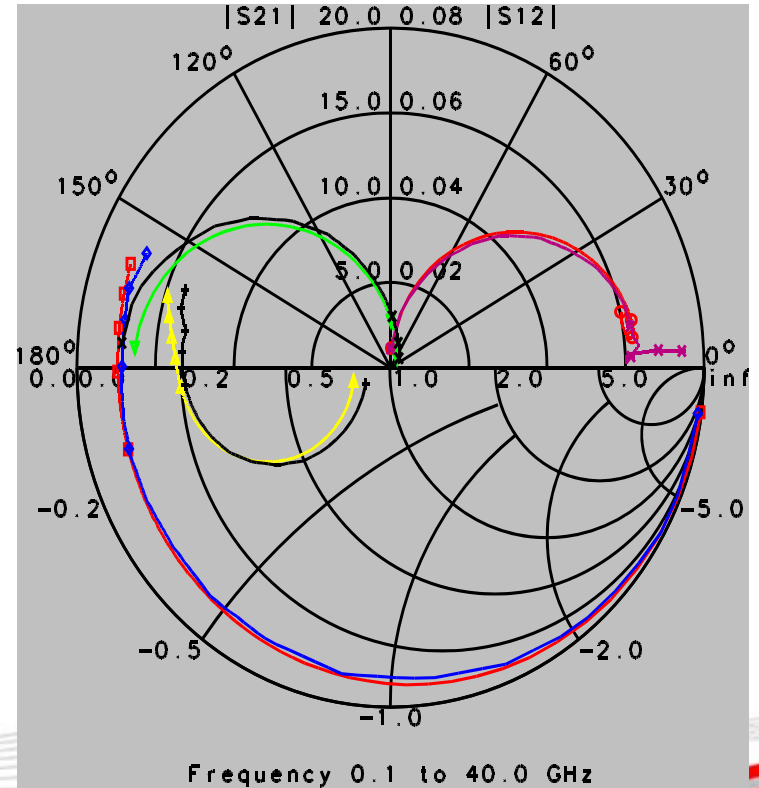
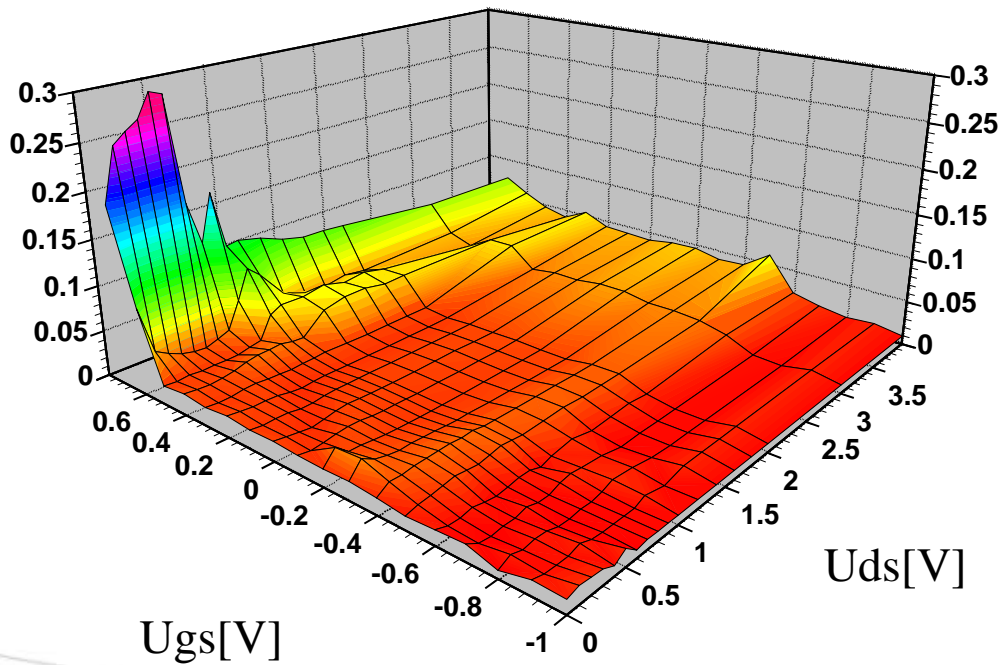


# Verifications

Deviations  
6x20  $\mu\text{m}$  HEMT

4x50  $\mu\text{m}$  ↗ 8x75  $\mu\text{m}$   
 $V_{GS} = 0 \text{ V}$ ,  $V_{DS} = 2 \text{ V}$

Fehler

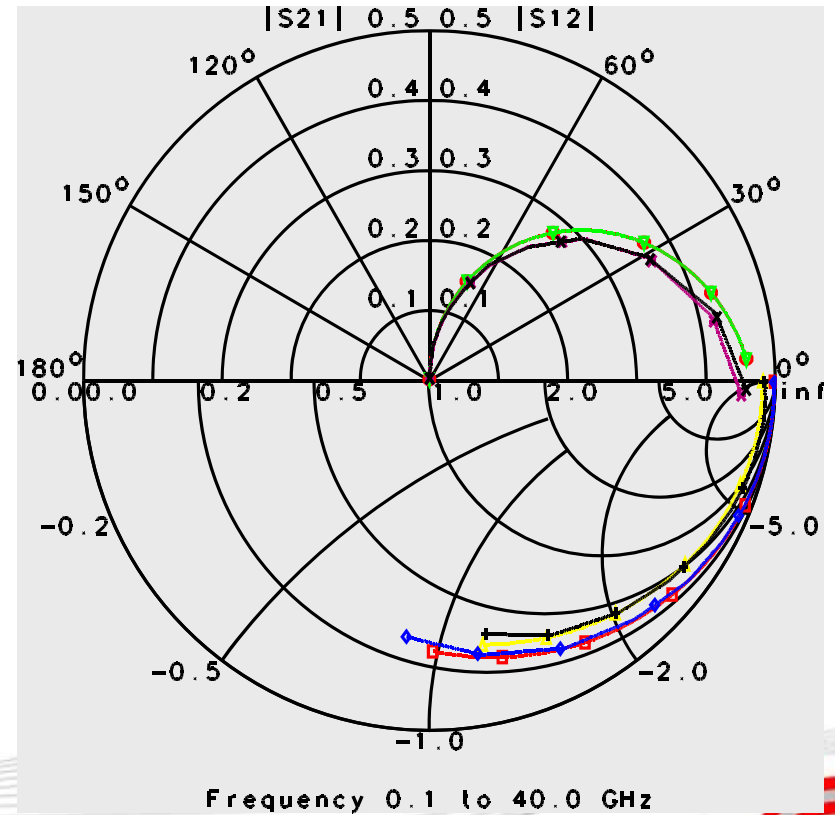
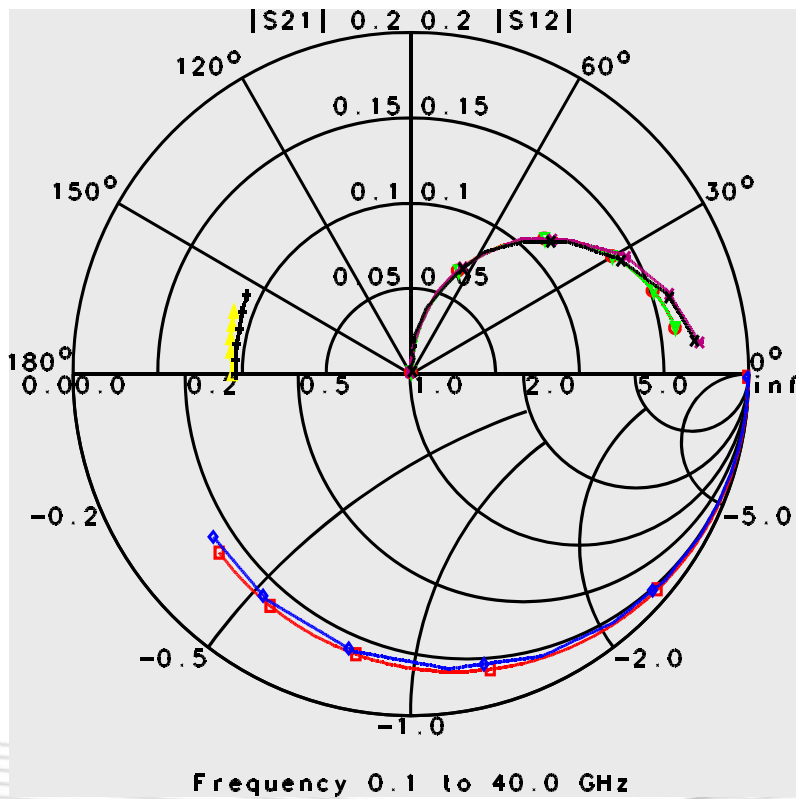




# Verifications

4x50  $\mu\text{m}$   $\nabla$  2x40  $\mu\text{m}$   
 $V_{GS} = 0 \text{ V}$ ,  $V_{DS} = 0 \text{ V}$

4x50  $\mu\text{m}$   $\nabla$  2x40  $\mu\text{m}$   
 $V_{GS} = -0.8 \text{ V}$ ,  $V_{DS} = 2 \text{ V}$

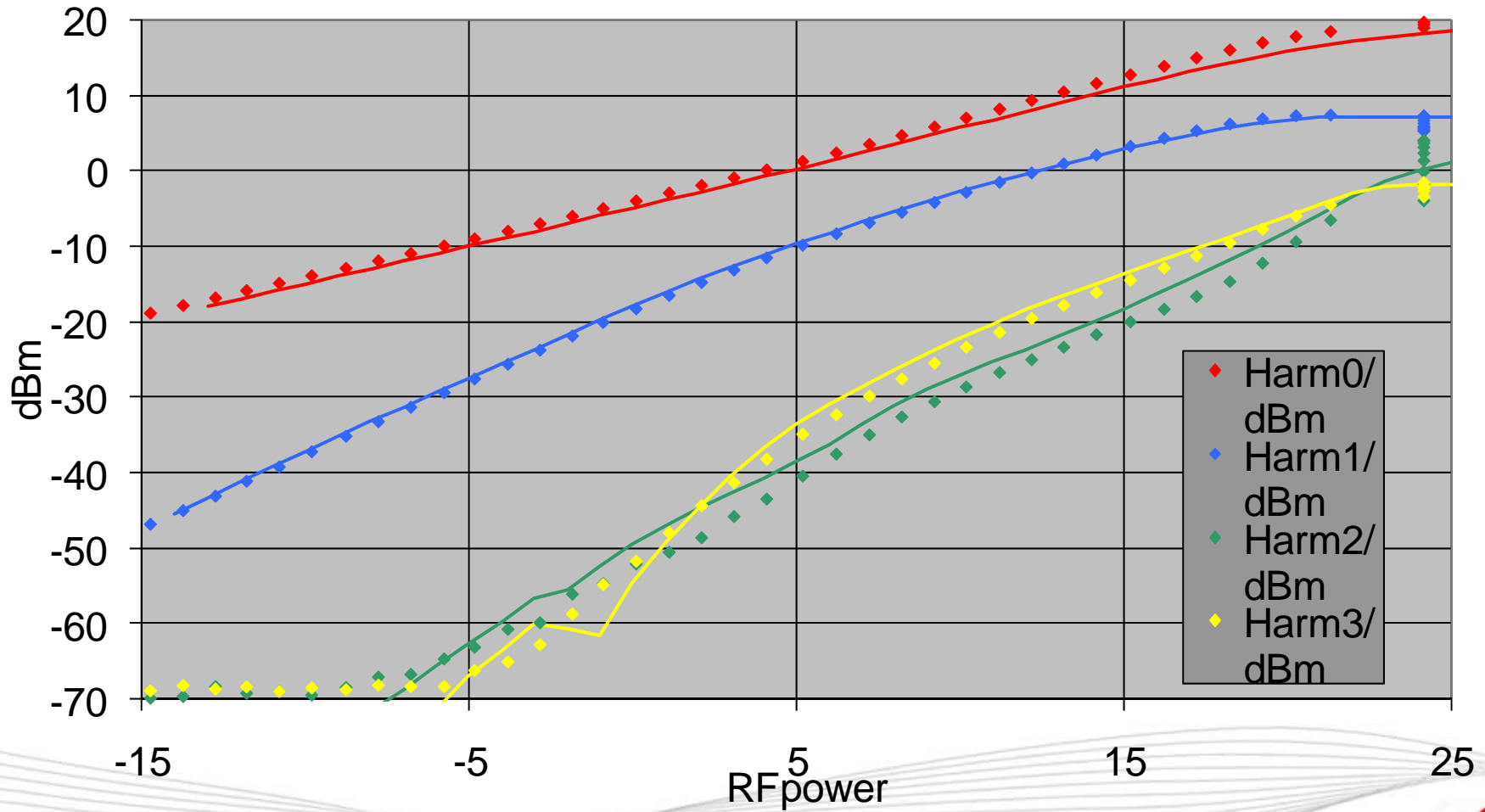






# Verifications

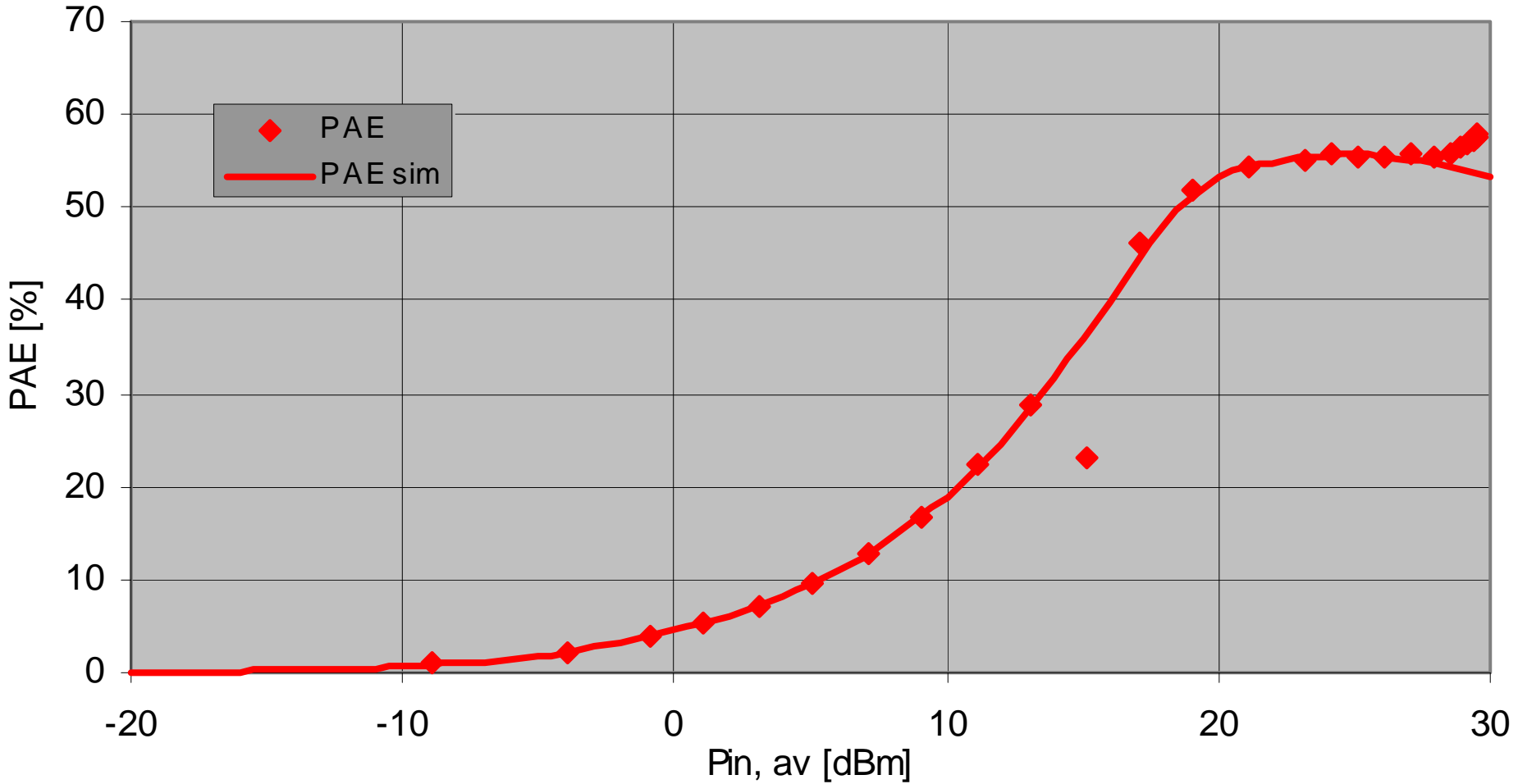
Comp 1x600 2.1 GHz , 26 V, 2.1 mA





# Verifications

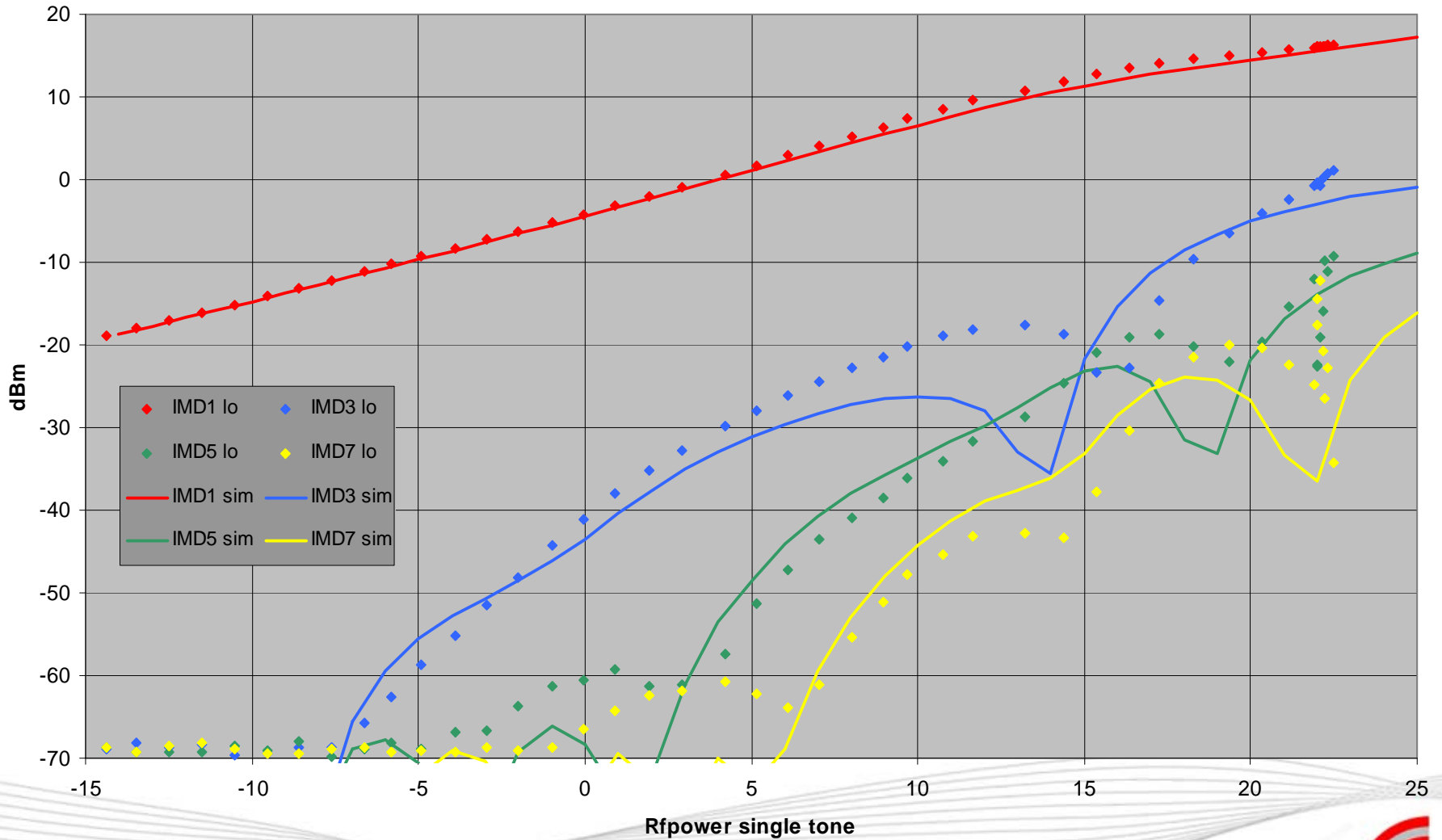
PAE, 600um LDMOS device, class B bias, matched,  $f = 2.0$  GHz





# Verifications

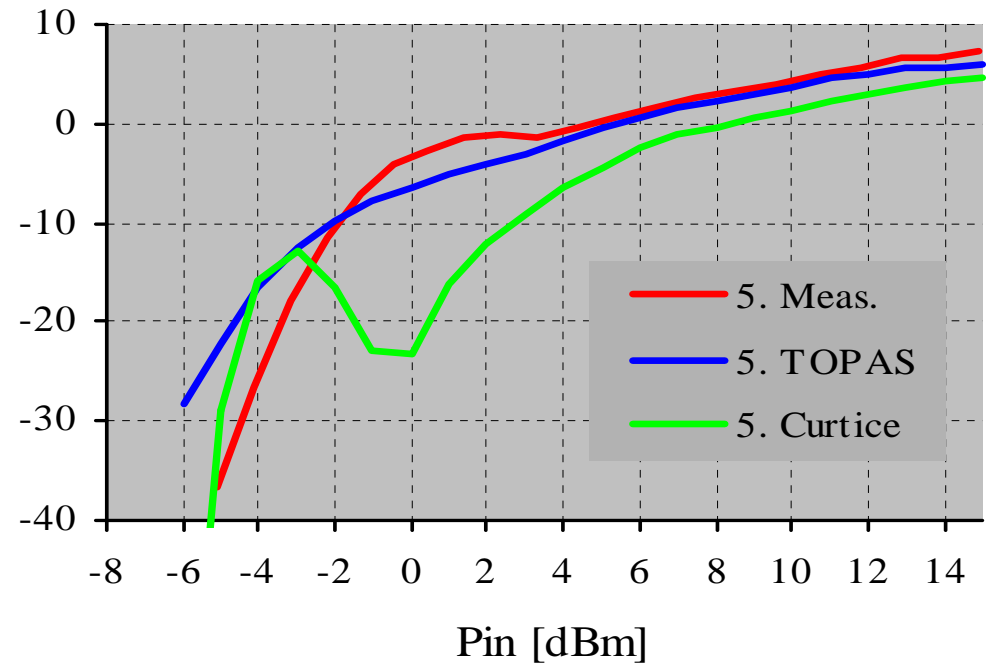
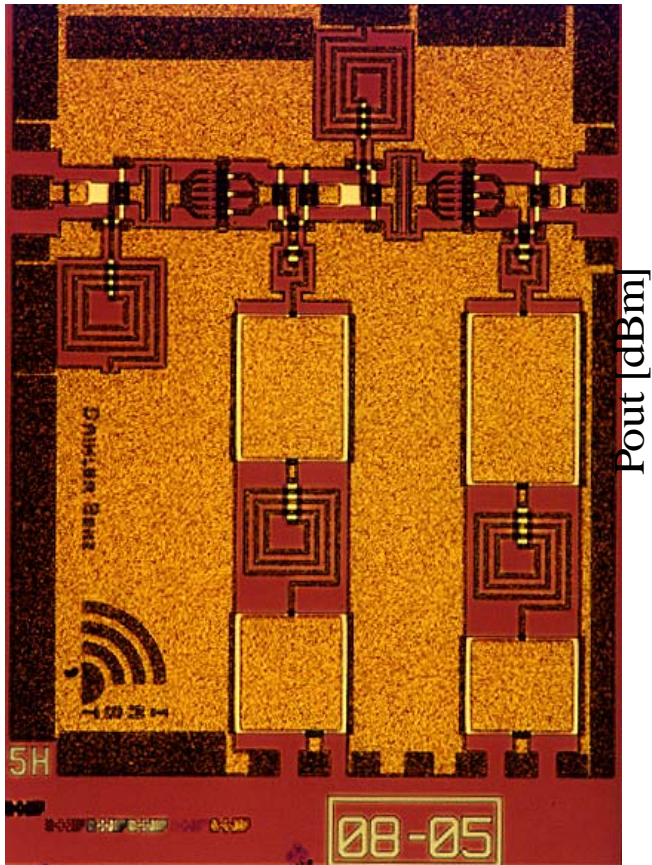
IMD 6x100 1.8 GHz, 2 MHz offset, 26 V, 2.1 mA





# Verifications

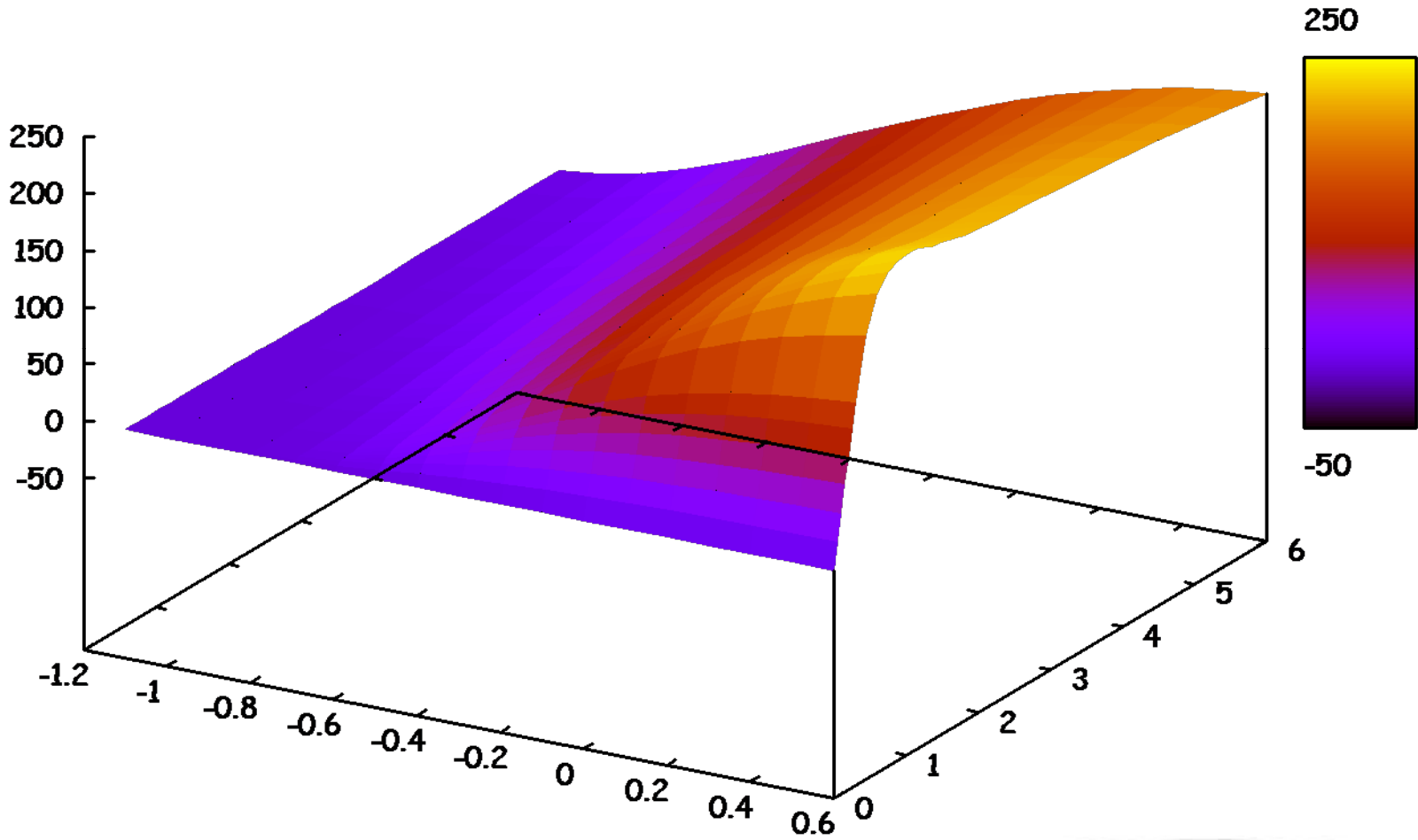
## Times 5 multiplier





# Oscillations

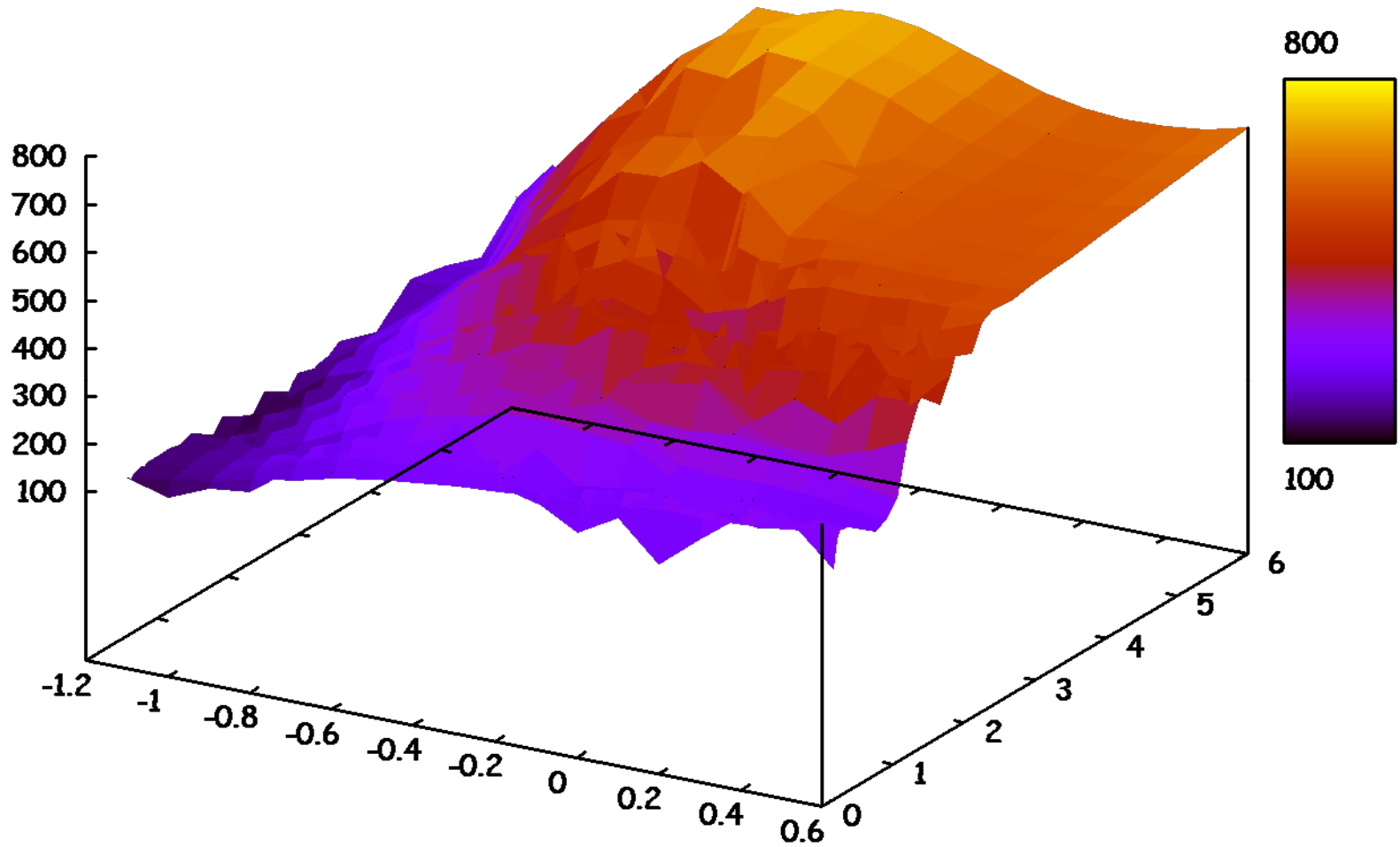
"FETplot.dc"





# Oscillations

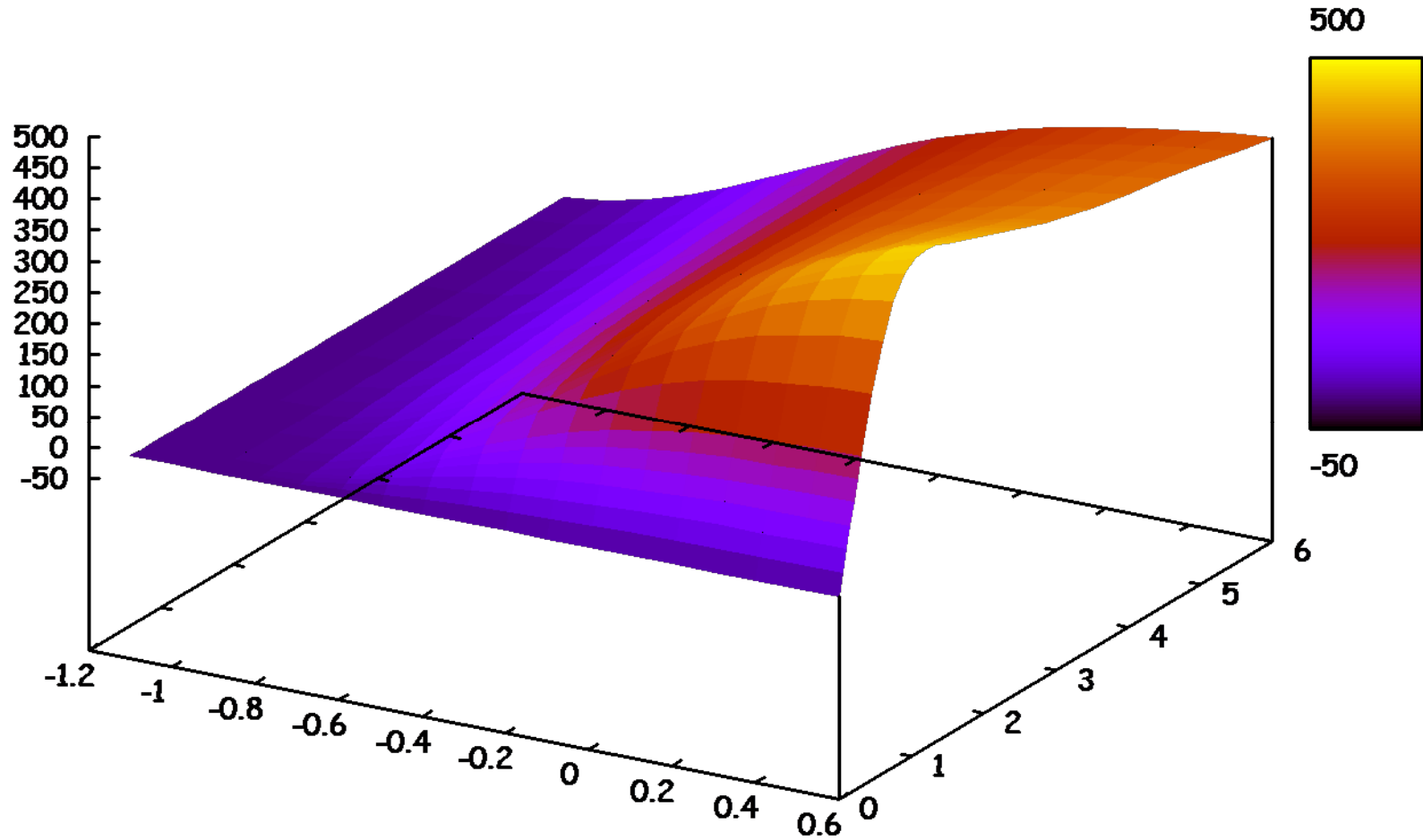
"Cgsintr.dat"





# Oscillations

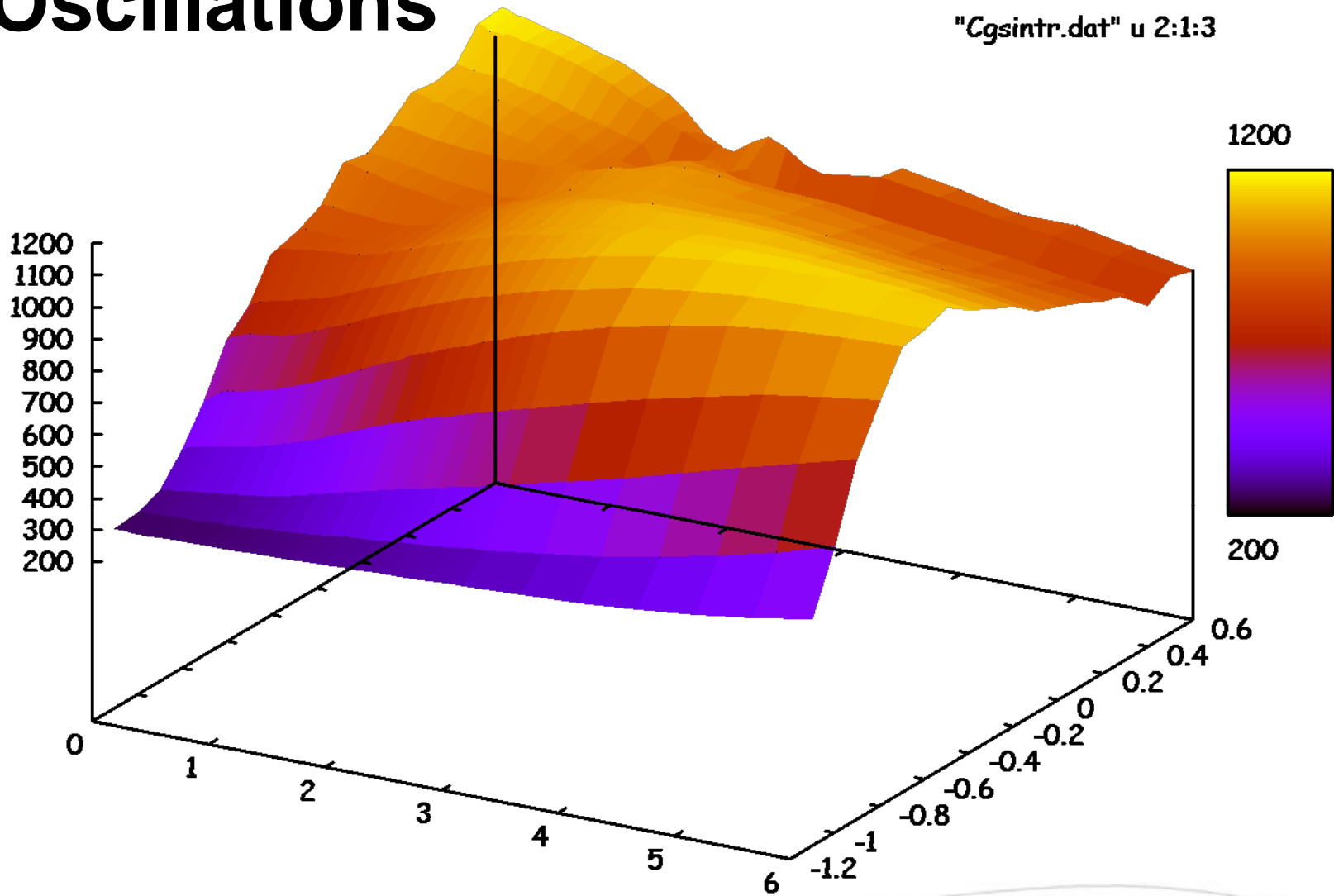
"FETplot.dc"





# Oscillations

"Cgsintr.dat" u 2:1:3

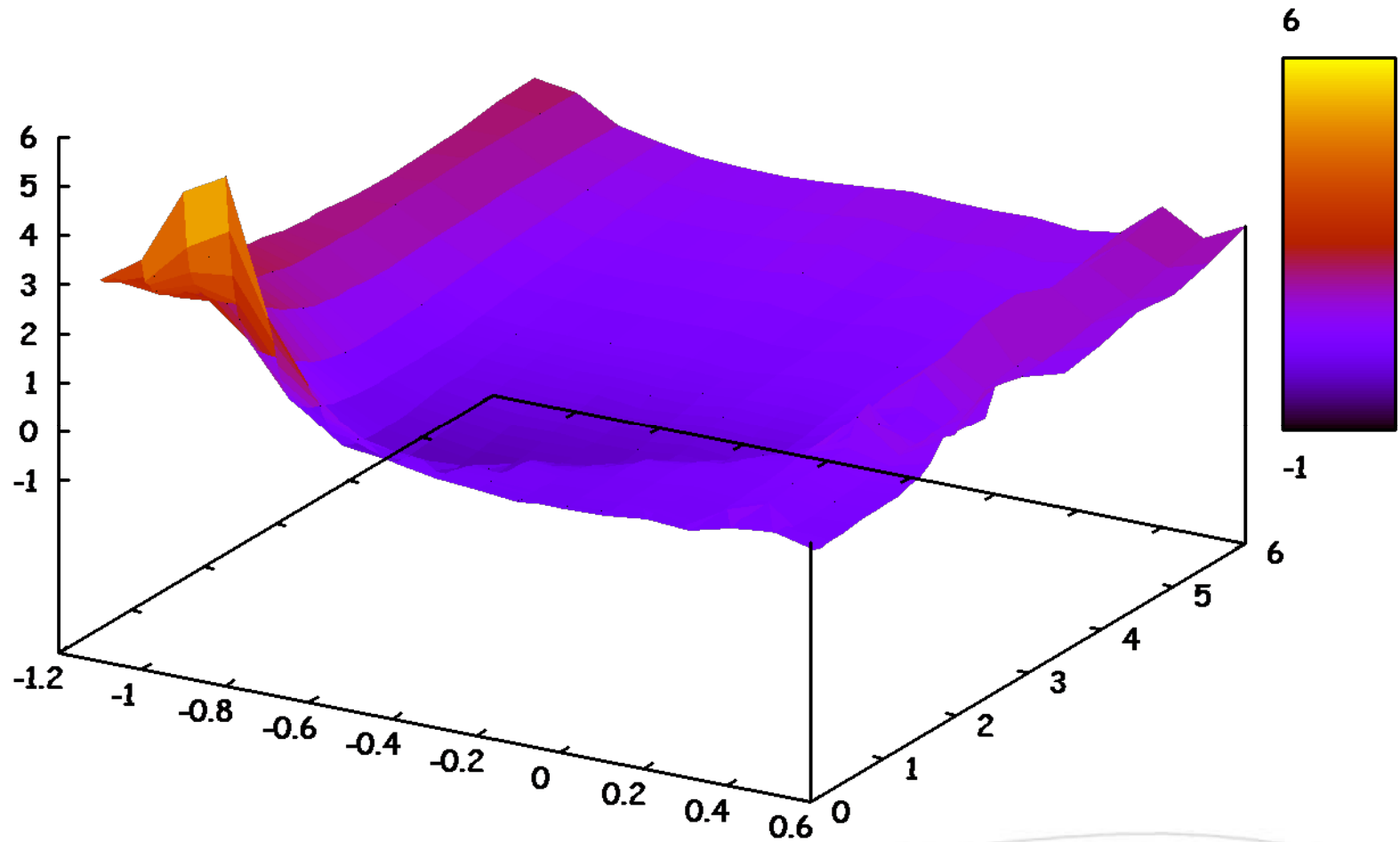






# Oscillations

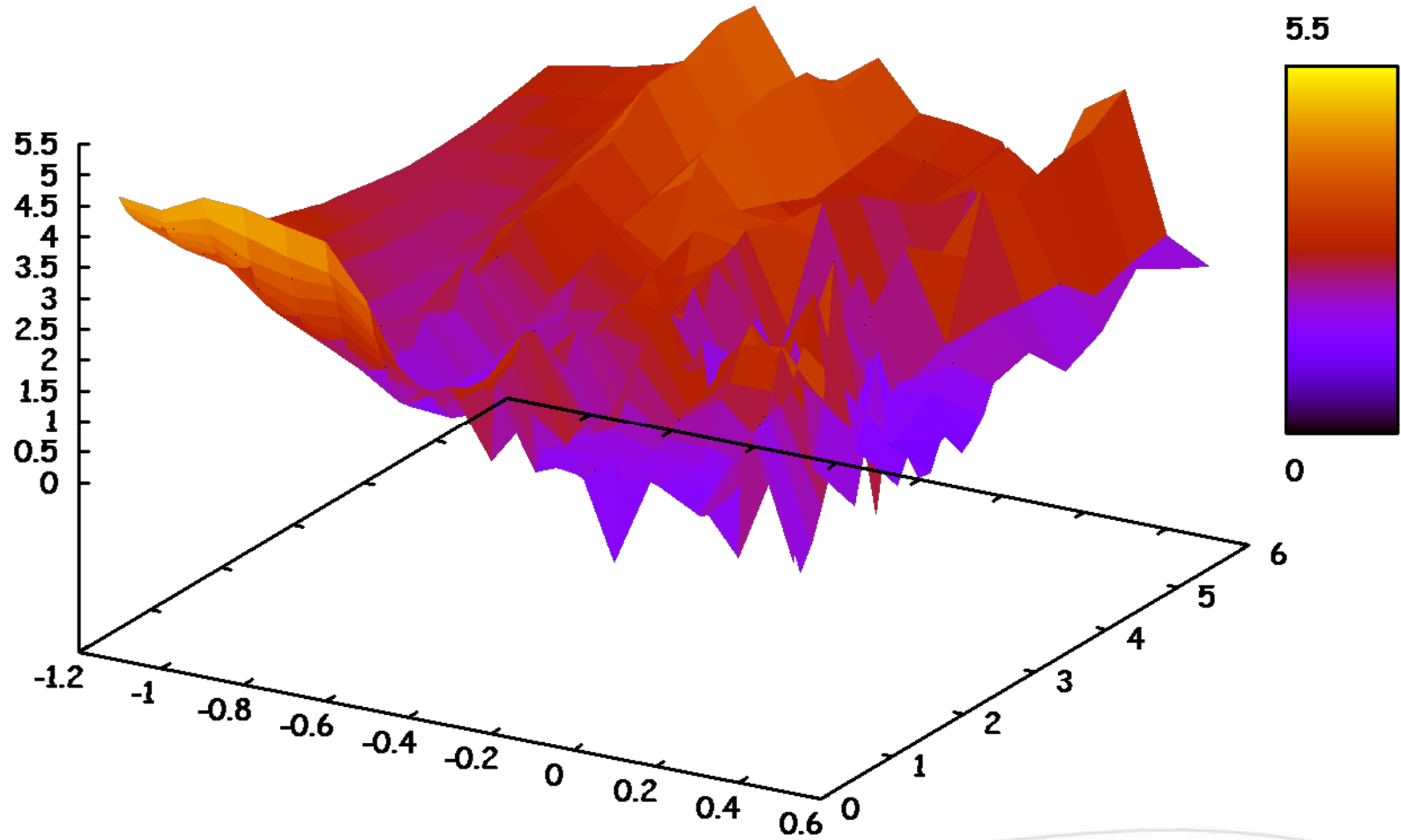
"Riintr.dat"



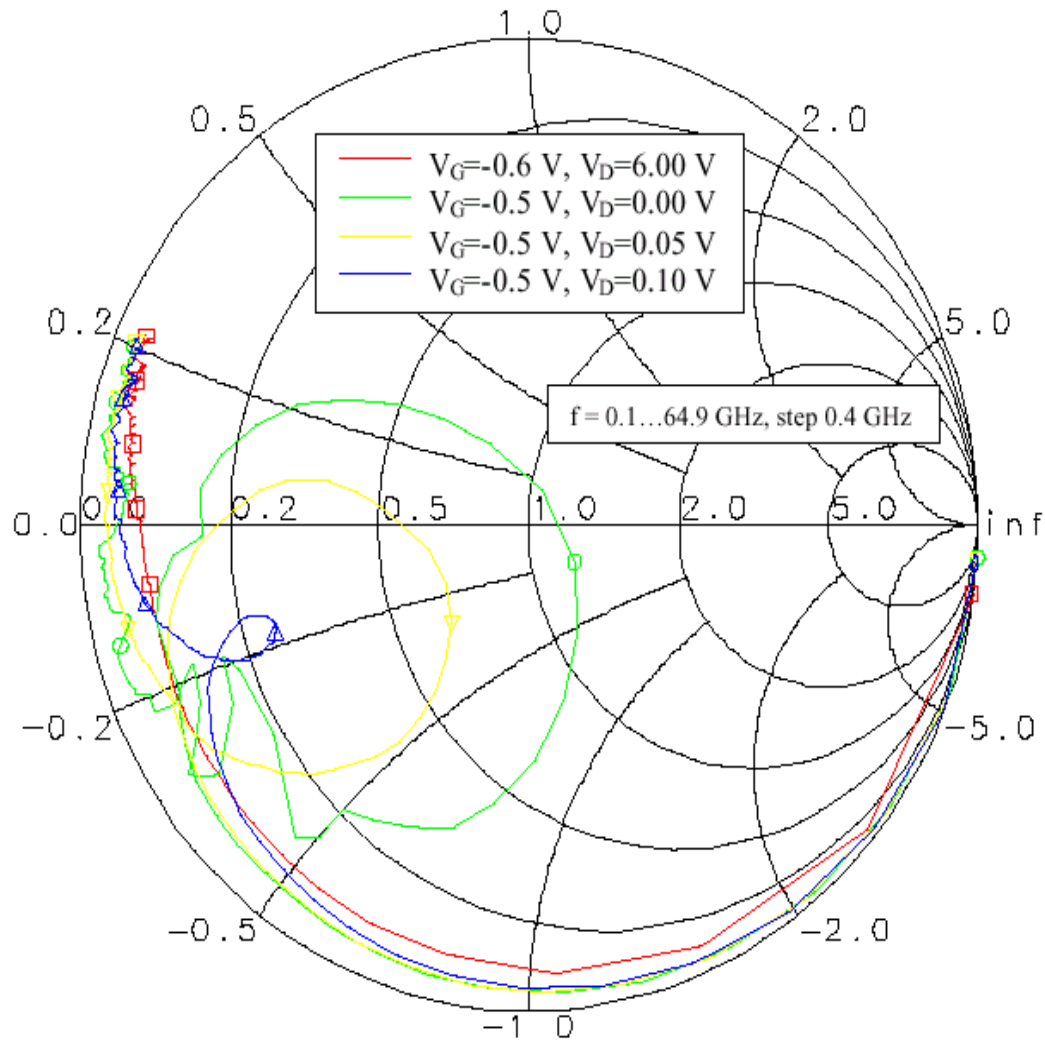


# Oscillations

"Rintr.dat"

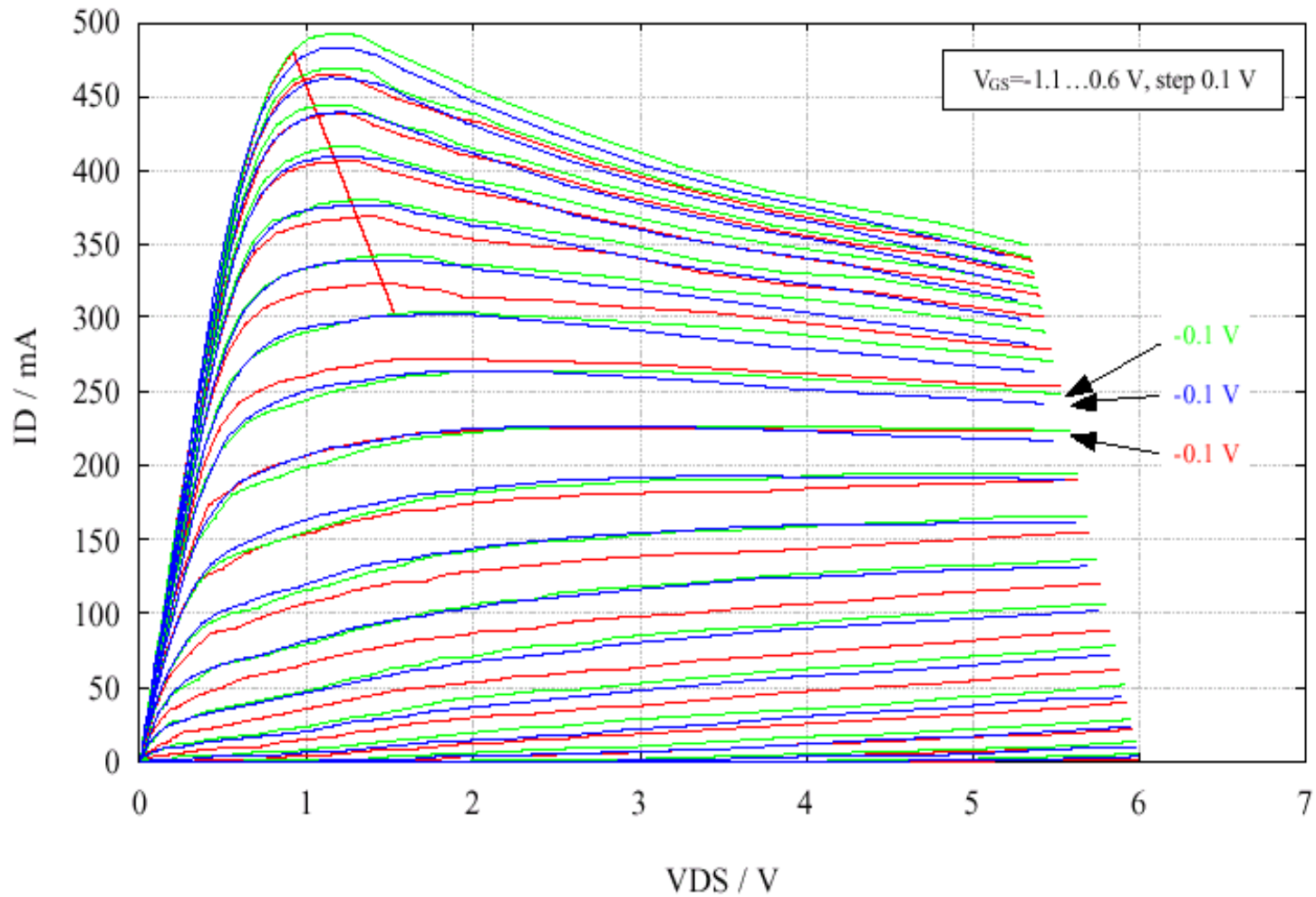


# Switching problems



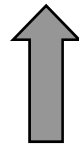
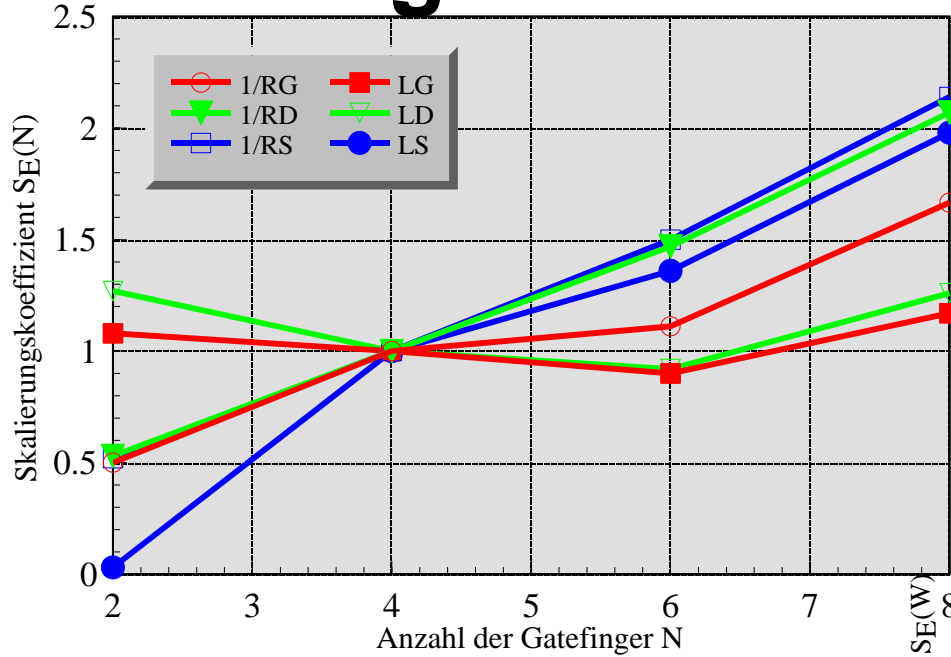


# Burn-in effects



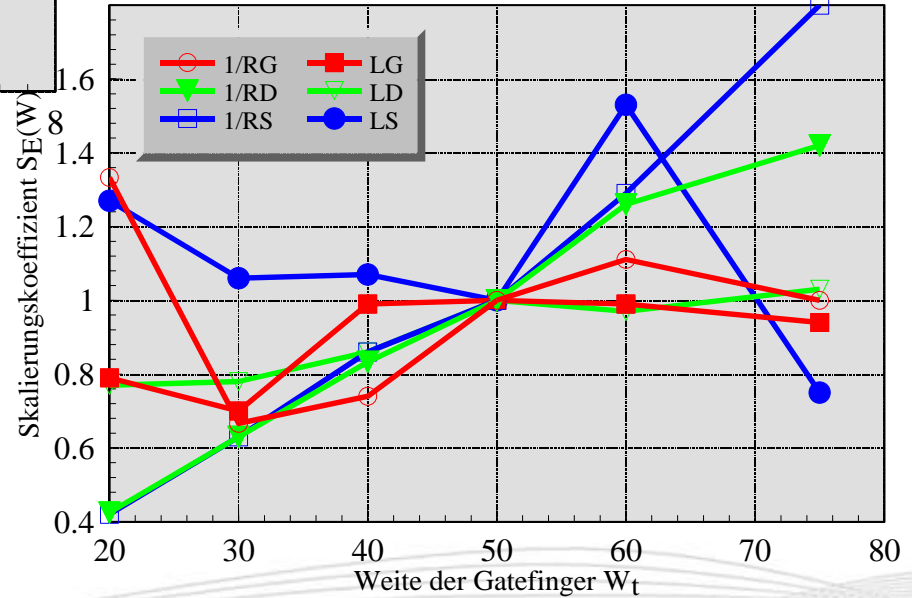


# Scaling of extrinsic elements



Variation of gate finger number

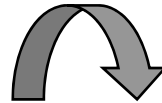
Variation of gate finger width





# Scaling of extrinsic elements

$$S_E(N) = a_{EN} \cdot N + b_{EN}$$



$$S_E(N, W_t) = S_E(N) \cdot S_E(W_t)$$

$$S_E(W_t) = a_{EW} \cdot W_t + b_{EW}$$

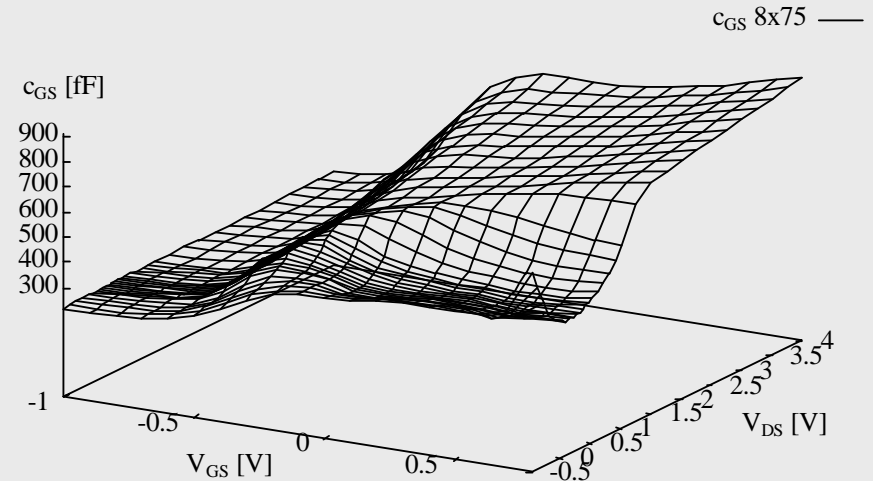
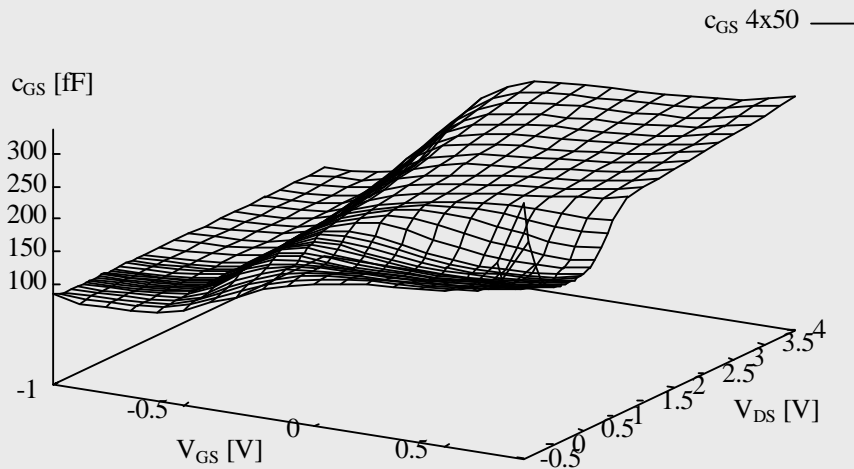
$S_E(N)$	$S_E(W)$	$a_{EN}$	$b_{EN}$	$a_{EW}$	$b_{EW}$
<b>GG</b>	<b>GG</b>	0.18	0.17	0.0	0.98
<b>GD</b>	<b>GD</b>	0.25	0.0	0.019	0.076
<b>GS</b>	<b>GS</b>	0.27	-0.04	0.024	-0.11
<b>1/LG</b>	<b>LG</b>	0.0	0.993	0.004	0.713
<b>1/LD</b>	<b>LD</b>	0.0	0.895	0.005	0.67
<b>LS</b>	<b>1/LS</b>	0.31	-0.46	0.006	0.68



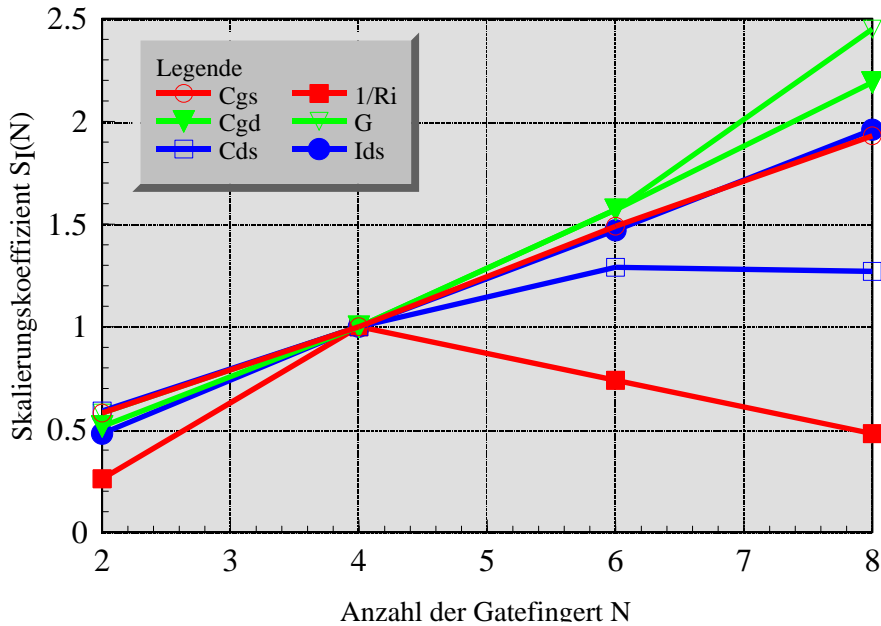
# Scaling of intrinsic elements

$$C_{old} = \frac{8 \times 75 \mu\text{m}}{4 \times 50 \mu\text{m}} = 3$$

$$C = \frac{\sum_{V_{gs}, V_{ds}} \frac{G_x(V_{GS}, V_{DS})}{G_{ref}(V_{GS}, V_{DS})}}{n_{V_{GS}, V_{DS}}}$$

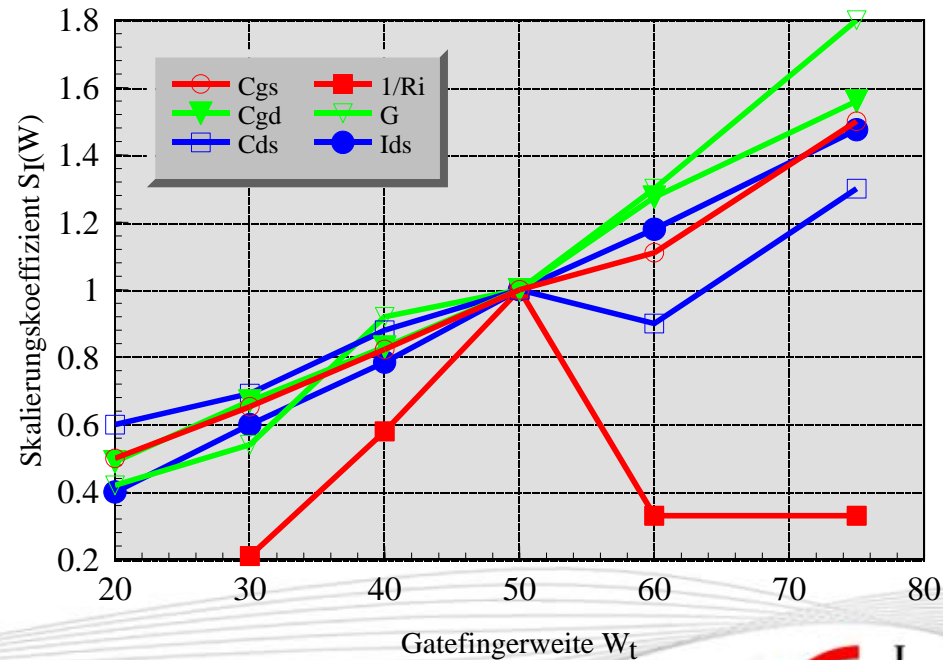


# Scaling of intrinsic elements



Variation of gate finger number

Variation of gate finger width



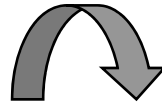




# Scaling of intrinsic elements

$$S_I(N) = a_{IN} \cdot N + b_{IN}$$

$$S_I(W) = a_{IWt} \cdot W + b_{IWt}$$



$$S_I(N, W) = S_I(N) \cdot S_I(W)$$

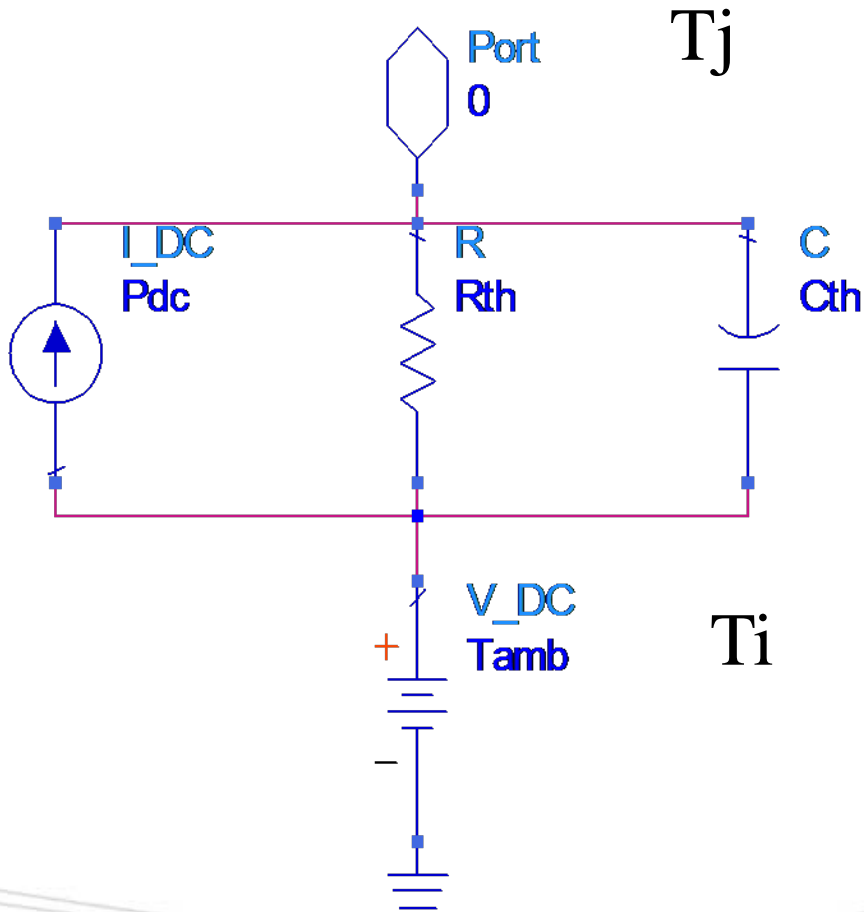
$S_I(N)$	$S_I(W)$	$a_{IN}$	$b_{IN}$	$a_{IW}$	$b_{IW}$
<b>Cgs</b>	<b>Cgs</b>	0.22	0.116	0.018	0.129
<b>Cgd</b>	<b>Cgd</b>	0.28	-0.08	0.019	0.077
<b>Cds</b>	<b>Cds</b>	0.12	0.459	0.011	0.371
<b>Gi</b>	<b>Gi</b>	0.02	0.52	-0.06	3.878
<b>G</b>	<b>G</b>	0.31	-0.14	0.025	-0.15
<b>Id</b>	<b>Id</b>	0.25	0.0	0.02	0.01

$$c_{new} = S_I(N = 4 \rightarrow N = 8) \cdot S_I(W_t = 50 \rightarrow W_t = 75)$$

$$1.93 \cdot 1.49 = 2.88$$



# Thermal model



$$C_{TH} \frac{d\Delta T}{dt} = P - \frac{\Delta T}{R_{TH}}$$

$$P = I_D V_{DS}$$

$$I_D = \frac{V_{Rd1} - V_{Rd2}}{R_D(V_{GS}, V_{DS})}$$

# 4D spline interpolation

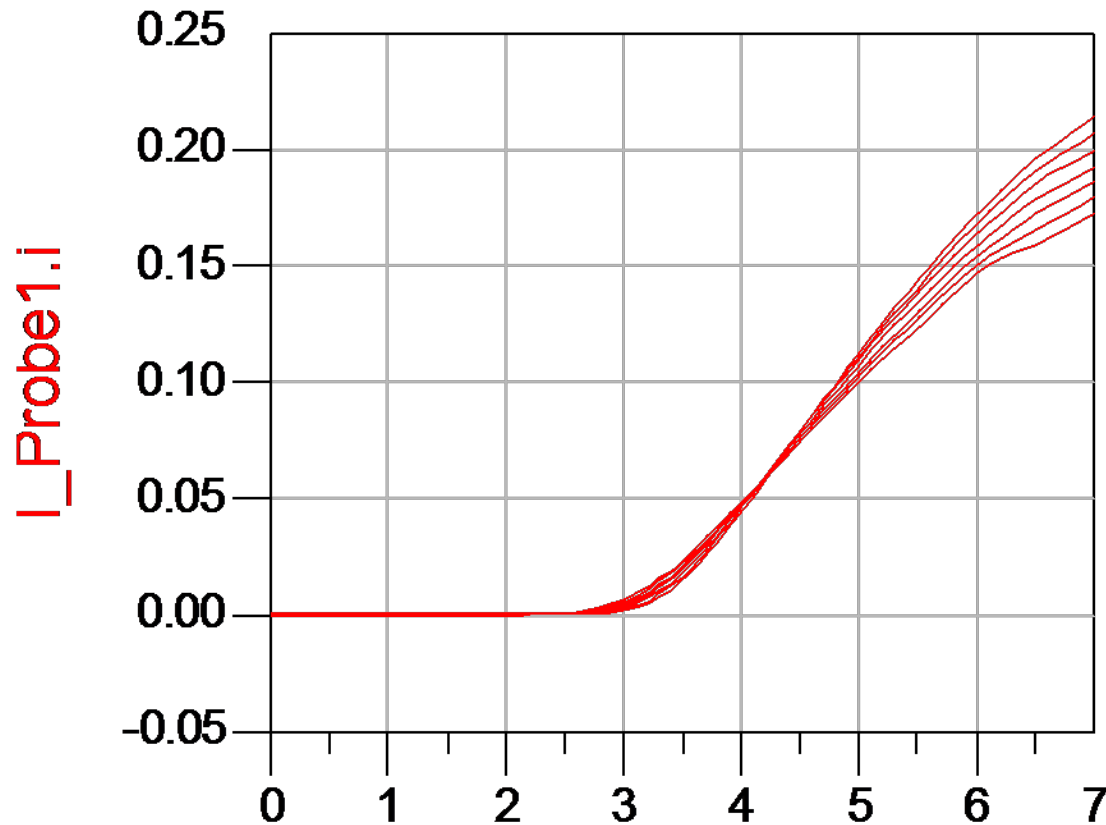
- Accurate description of  $I_D(V_{GS}, V_{DS}, T_{junc})$

$$f(\vec{x}) = \sum_{i=0}^3 \sum_{j=0}^3 \sum_{k=0}^3 a_{ijk} x_1^i x_2^j x_3^k$$

- 64 unknown values, 8 points at same time

$$f, \frac{\partial f}{\partial x_i}, \frac{\partial^2 f}{\partial x_i \partial x_j} \Big|_{i \neq j}, \frac{\partial^3 f}{\partial x_1 \partial x_2 \partial x_3}$$

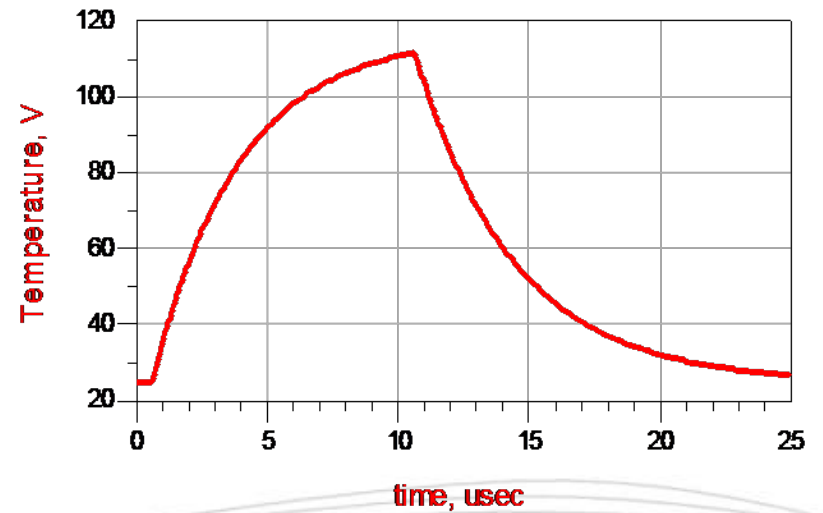
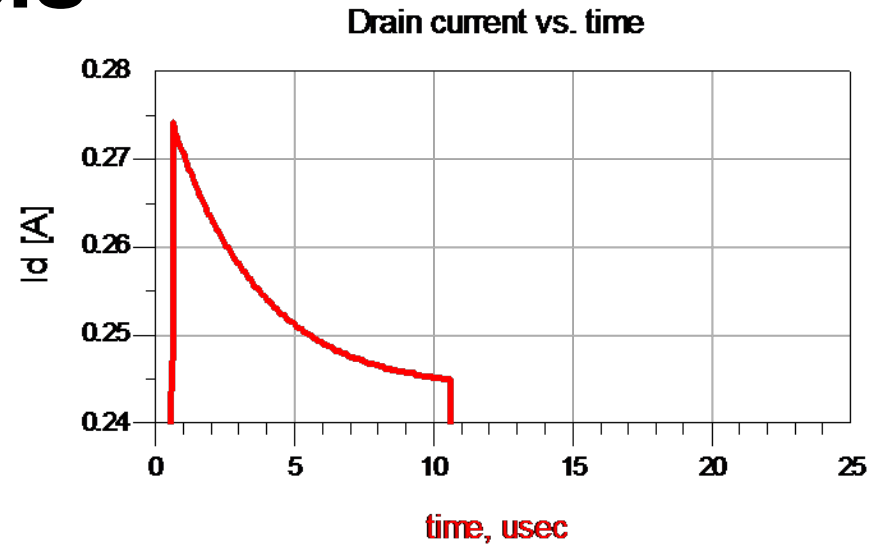
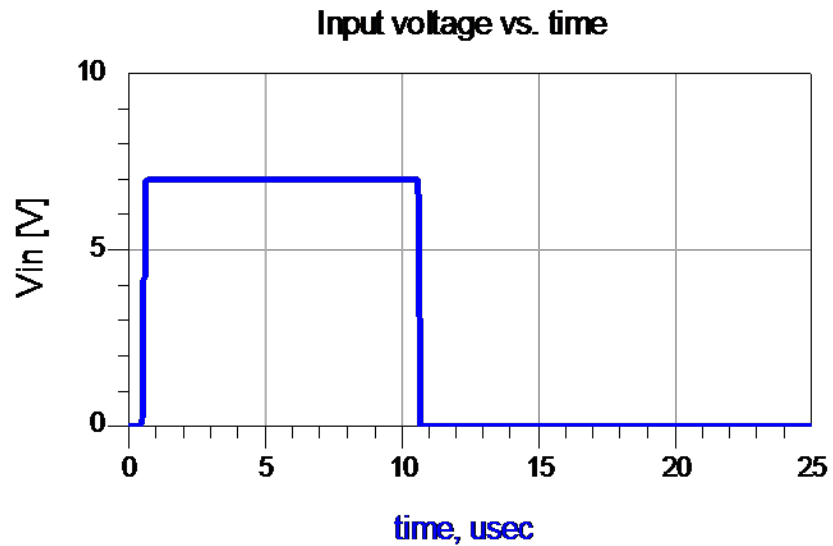
# DC verification (LDMOS example)



→ Intersection  
in one point

$V_{gs}$   
7x100 μm device

# Transient analysis



# Rth/Cth extraction

→ Compare pulsed and CW currents at different temperatures

$$R_{TH} = \frac{T - T_{amb}}{V_{DS} I_{DS}}$$

→ Cth: Monitor current versus time

# Thank you for you attention

→ Any questions?



# Model implementation into ADS

Rüdiger Follmann





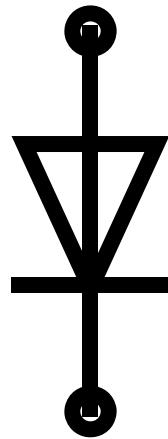
# Contents

- PN-diode, equivalent circuit and equations
- Linear part
- Non-linear part
- Linearized part
- Noise
- Interface
- Consistent implementation



# PN diode

Implementation of a pn-diode model  
into Agilent's ADS





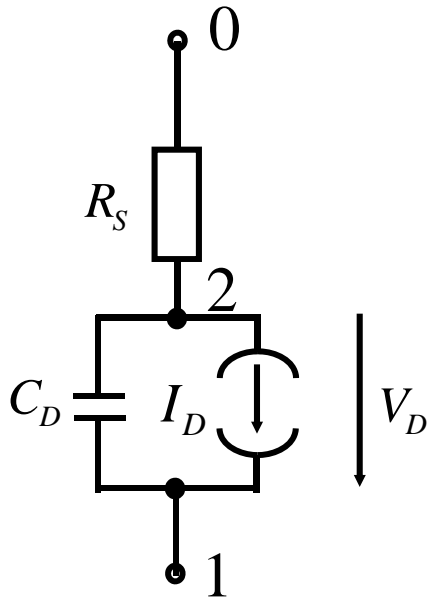
# How to start?

A non-linear model consists of the parts

- Equivalent circuit and associated equations
- Linear part containing linear elements
- Same with non-linear part
- Bias point dependent linearized part (Jacobian matrix)
- Bias dependent noise part



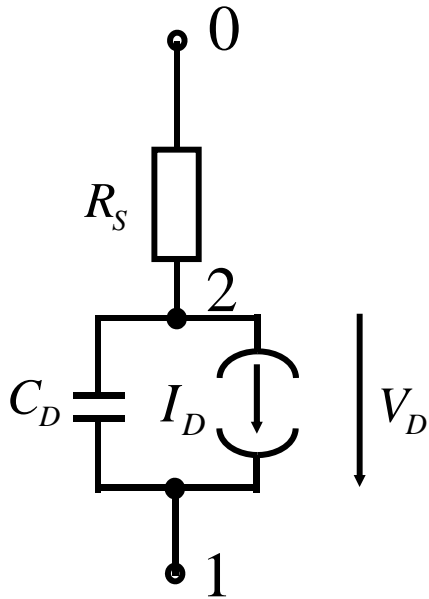
# ADS specific things



- All nodes are numbered
- Outer nodes get smallest numbers



# Equivalent circuit and equations



$$I_D(V_D) = I_S \left( e^{\frac{V_D}{V_{te}}} - 1 \right) + 10^{-12} \frac{\text{A}}{\text{V}} V_D$$

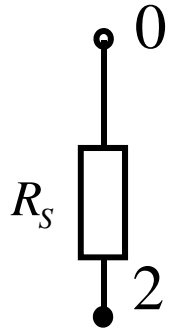
$$\frac{dI_D}{dV_D} = \frac{I_S e^{\frac{V_D}{V_{te}}}}{V_{te}} + 10^{-12} \frac{\text{A}}{\text{V}}$$

$$C_D(V_D) = TT \frac{dI_D}{dV_D} + CJO \left( 1 - \frac{V_D}{VJ} \right)^{-M}$$

$$Q_D(V_D) = \int_0^{V_D} C_D(\tilde{V}_D) d\tilde{V}_D = TT \cdot I_D + \frac{VJ \cdot CJO}{1-M} \left( 1 - \left( 1 - \frac{V_D}{VJ} \right)^{1-M} \right)$$



# Linear part



$R_s$  is the only linear element between nodes 0-2

COMPLEX  $y$ ;

```
y.real = 1/Rs; y.imag = 0.0;  
status = add_y_branch(userInst, 0, 2,  
y);
```

Admittances here

nodes

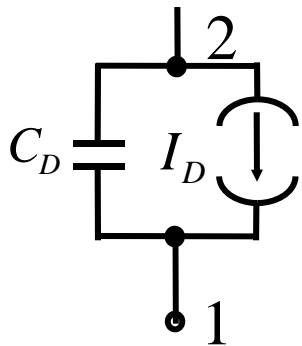
Y-matrix





# Non-linear part

- Number all nodes in order to get the voltages
- Start with outer nodes
- Use code calculates charges at each node and non-linear currents out of each node



$I_D$  and  $C_D$  are non-linear elements between nodes 1-2



# Linearized part

- Calculation of partial derivatives for non-linear elements with respect to the nodes to get capacitances and conductances for Jacobian matrix
- The linearized part does not influence the final harmonic balance solution
- The linearized part influences the convergence speed





# Noise

→ Noise part contains the bias dependent correlation parameters - normalized to  $4kT_0$

→ This part is only needed for noise analysis

## Possible noise sources:

Thermal noise  $\langle i_{th}^2 \rangle = \frac{4kT_0}{R} \Delta f$

Shot noise  $\langle i_{shot}^2 \rangle = 2qI_D \Delta f$

1/f noise  $\langle i_{1/f}^2 \rangle = KF \frac{I_D^{AF}}{f^{FFE}} \Delta f$

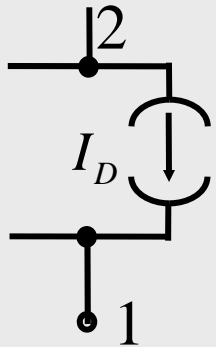
Burst or popcorn noise

$$\langle i_{burst}^2 \rangle = KB \frac{I_D^{CF}}{1 + \left( \frac{f}{f_{CF}} \right)^2} \Delta f$$



# Non-linear part

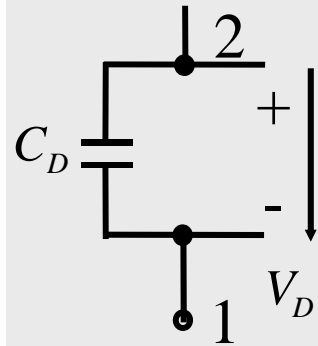
## Calculation of node currents and charges



Node 1:  $i_1 = -I_D$

Node 2:  $i_2 = +I_D$

Current from node:+, to node:-



Node 1:  $q_1 = -Q_D$

Node 2:  $q_2 = +Q_D$

	Node	i	q
		↓	↓
		↓	↓



```
status = add_nl_iq(userInst, 1, -id, -qd) &&
         add_nl_iq(userInst, 2, +id, +qd);
```





# Jacobian matrix

$$\frac{\partial I_1}{\partial V_1} = -1 \cdot \left( -\frac{dI_D}{dV_D} \right) = \frac{dI_D}{dV_D}$$

$$\frac{\partial I_1}{\partial V_2} = -\frac{dI_D}{dV_D}$$

$$\frac{\partial I_2}{\partial V_1} = -\frac{dI_D}{dV_D}$$

$$\frac{\partial I_2}{\partial V_2} = \frac{dI_D}{dV_D}$$

$$\frac{\partial Q_1}{\partial V_1} = C_D$$

$$\frac{\partial Q_1}{\partial V_2} = -C_D$$

$$\frac{\partial Q_2}{\partial V_1} = -C_D$$

$$\frac{\partial Q_2}{\partial V_2} = C_D$$



Real part



Imaginary part

partial derivatives

g

c

+  
-



$$V_D = V_2 - V_1$$

status =

```
add_nl_gc(userInst, 1, 1, +gd, +cd) &&
add_nl_gc(userInst, 1, 2, -gd, -cd) &&
add_nl_gc(userInst, 2, 1, -gd, -cd) &&
add_nl_gc(userInst, 2, 2, +gd, +cd);
```





# Noise

```
COMPLEX thermal, dNoise;
```

```
thermal.imag = dNoise.imag = 0.0;
```

```
thermal.real = 1.0/Rs*DEV_TEMP/NOISE_REF_TEMP;
```

Thermal noise

```
dNoise.real = 2 * CHARGE * id;
```

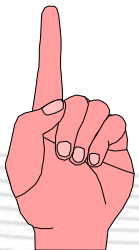
Shot noise

```
dNoise.real = kf * pow(id, AF)*pow(omega/TWOPI, -FFE);
```

1/f noise

```
dNoise.real /= FOUR_K_T0;
```

```
status =      add_n_branch(userInst, 0, 2, thermal) &&  
              add_n_branch(userInst, 1, 2, dNoise);
```



**Attention: All noise currents are normalized to  $4KT_0$**



# Interface

`nonlin_ele.h`

```
// name      numPars   params   compute_y   post_analysis   senior Info  
//   numExtNodes  pre_analysis  compute_n   devDef   tranDef
```

```
{"PNDIODE", 0, size(PNDIODE), PNDIODE, NULL, NULL, NULL, NULL,  
NULL, NULL, NULL}
```

`nonlin_def.h`

```
static UserNonLinDef PNDIODE =  
{  
    0,          /* numIntNodes */  
    NULL,      /* analyze_lin() */  
    sdiode_nl, /* analyze_nl() */  
    sdiode_ac, /* analyze_ac() */  
    NULL,     /* modelDef   */  
    NULL     /* analyze_ac_n */  
};
```



# Interface

nonlin\_typ.h

```
PNDIODE[] =  
{ /* P-N junction diode */  
  {"AREA",  REAL_data},  
  {"IS",    REAL_data},  
  {"RS",    REAL_data},  
  {"N",     REAL_data},  
  {"TT",    REAL_data},  
  ...  
}
```

nonlin\_fun.h

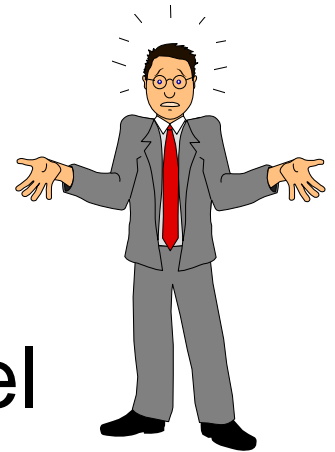
```
* NON-LINEAR PN-DIODE MODEL */  
EXTERN_FUNCTION( extern boolean  pndiode_lin, (UserInstDef *userInst, double omega));  
EXTERN_FUNCTION( extern boolean  pndiode_nl,  (UserInstDef *userInst, double *vPin));  
EXTERN_FUNCTION( extern boolean  pndiode_ac,  (UserInstDef *userInst, double *vPin, double omega));  
EXTERN_FUNCTION( extern boolean  pndiode_ac_n,(UserInstDef *userInst, double *vPin, double omega));
```

# Interface

→ AEL programming language is the GUI for the simulator



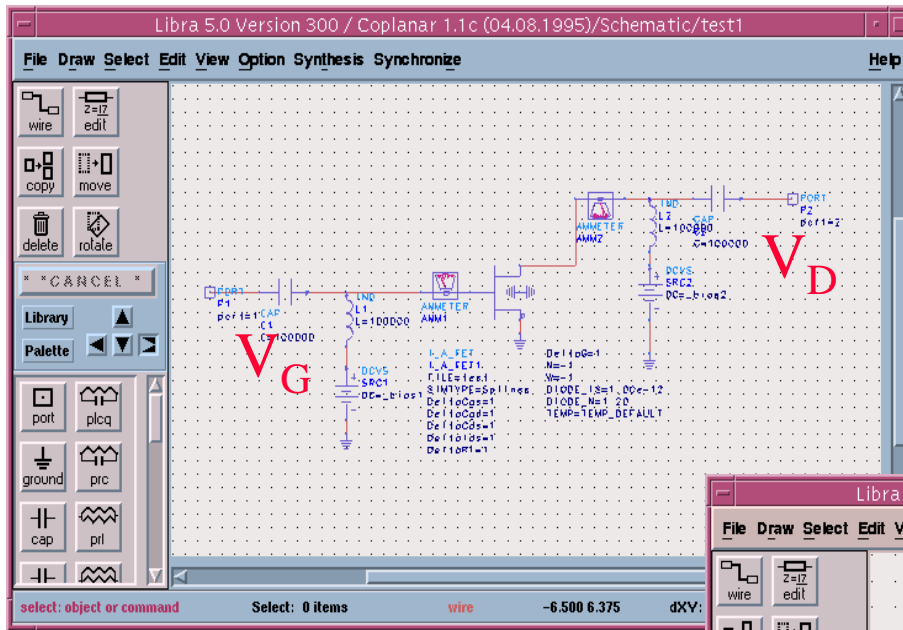
# Summary



- Different parts of a non-linear model
- Nonlinear equations and their derivatives
- Implementation into circuit simulation software
- Noise sources
- Jacobian matrix



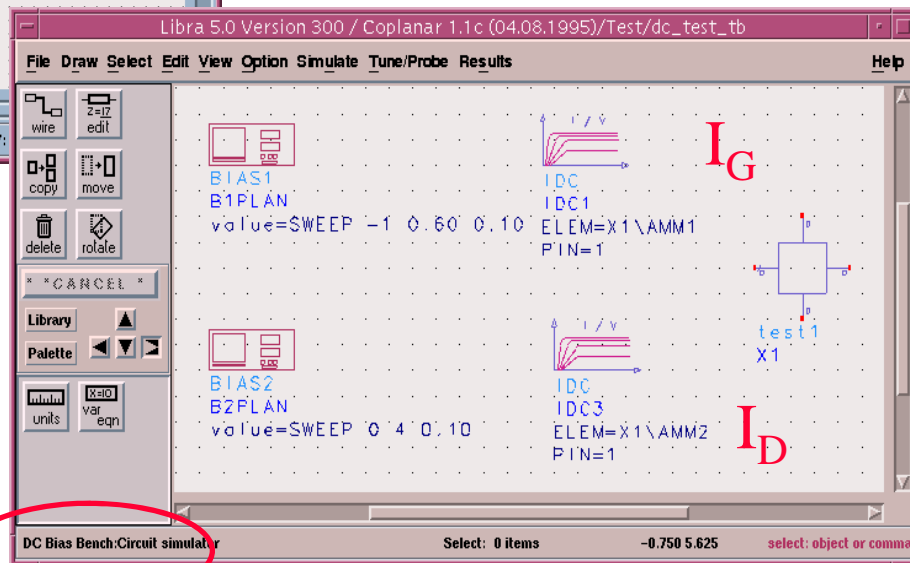
# DC tests



All tests are shown for a transistor device. They are valid for diode devices as well.

Perform a DC analysis first!

Only currents are calculated

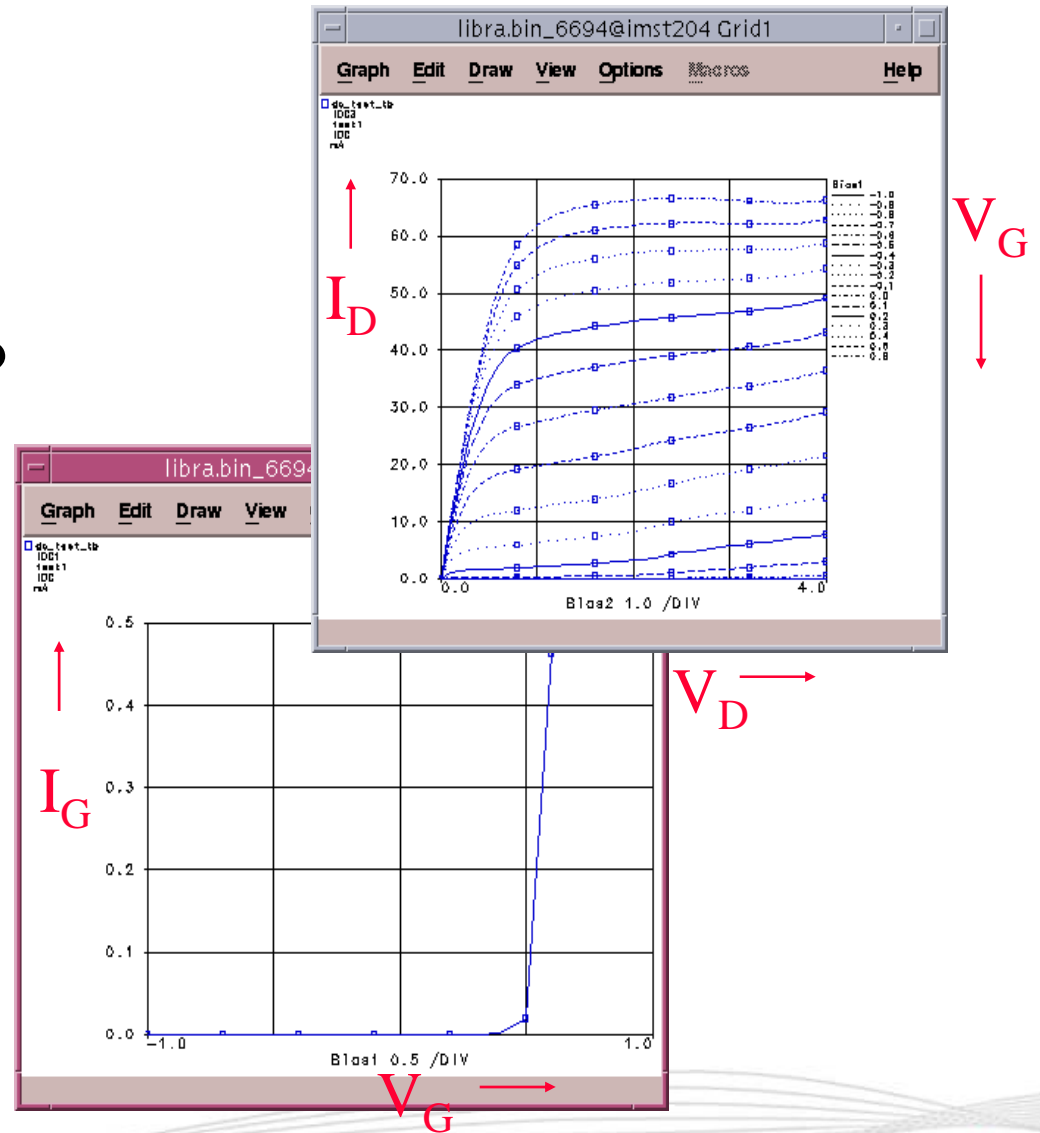


DC testbench



# DC tests

- IV output curves OK?
- IV input curves OK?
- Curves typical for element?
- Show measurements similar behaviour?

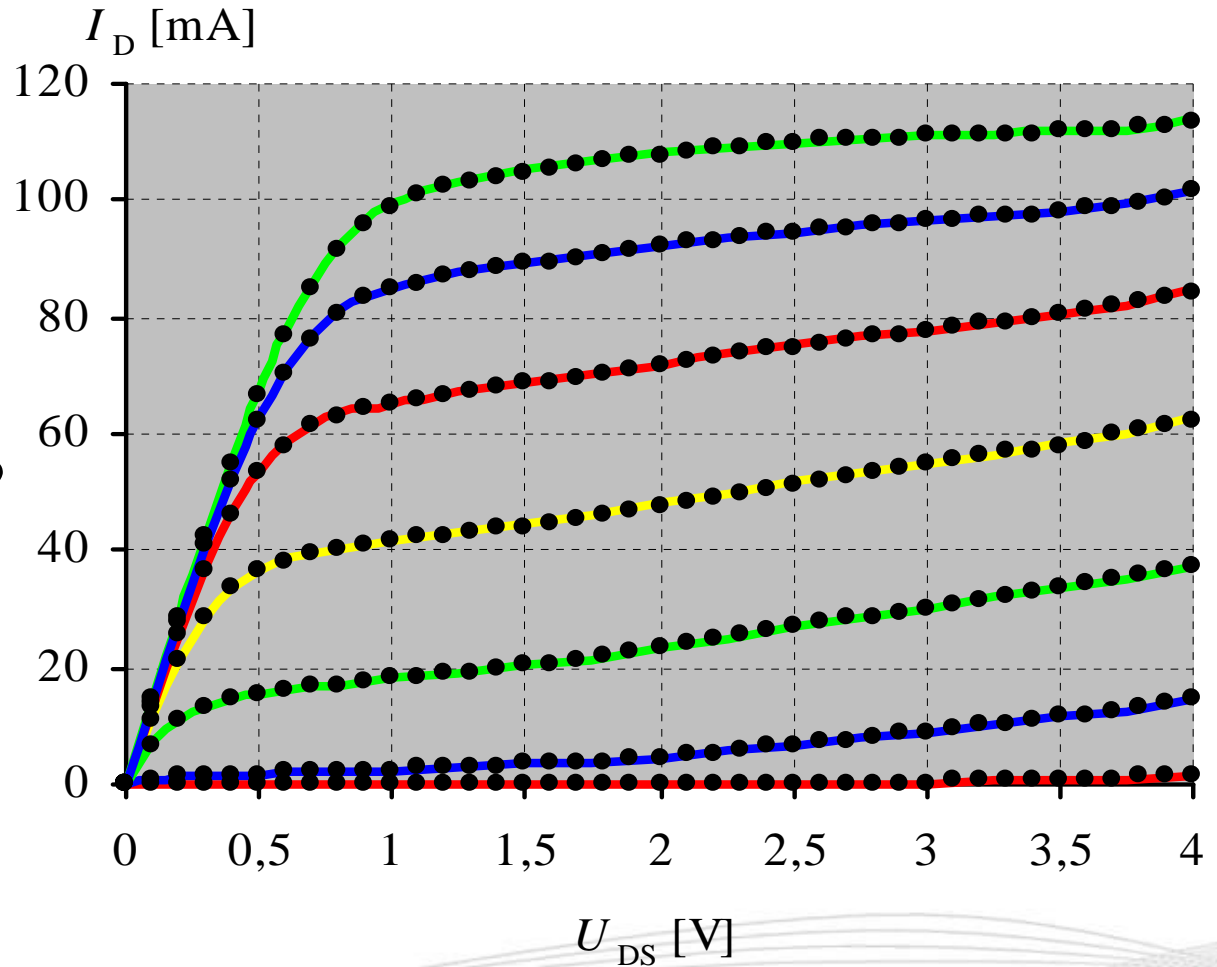




# DC tests

T4x50 $\mu\text{m}$  HEMT, simulation vs. measurements

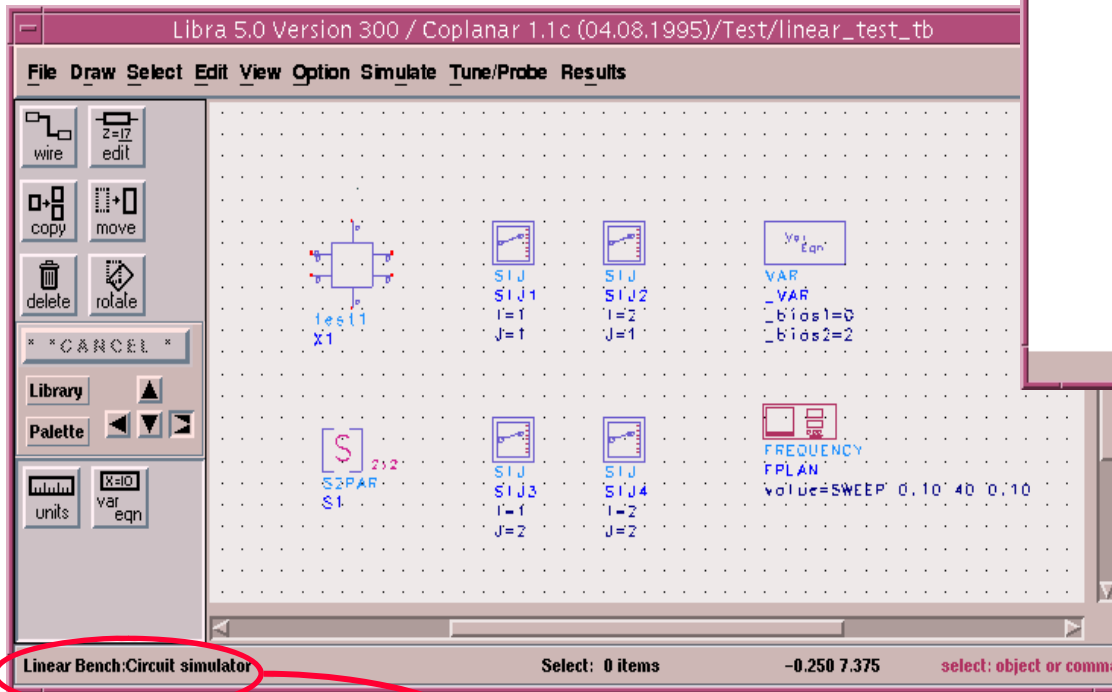
Show simulation and measurements similar behaviour?



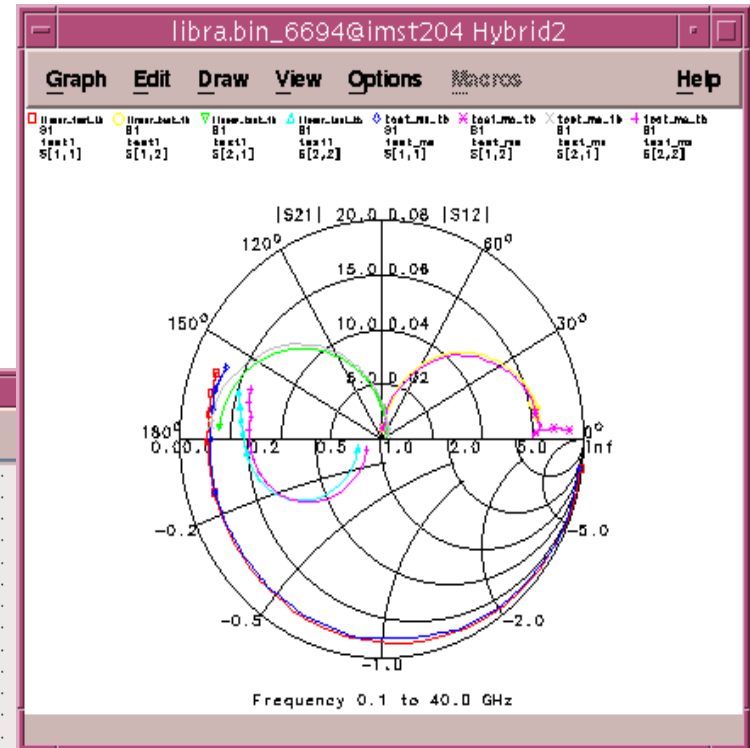
# RF Tests

Are measured and simulated S-parameters similar ?

Transistor: Gain, pinch-off S-parameters OK?



Lineares testbench

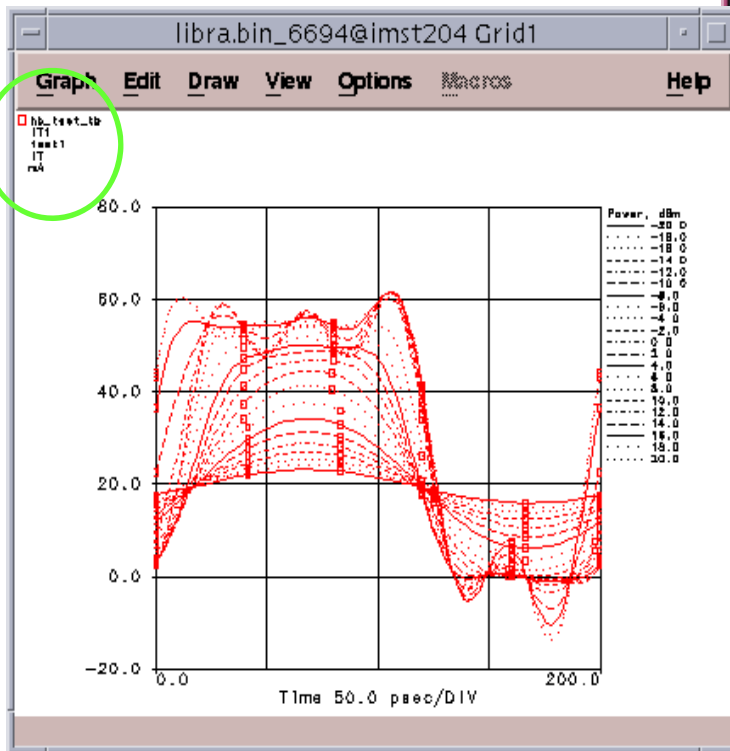
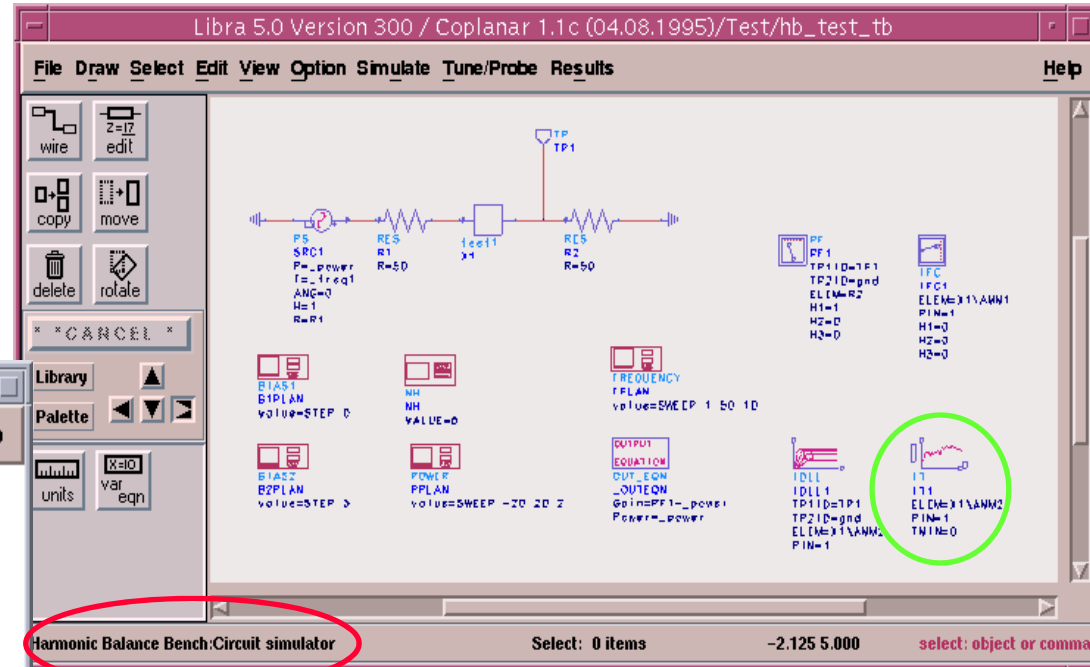


Diode: Forward and reverse S-parameters OK?



# HB tests

Simulate a power sweep



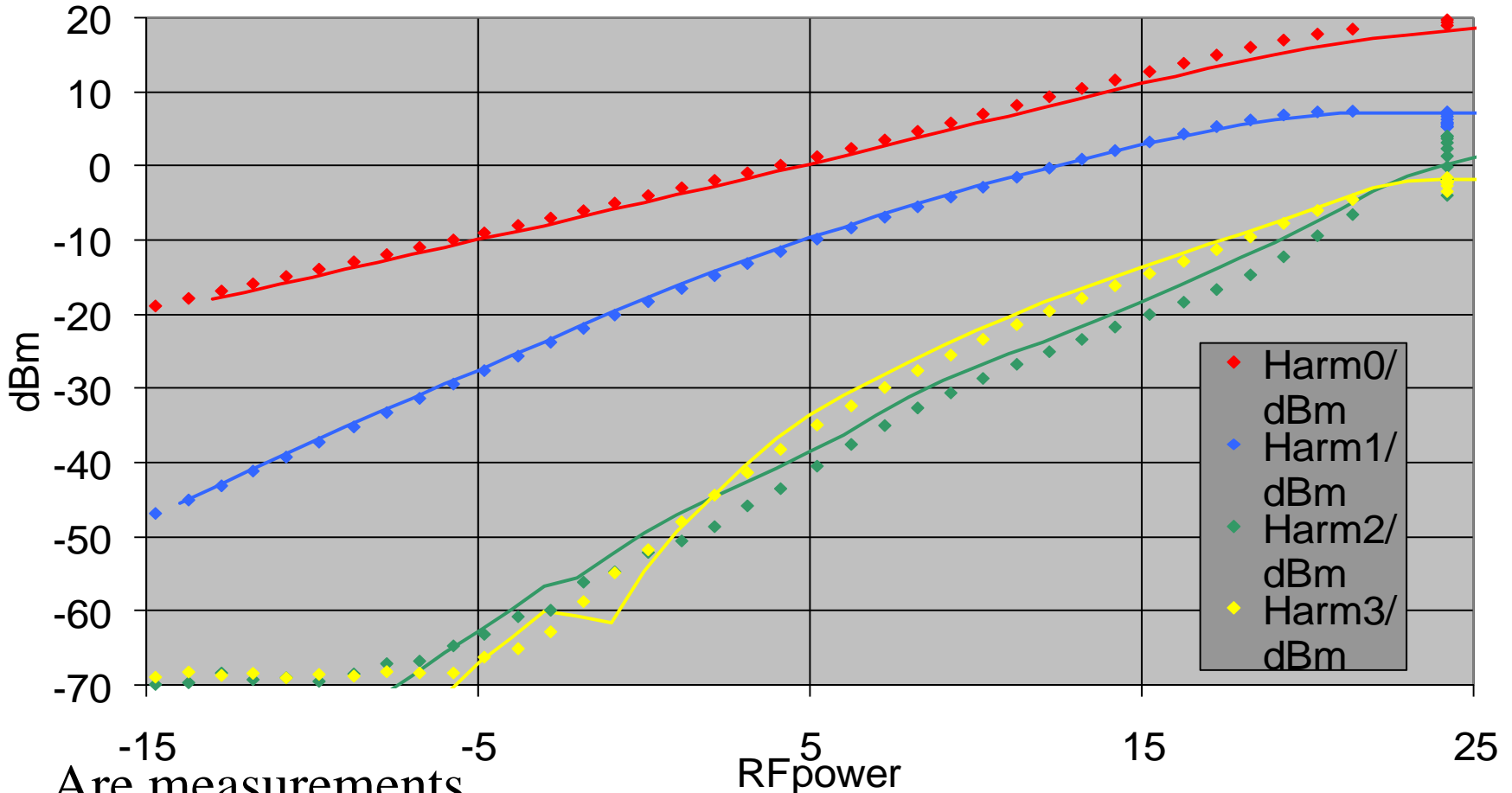
Harmonic Balance testbench

Is the behaviour as expected?  
Are the nonlinearities dominant  
for high input power



# HB tests

Comp 1x600 2.1 GHz , 26 V, 2.1 mA



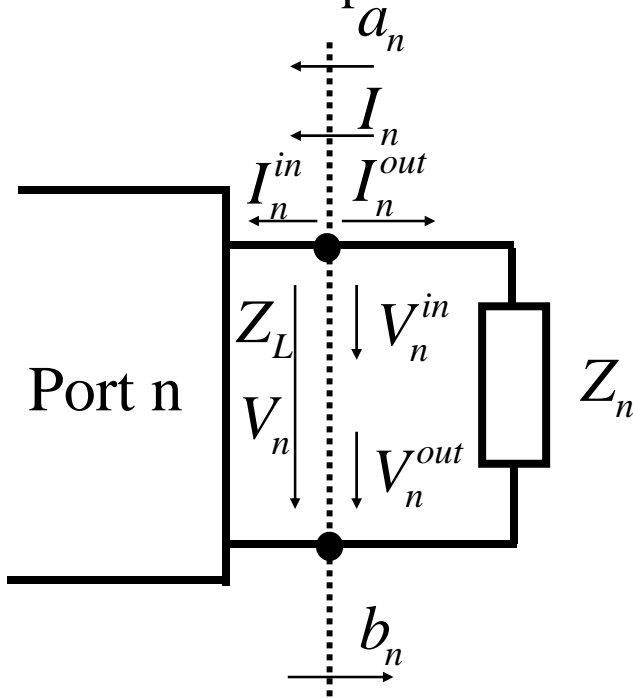
Are measurements  
and simulations  
similar ?

How good is the  
quality of the model ?



# Consistent implementation

Calculation of s-parameters using voltage and current definition



Waves in and out of port n

$$a_n = \frac{V_n^{in}}{\sqrt{Z_{Ln}}} = I_n^{in} \sqrt{Z_{Ln}}$$

$$b_n = \frac{V_n^{out}}{\sqrt{Z_{Ln}}} = I_n^{out} \sqrt{Z_{Ln}}$$

Currents and voltages

$$u_n = \frac{V_n}{\sqrt{Z_{Ln}}} = \frac{V_n^{in} + V_n^{out}}{\sqrt{Z_{Ln}}} = a_n + b_n$$

$$i_n = I_n \sqrt{Z_{Ln}} = (I_n^{in} - I_n^{out}) \sqrt{Z_{Ln}} = a_n - b_n$$

$$\Rightarrow \begin{cases} a_n = \frac{1}{2}(u_n + i_n) \\ b_n = \frac{1}{2}(u_n - i_n) \end{cases}$$

S matrix

$$\|b\| = \|s\| \cdot \|a\|$$

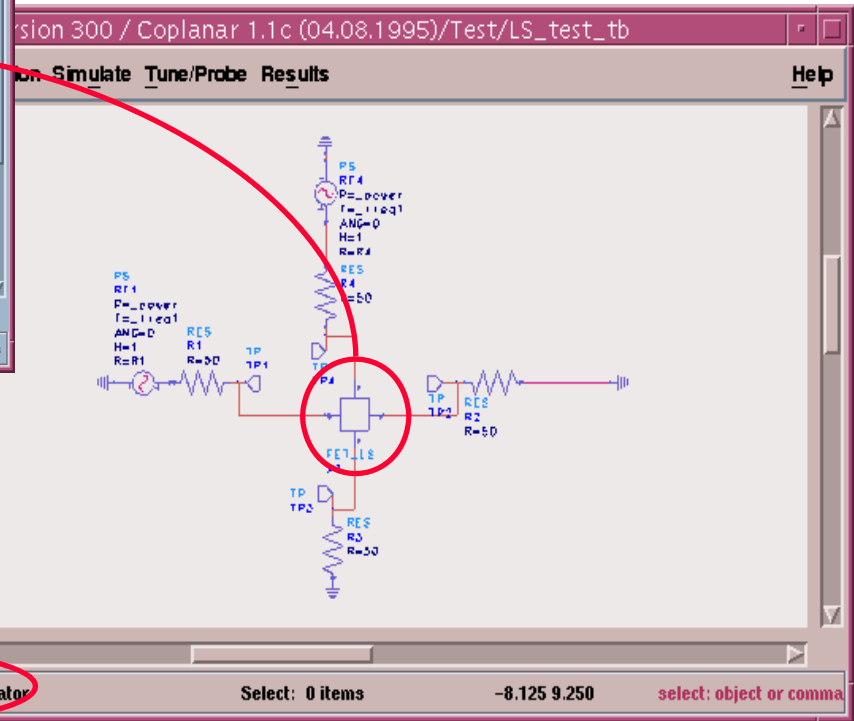
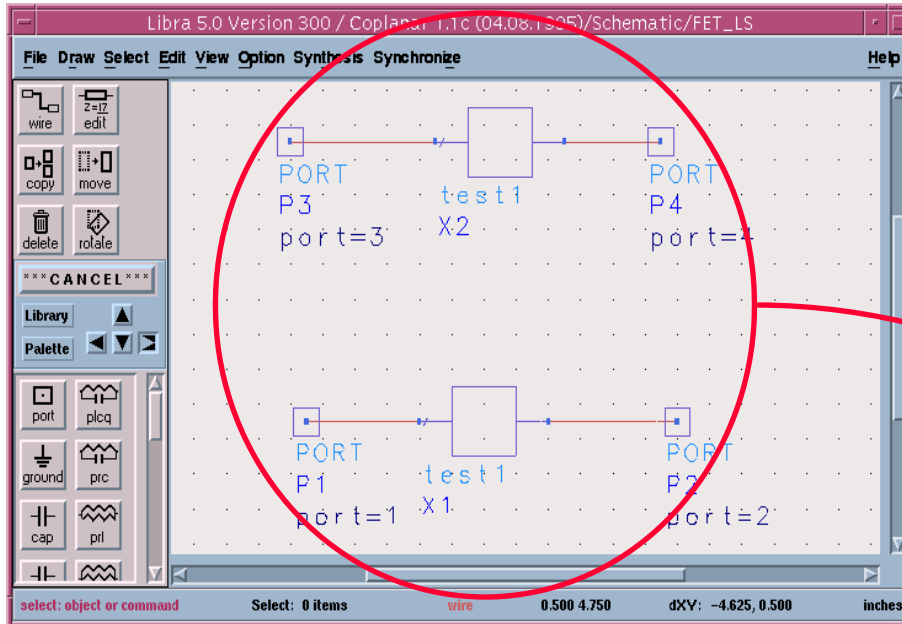
Example

$$s_{11} = \left. \frac{b_1}{a_1} \right|_{a_2=0}$$

$$s_{11,dB} = 20 \cdot \log \frac{u_1 - i_1}{u_1 + i_1}$$

# Consistent implementation

Calculation of small signal S-parameters using a large signal test bench



Harmonic balance testbench

Harmonic Balance Bench: Circuit simulator





# Consistent implementation

Calculation of small signal s-parameters using a large signal testbench

```

OUTPUT
EQUATION
OUT_EQN
OUTEQN
a11=VFC1/7.07+IFC1*7.07*1e-3
a22=VFC4/7.07+IFC4*7.07*1e-3
b11=VFC1/7.07-IFC1*7.07*1e-3
b22=VFC4/7.07-IFC4*7.07*1e-3
b21=VFC2/7.07-IFC2*7.07*1e-3
b12=VFC3/7.07-IFC3*7.07*1e-3
s11=20*log(b11/a11)
s11_ang=b11/a11
s22=20*log(b22/a22)
s22_ang=b22/a22
s21=20*log(b21/a11)
s21_ang=b21/a11
s12=20*log(b12/a22)
s12_ang=b12/a22
    
```

VFC1	IFC1	VFC2	IFC2	VFC3	IFC3
TP1 ID=TP1	ELEM=R1	TP1 ID=TP2	ELEM=R2	TP1 ID=TP3	ELEM=R3
TP2 ID=gnd	PIN=1	TP2 ID=gnd	PIN=1	TP2 ID=gnd	PIN=1
H1=1	H1=1	H1=1	H1=1	H1=1	H1=1
H2=0	H2=0	H2=0	H2=0	H2=0	H2=0
H3=0	H3=0	H3=0	H3=0	H3=0	H3=0

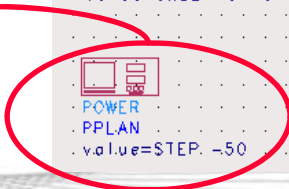
VFC4	IFC4
TP1 ID=TP4	ELEM=R4
TP2 ID=gnd	PIN=1
H1=1	H1=1
H2=0	H2=0
H3=0	H3=0

NH	P <sub>out_RF</sub>	P <sub>in</sub>	PSPEC1
NH	TP1 ID=TP2	TP1 ID=TP1	TP1 ID=TP2
VALUE=5	TP2 ID=gnd	TP2 ID=gnd	TP2 ID=gnd
	ELEM=R2	ELEM=R1	ELEM=R2
	H1=1	H1=1	
	H2=0	H2=0	
	H3=0	H3=0	

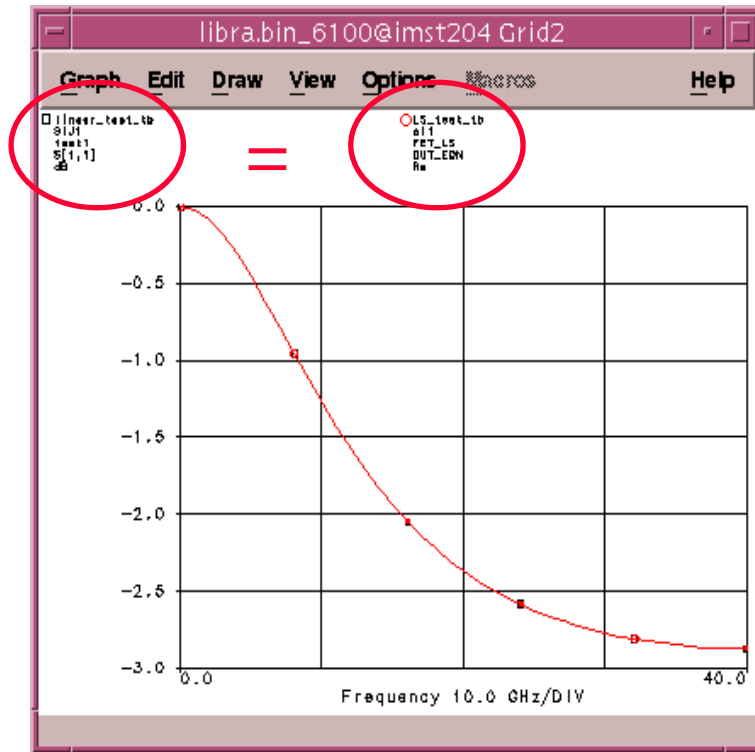
  

FREQUENCY	PPLAN	B2PLAN
FPLAN	value=SWEEP: 0:10:40:1	value=STEP: -50

Small signal!  
-50 dBm

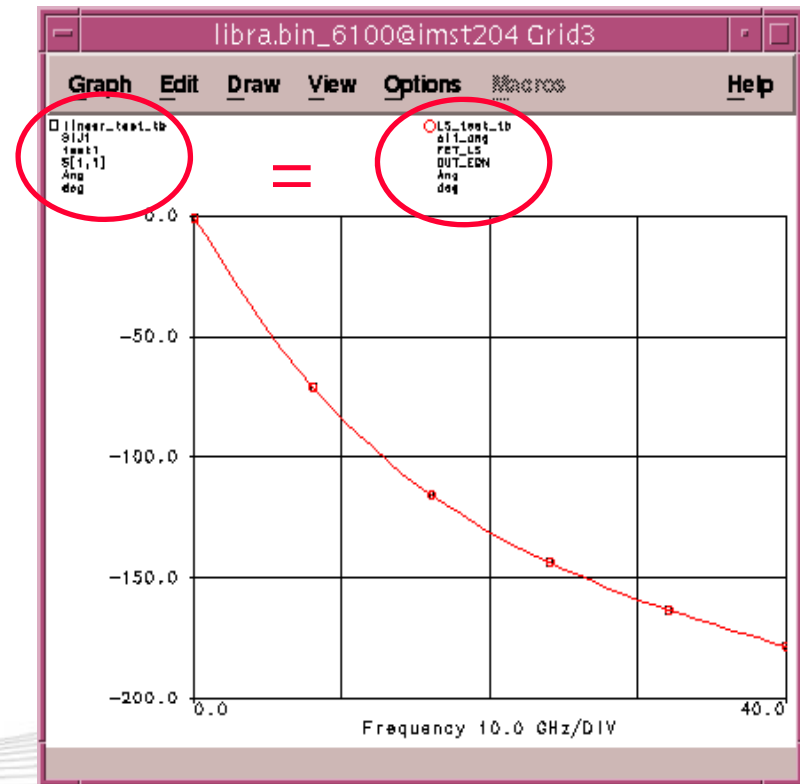


# Consistent implementation



Mag( $s_{11}$ ), simulated using  
Small signal and large signal  
testbench for very low  
input power (-50 dBm)

Phase( $s_{11}$ ), simulated using  
Small signal and large signal  
testbench for very low  
input power (-50 dBm)





# Needful things

Linearize  $\exp()$  function for better conversion and avoid errors such as numerical overflows

$$f(x) = \begin{cases} \exp(x) & x \leq x_0 \\ mx + b & x > x_0 \end{cases}$$

Function must be continuous at  $x_0$

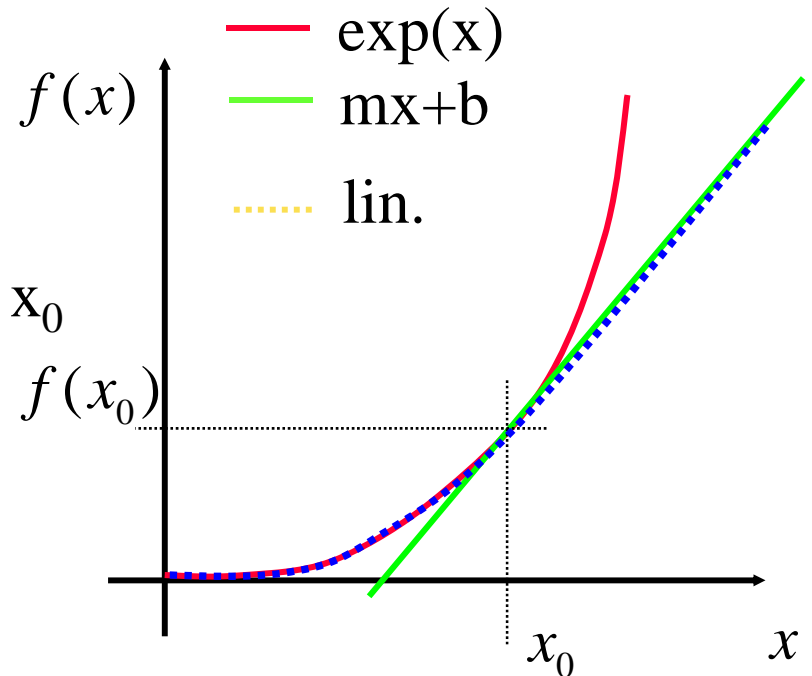
$$f_1(x_0) = f_2(x_0)$$

$$\left. \frac{df_1}{dx} \right|_{x_0} = \left. \frac{df_2}{dx} \right|_{x_0}$$

$$\Rightarrow \exp(x_0) = mx_0 + b$$

$$m = \exp(x_0)$$

$$\Rightarrow b = \exp(x_0)(1 - x_0) \Rightarrow f_2(x) = \exp(x_0)(x + 1 - x_0)$$





# Summary

- Perform different tests (DC, RF, harmonic balance)
- Typical results for a FET
- Calculation of small signal s-parameters using a large signal testbench
- Linearization of functions



Foundries, MMICs, systems

Rüdiger Follmann



# Content

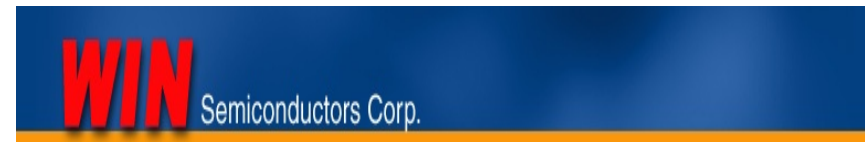
- MMIC foundries
- Designs and trends
- Examples

# MMIC foundries

## Foundries



IMST is a UMS  
certified design house



## Memberships



MOSIS



# GaAs in principal

- 3,4 and 6 inch production
- Target markets: High power and linearity, low noise, broad band
- Specials available (e.g. E/D mode or HBT and pHEMT on same wafer)
- Frequencies up to 100 GHz
- Radiation hard



# GaAs foundries

→ OMMIC, France

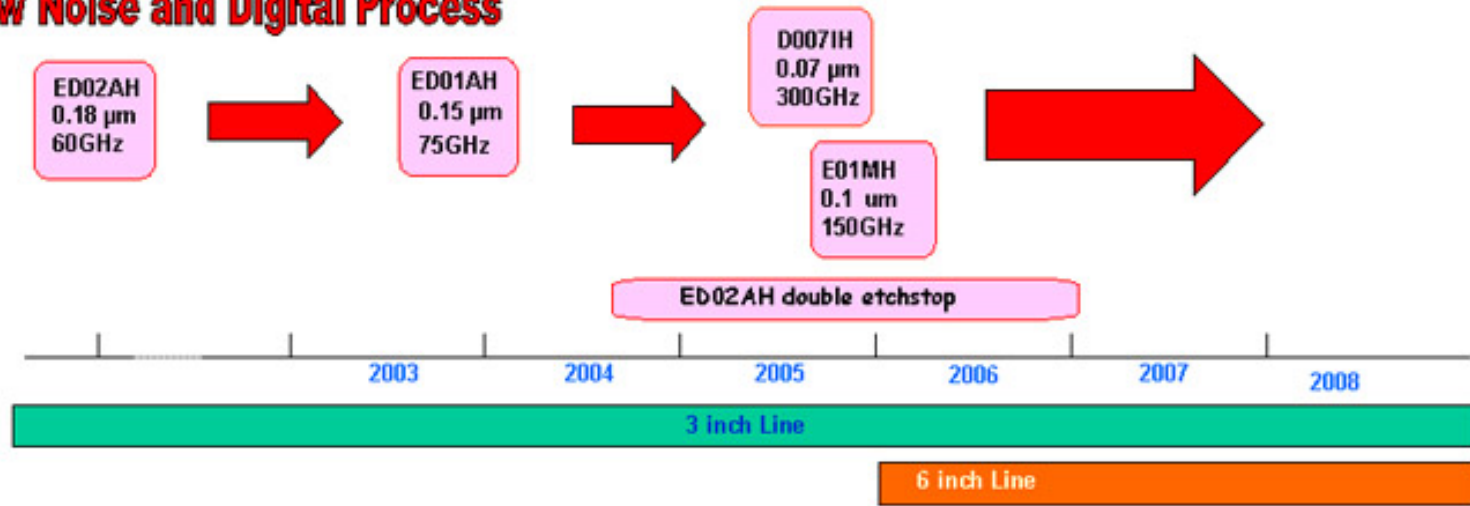
## Power Process



## InP HBT



## Low Noise and Digital Process



# GaAs foundries

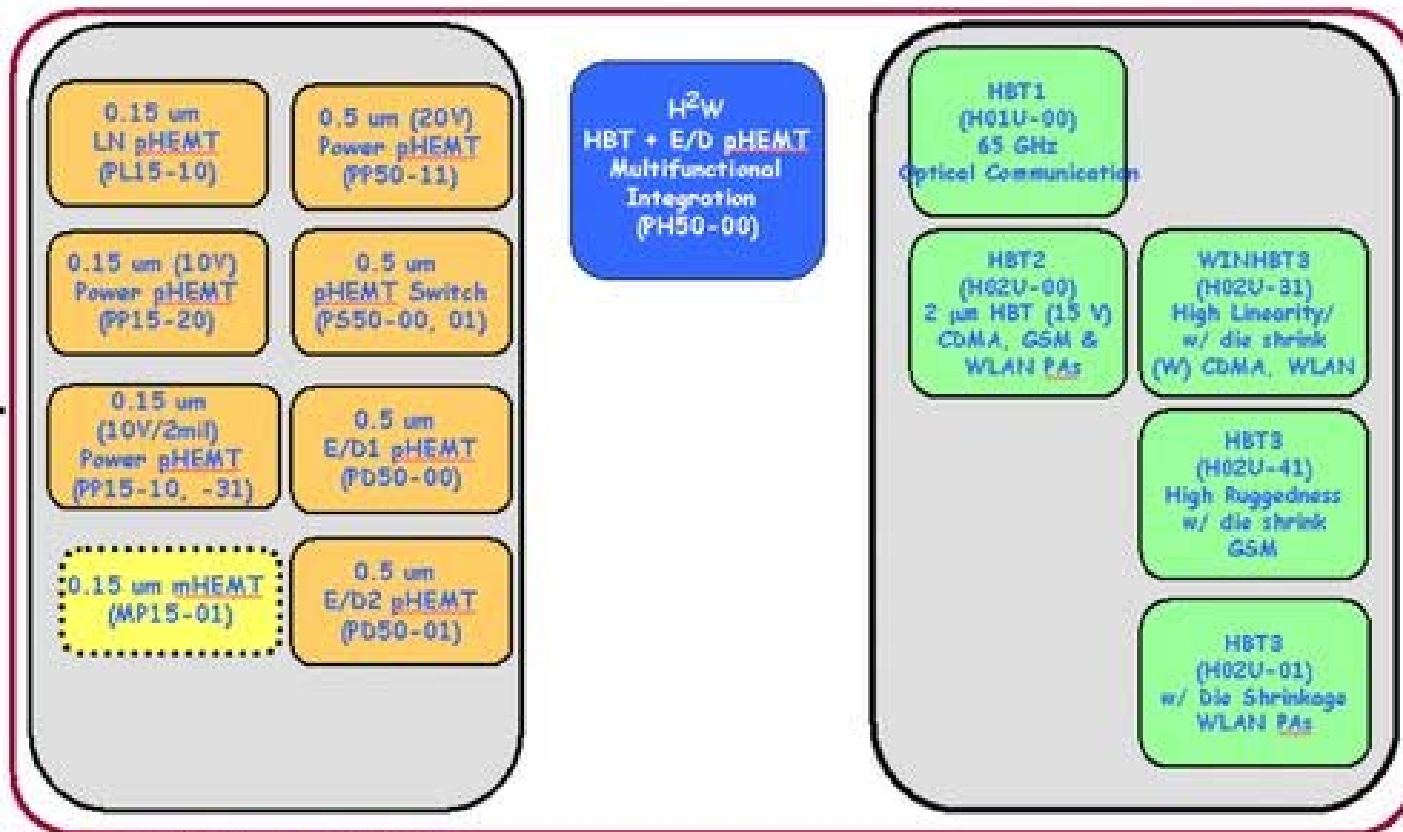
→ UMS, France (+ USA)



# WIN, Taiwan

→ WIN, Taiwan

## Technology Roadmap - In Production



• Process qualified and model ready.

• Conditional Release

# GaN

- 4 inch to 6 inch wafers
- Several foundries (TriQuint, UMS, Cree, Sandia and others)
- Very high power possible
- Defense market, radar, telecommunication
- Single transistor devices available, very first MMICs launched (IMS 2008, Cree)
- „Reliability“ problems
- Frequencies up to 20 GHz and higher (100 GHz)

# State-of-the-art

→ HRL examples

## GaN HFET MMIC Power Amplifiers

GaN POWER AMPLIFIERS

Part Number	Function	Frequency (GHz)	Gain (dB)	P1dB (dBm)	Psat (dBm)	Application Note
<a href="#">PA3C-76</a>	High Power Amplifier	71-76	15	24	26	<a href="#">X</a>
<a href="#">PA3C-86</a>	High Power Amplifier	81-86	13	24	26	<a href="#">X</a>
<a href="#">PA3C-96</a>	High Power Amplifier	91-96	12	23.5	25.5	<a href="#">X</a>

<http://www.hrl.com/media/gan/gan.html>

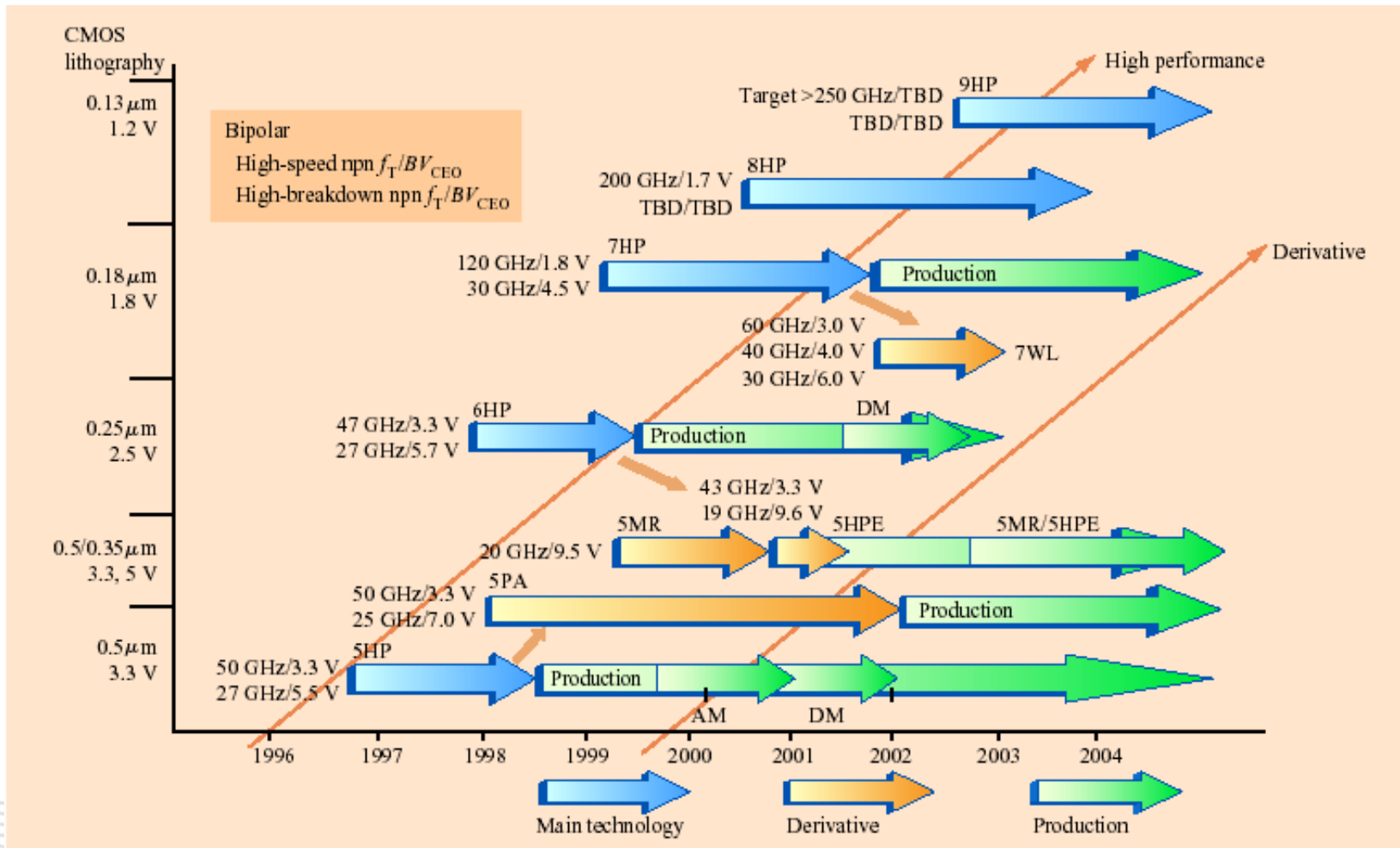
<http://kiss.caltech.edu/mmic2008/presentations/micovic.pdf>

# Si(Ge)

- 8 inch production
- Combination of CMOS logic, ECL and BiCMOS
- Frequencies up to 100 GHz
- Complete transceiver chips possible (e.g. 60 GHz)
- Well known foundries e.g. IBM (8HP)
- Si LDMOS for high power

# SiGe

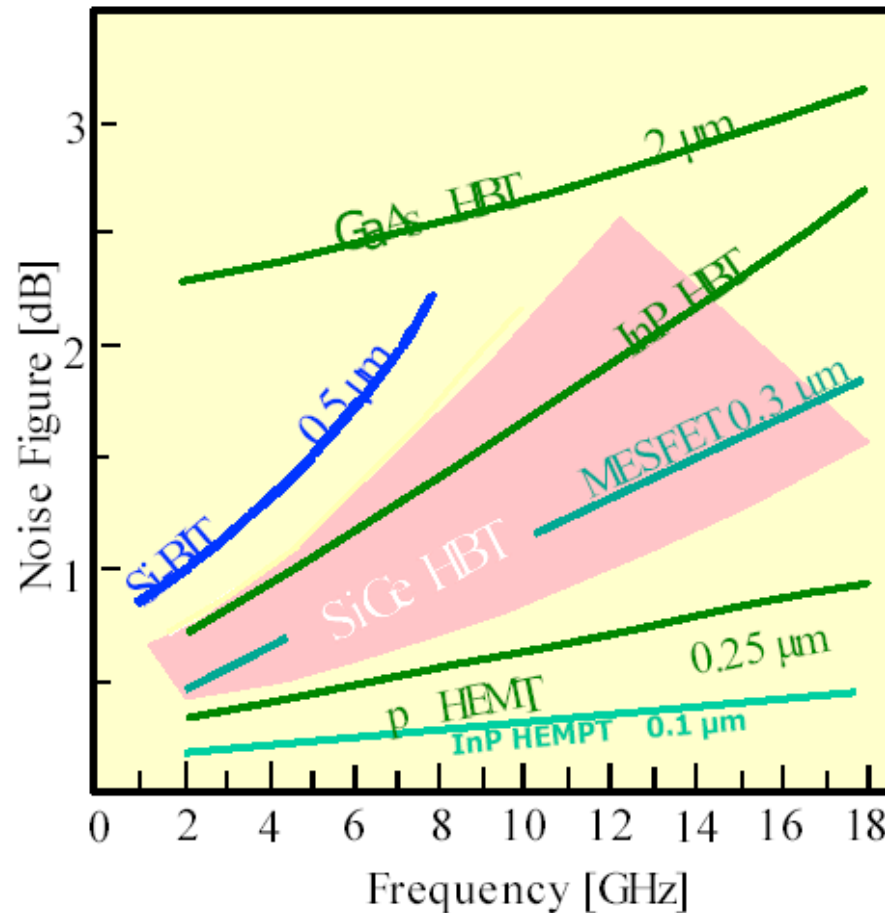
## → IBM roadmap



# Trade-offs

→ Noise figure

*Noise Figure Comparison of SiGe, Si & GaAs Technologies*

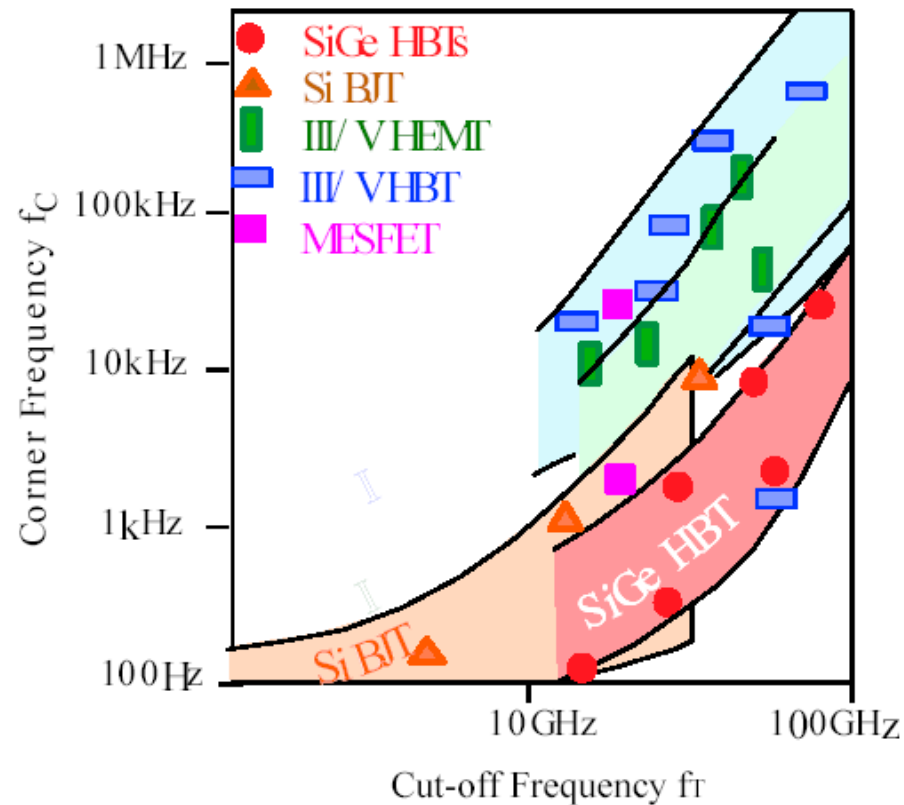




# Trade-offs

→ 1/f noise

*Low Frequency Phase Noise of SiGe, Si & GaAs Technologies*



# Trade-offs

→ Costs

Item	GaAs		SiGe		Units
	FET	HBT	HBT	BiCMOS	
Feature Size	0.5	2.0	0.5	0.5	μm
Starting Material	200	600	200	200	\$
Mask steps	12	14	28	32	
Photo cost	1200	1400	2800	3200	\$
Raw cost	1400	2000	3000	3400	\$
Wafer Diameter	100	100	200	200	mm
Yield	80	70	95	95	%
Cost/mm <sup>2</sup>	0.22	0.36	0.10	0.11	\$/mm <sup>2</sup>

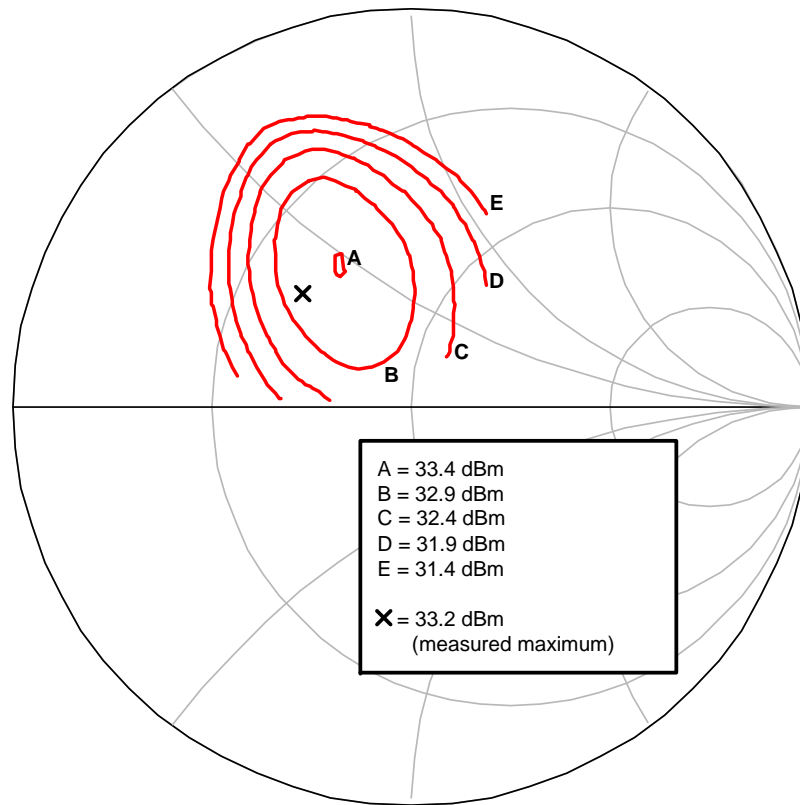
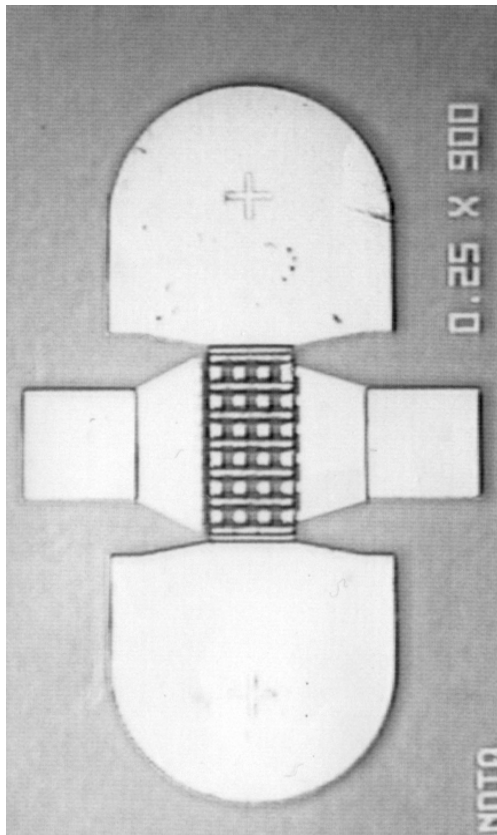
# Trade-offs

→ Power and linearity

Technology	Price/Watt	Power Density	Supply Voltage	Linearity	Frequency	PAE
Si BJT	Low Cost	Medium	26 V	Poor	<2 GHz	Low
SiGe BJT	Low Cost	Medium	<20 V	Good	>2 GHz	High
Si LDMOS	Low Cost	Low	26 V	Very Good	<3 GHz	Medium
GaAs MESFET	Competitive	Medium	12 V	Good	>2 GHz	Medium
GaAs pHEMT	Medium	Medium	8 V to 12 V	Very Good	>2 GHz	High
GaAs HBT	Competitive	High	8 V to 26 V	Good	>2 GHz	High
SiC MESFET	Competitive	Very High	48 V	Good	>4 GHz	Medium
GaN HEMT	N/A	Very High	48 V	Promising	>12 GHz	High

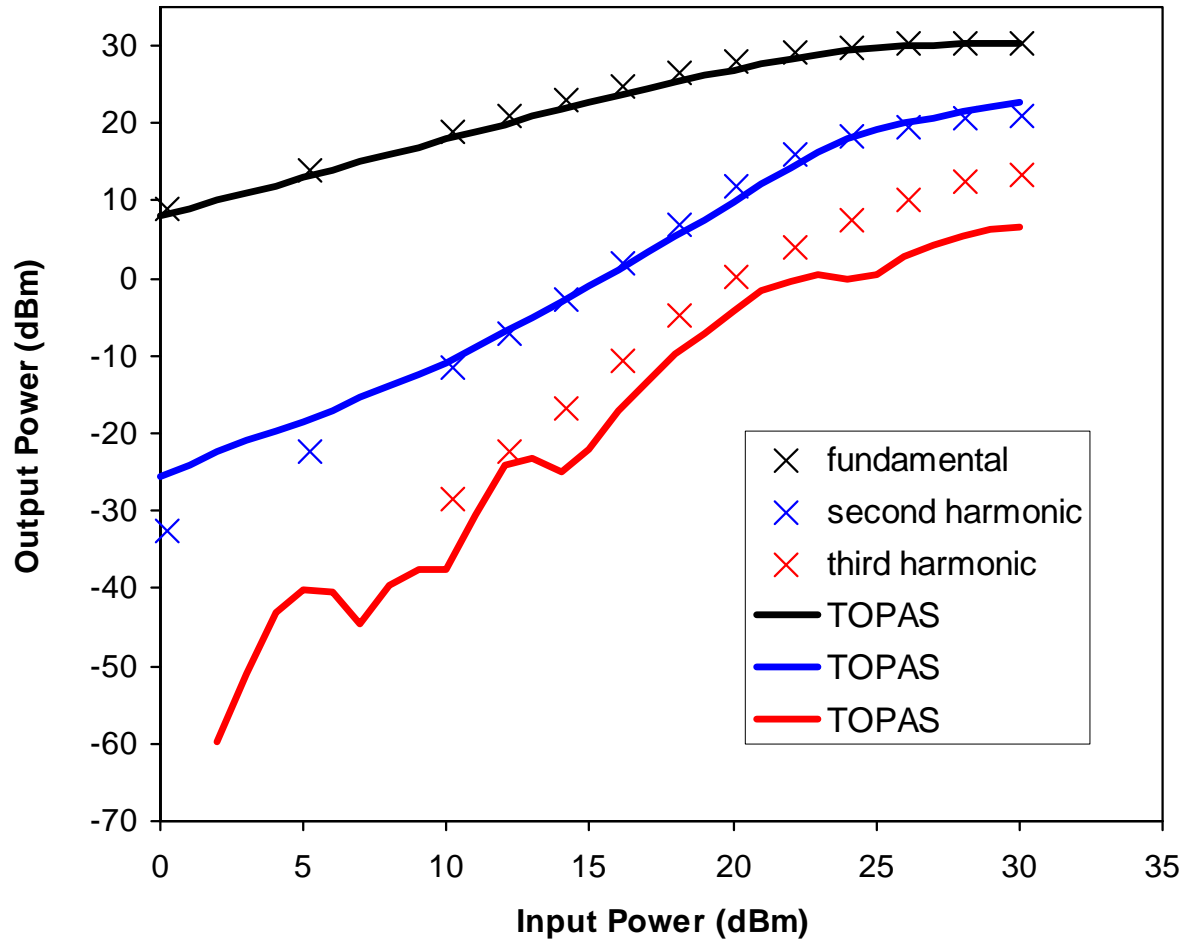
# GaN devices

→ Non-linear model and measurement



# GaN devices

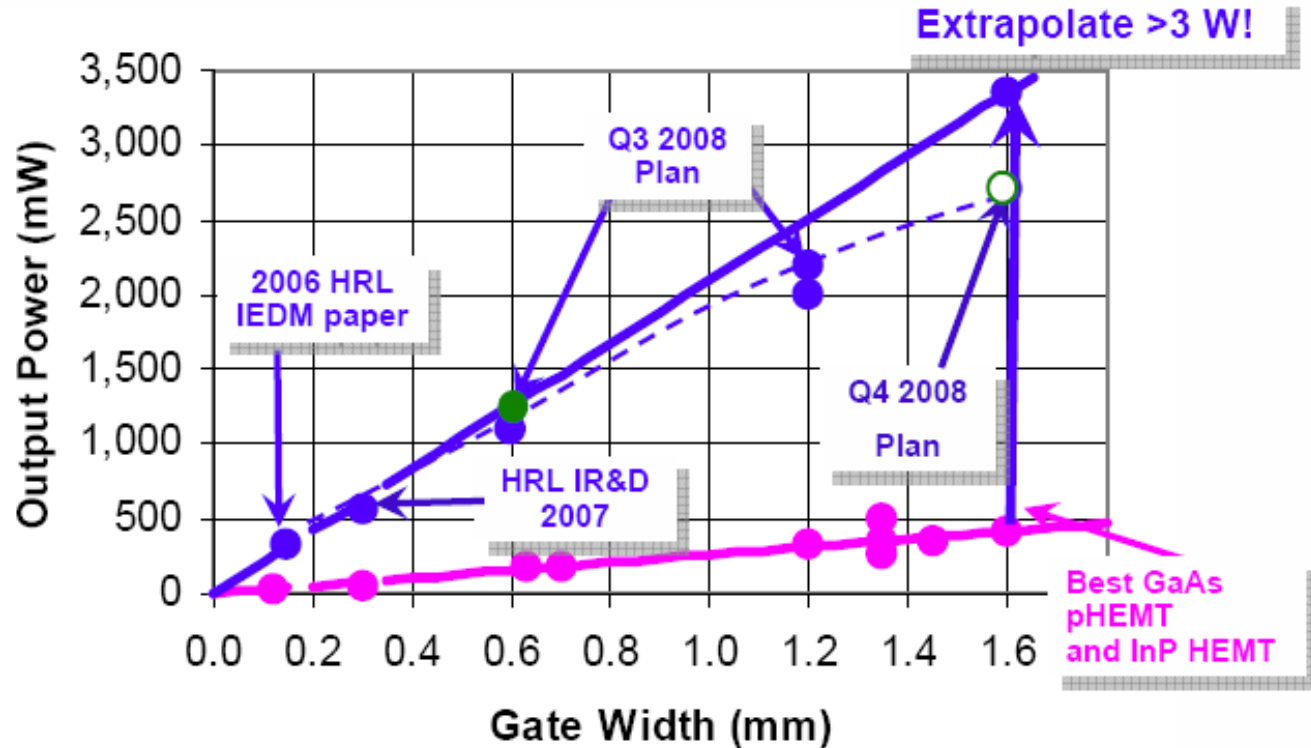
→ Model verification



# GaN mmwave power



## HRL W-band GaN Roadmap



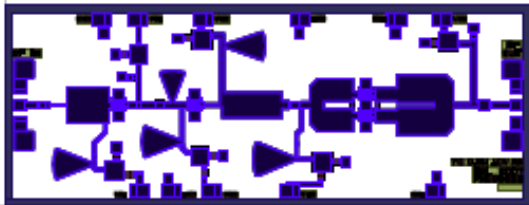
**Disruptive W-band GaN Power MMICs**  
**8X higher power density than mmW GaAs pHEMT**



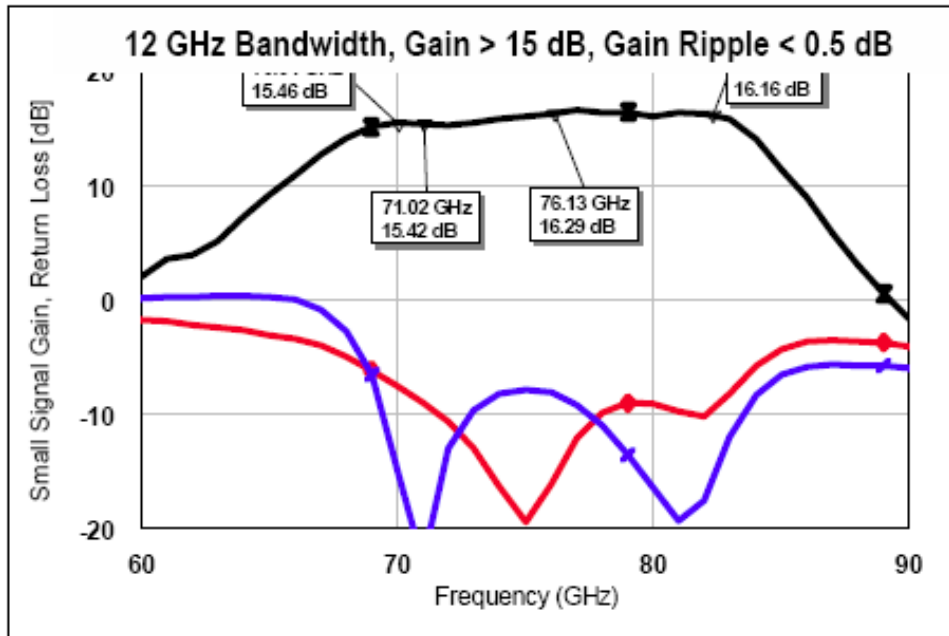
# GaN mmwave PA



## 500 mW 70 GHz GaN MMIC PA



70 GHz MMIC Chip Layout  
Size 3.4 mm x 1.3 mm  
Operating Voltage = 15 V  
Measured Gain > 15 dB



Measured small signal gain of 70 GHz 500 mW GaN MMIC PA.

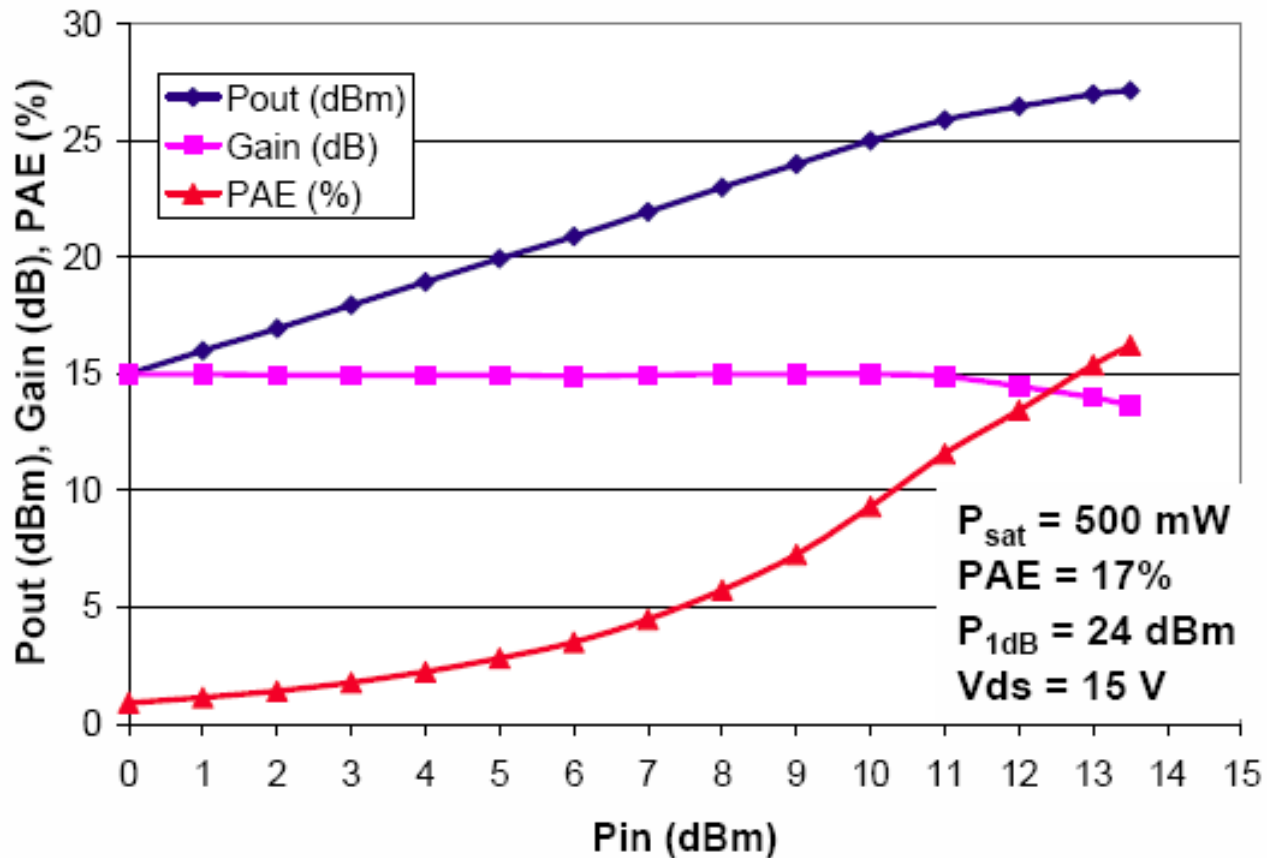
Performance meets design goal.



# GaN mmwave PA

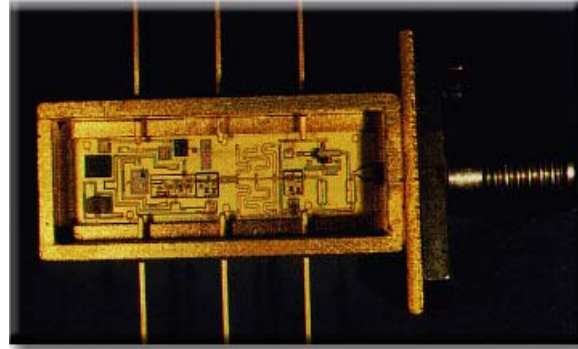


Output power of 70 GHz MMIC measured at a frequency of 76 GHz



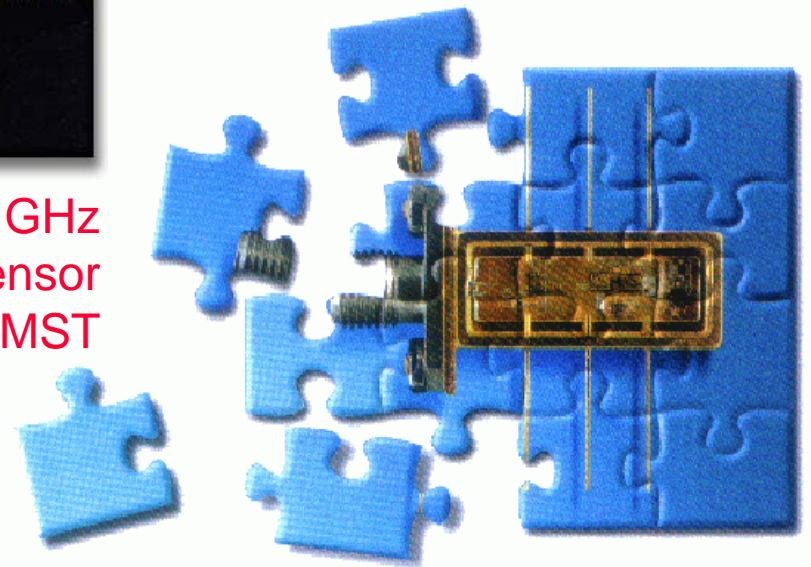


# Integrated coplanar 24 GHz sensor



Many pieces – one solution  
M5-Service.

World's 1<sup>st</sup> 24 GHz  
coplanar sensor  
designed at IMST



Rosemount 24 GHz level sensor

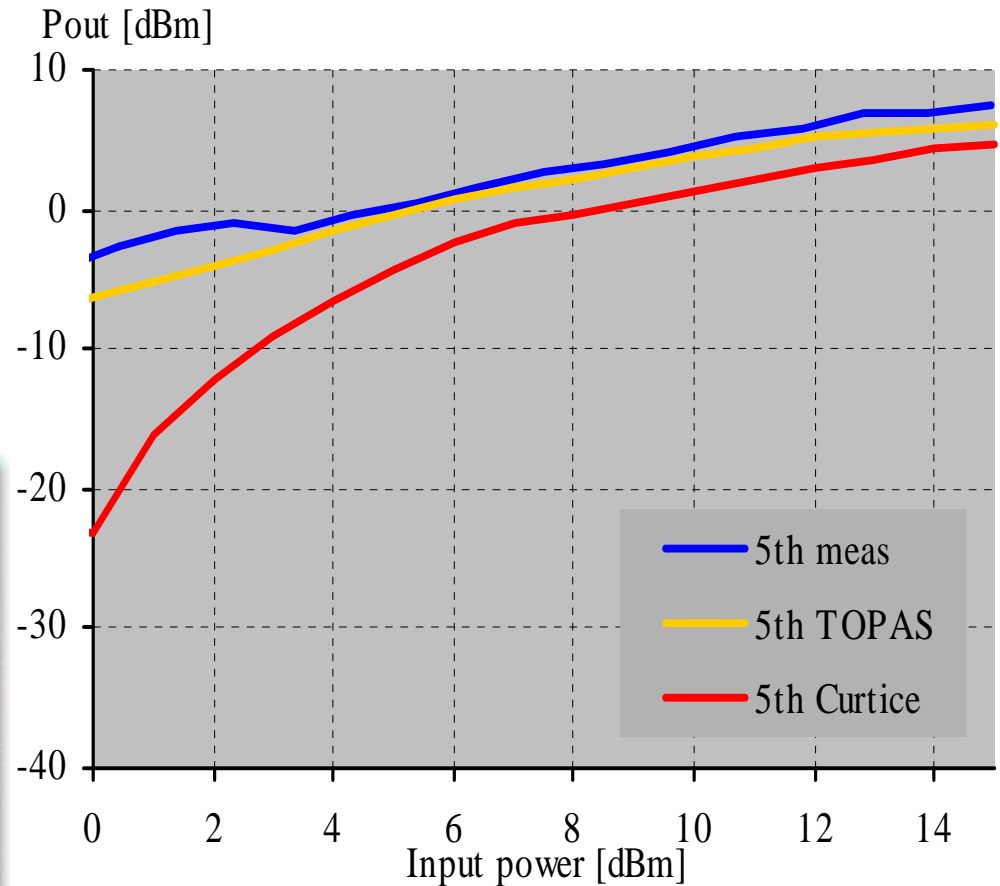
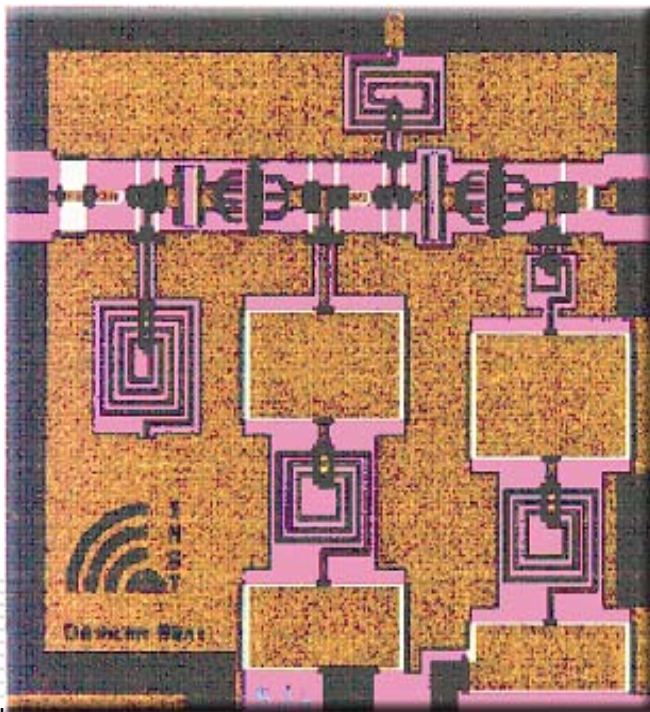


M5 Service is our understanding  
of a comprehensive service in

Microwave / Millimeterwave  
Module Engineering and  
Manufacturing.

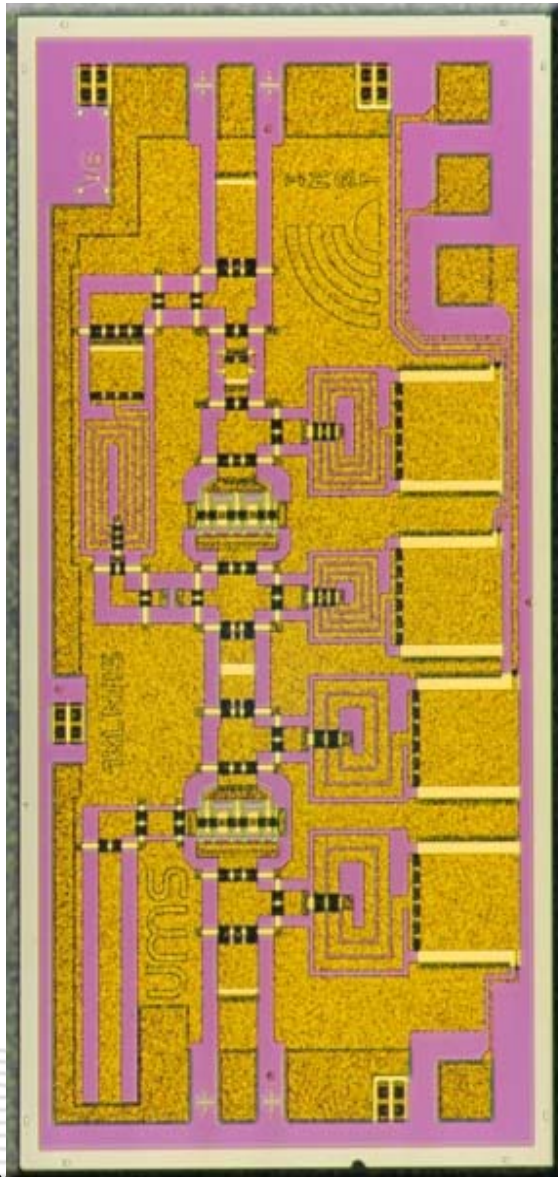
# Integrated GaAs circuits – 24 GHz sensor

Simulated using  
**TOPAS**

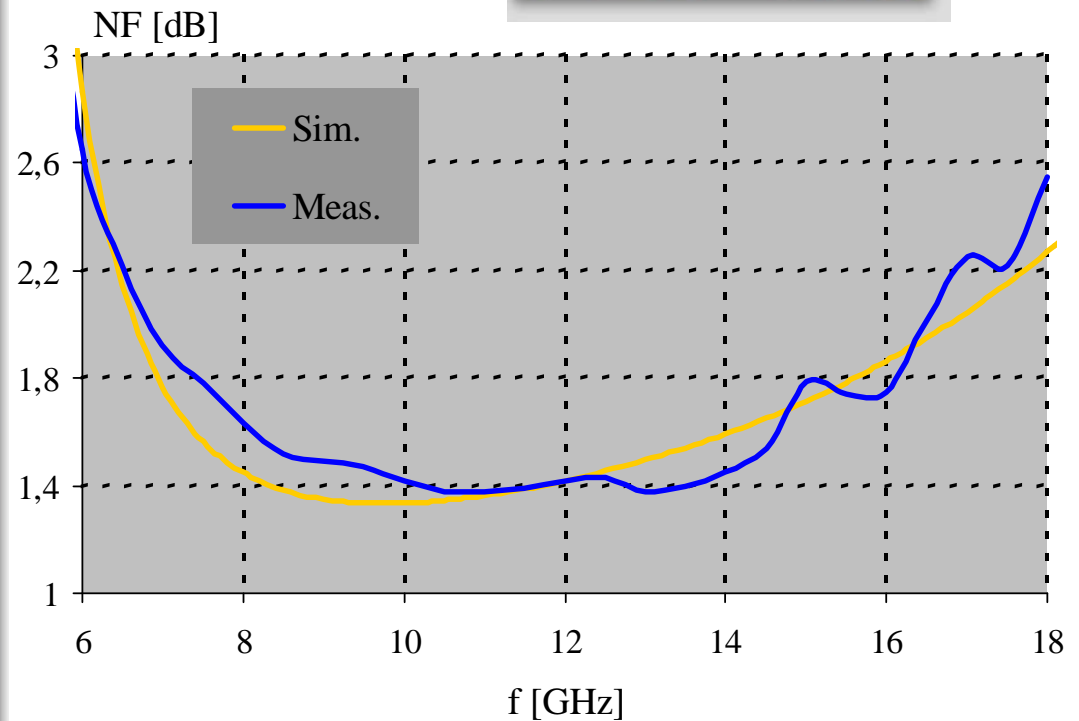


Frequency times 5 multiplier

# GaAs circuits – 10 GHz LNA



Simulated  
using



Low noise amplifier

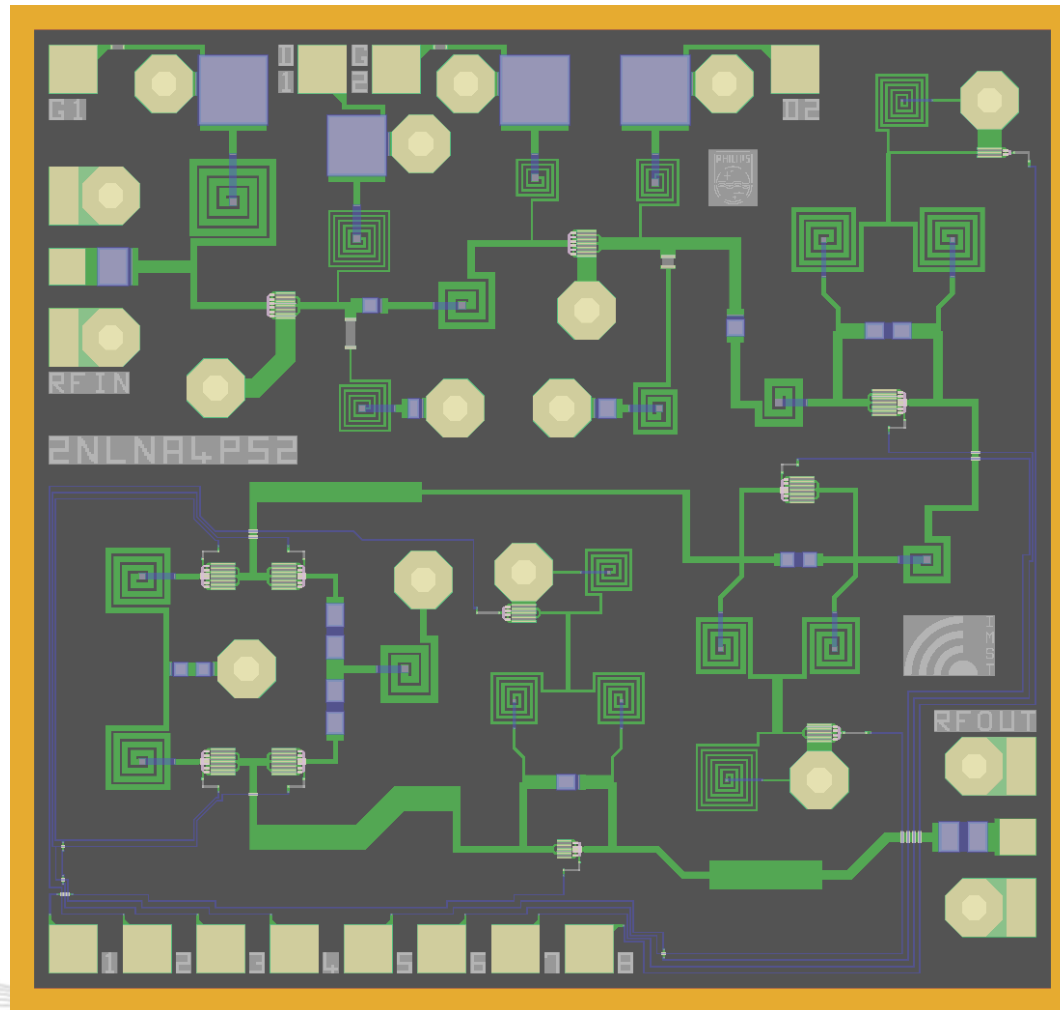
# Core Chip Design : 2NLNA4PS2

## Specifications:

- Ku-band core chip including the 2-stage LNA and the 4-bit phase shifter
- Technology: OMMIC - ED02AH
- LNA bias supply:  $V_{G1,2} = -0.2 \text{ V}$ ,  $V_{D1,2} = 2.0 \text{ V}$ ,  $I_{D1} = 28.2 \text{ mA}$ ,  $I_{D2} = 29.0 \text{ mA}$
- PS control voltages:  $V_C = 0 \text{ V} / -2 \text{ V}$
- $f = 10.7 \dots 12.7 \text{ GHz}$
- $S_{11} \leq -13.3 \text{ dB}$  (all states)
- $S_{22} \leq -11.6 \text{ dB}$  (all states)
- $S_{21} = 13.2 \dots 14.4 \text{ dB}$  (all states)
- RMS amplitude error = 0.4 dB
- RMS phase error = 2.6 °
- $A = 2.17 \times 2.05 \text{ mm}^2 = 4.45 \text{ mm}^2$ 
  - ⇒ including half dicing street
  - ⇒ including DC pads (#8) for the PS control (not necessary if using the DC control circuit)
  - ⇒ excluding DC control circuit (serial to parallel converter + buffers)

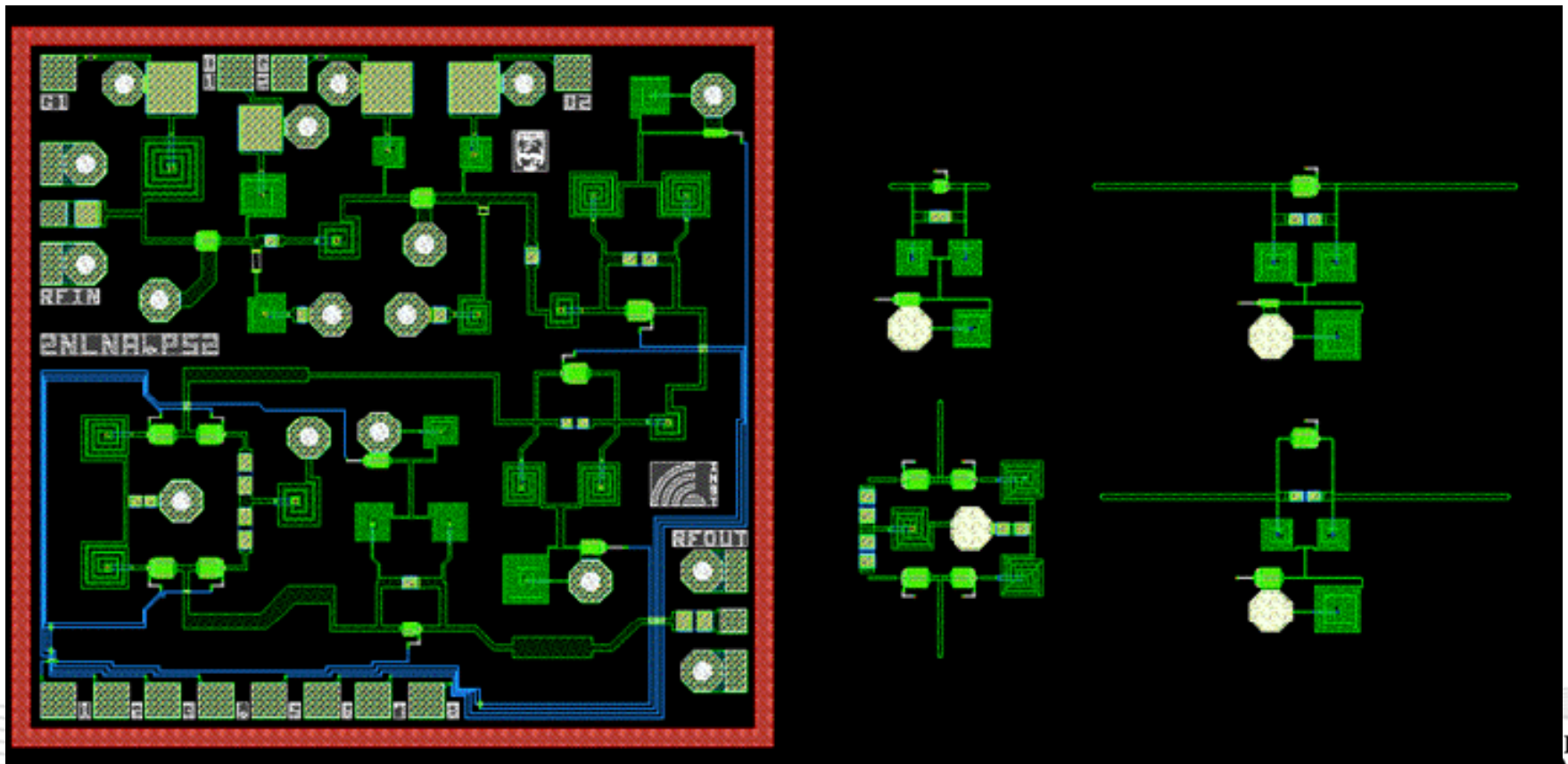
# Core Chip Design : 2NLNA4PS2

Layout:

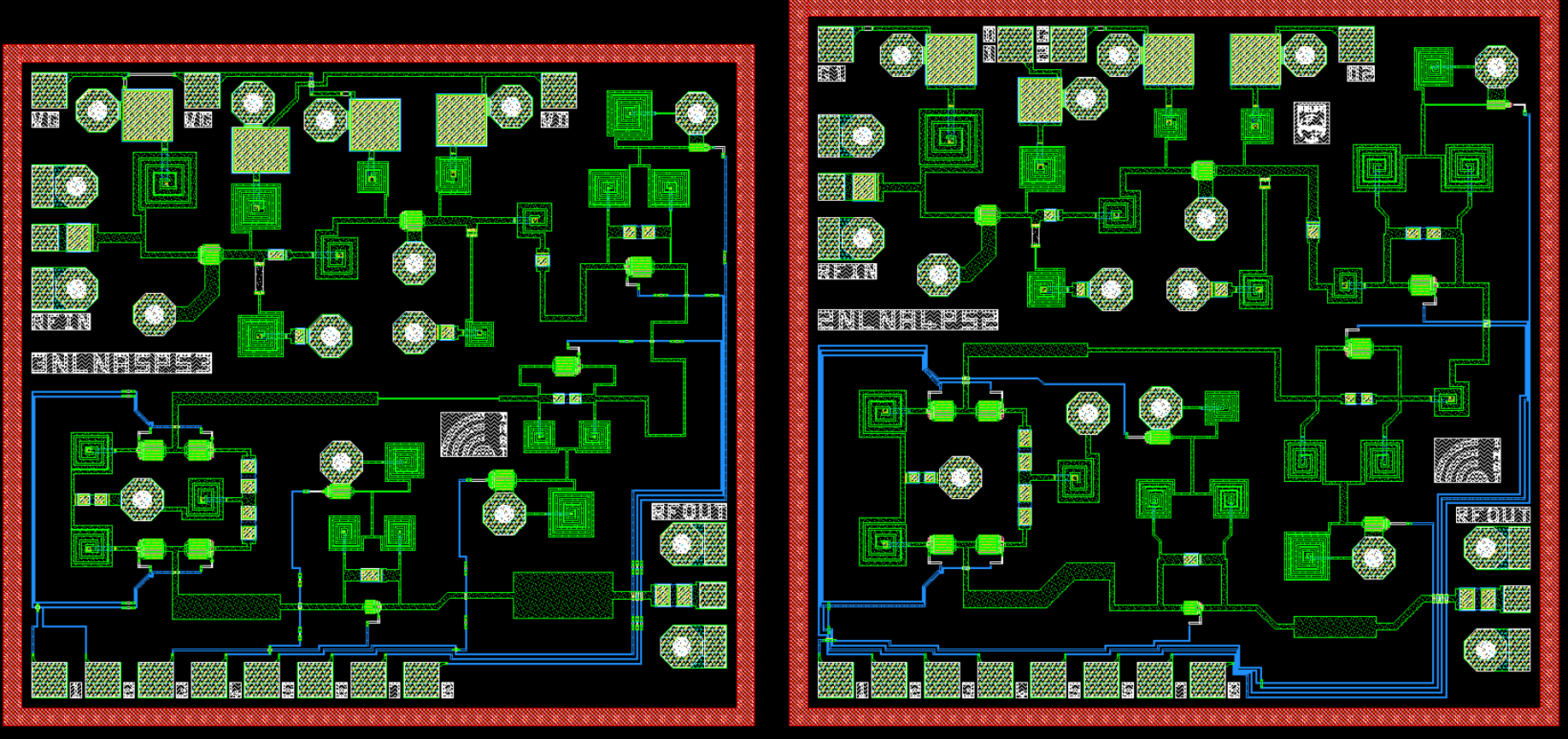


# Momentum simulation

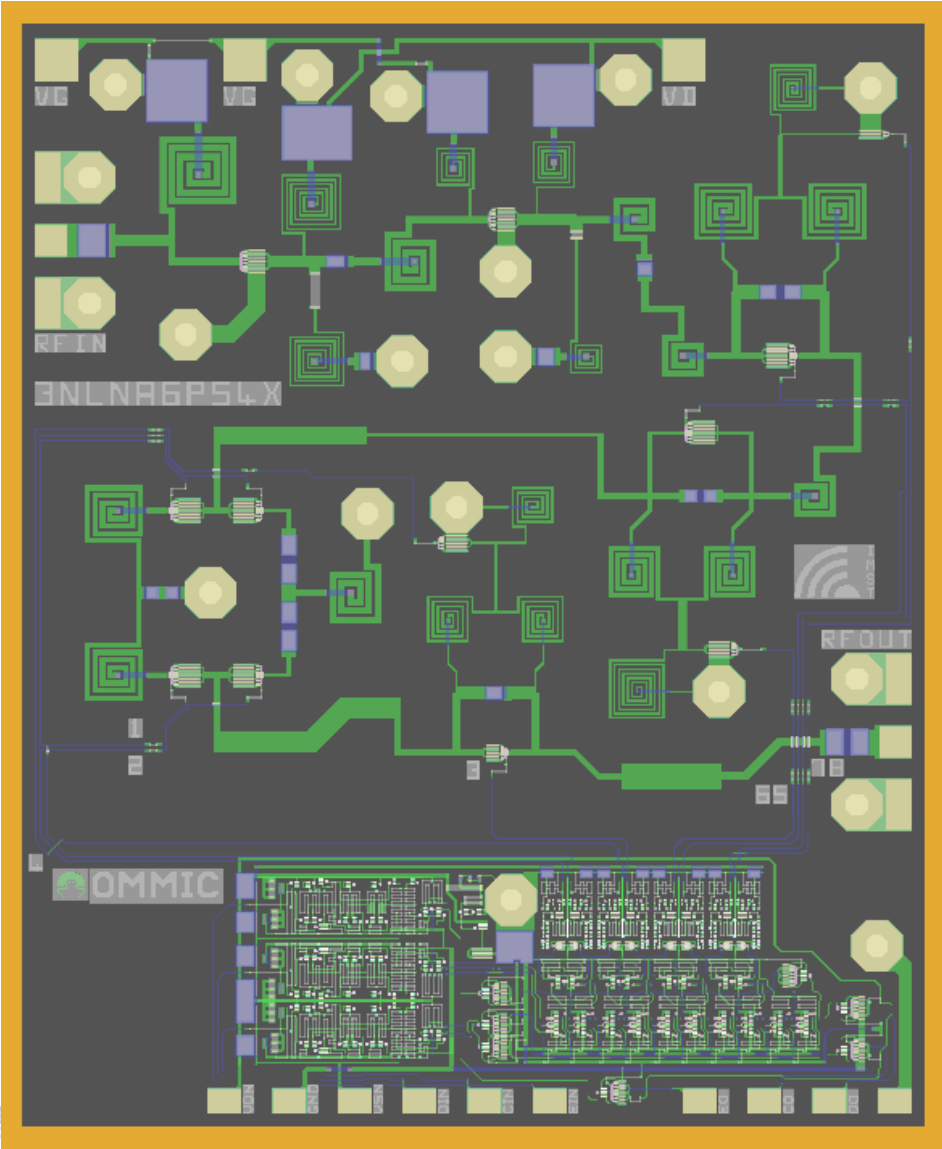
→ Higher integration possible



# Size reduction



# Including logic



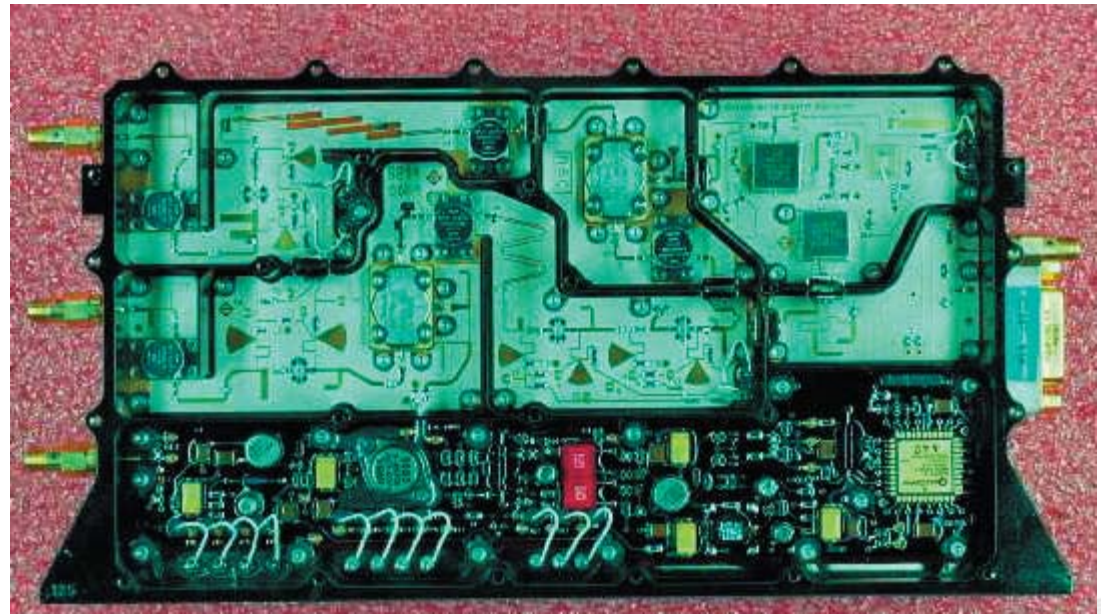


# System example synthesizer



- Large size (LO)
- Heavy
- Single frequency

→ small and integrated chip



[http://www.saabgroup.com/en/ProductsServices/BusinessUnit/saab\\_ericsson\\_space.htm](http://www.saabgroup.com/en/ProductsServices/BusinessUnit/saab_ericsson_space.htm)

<http://products.saabgroup.com/PDBWebNew/GetFile.aspx?PathType=ProductFiles&FileType=Files&Id=6071>

# Phase noise

Simplified Leeson equation

$$L(f_m) = \frac{FkTG}{8Q_L P} \left( \frac{f_r}{f_m} \right)^2$$

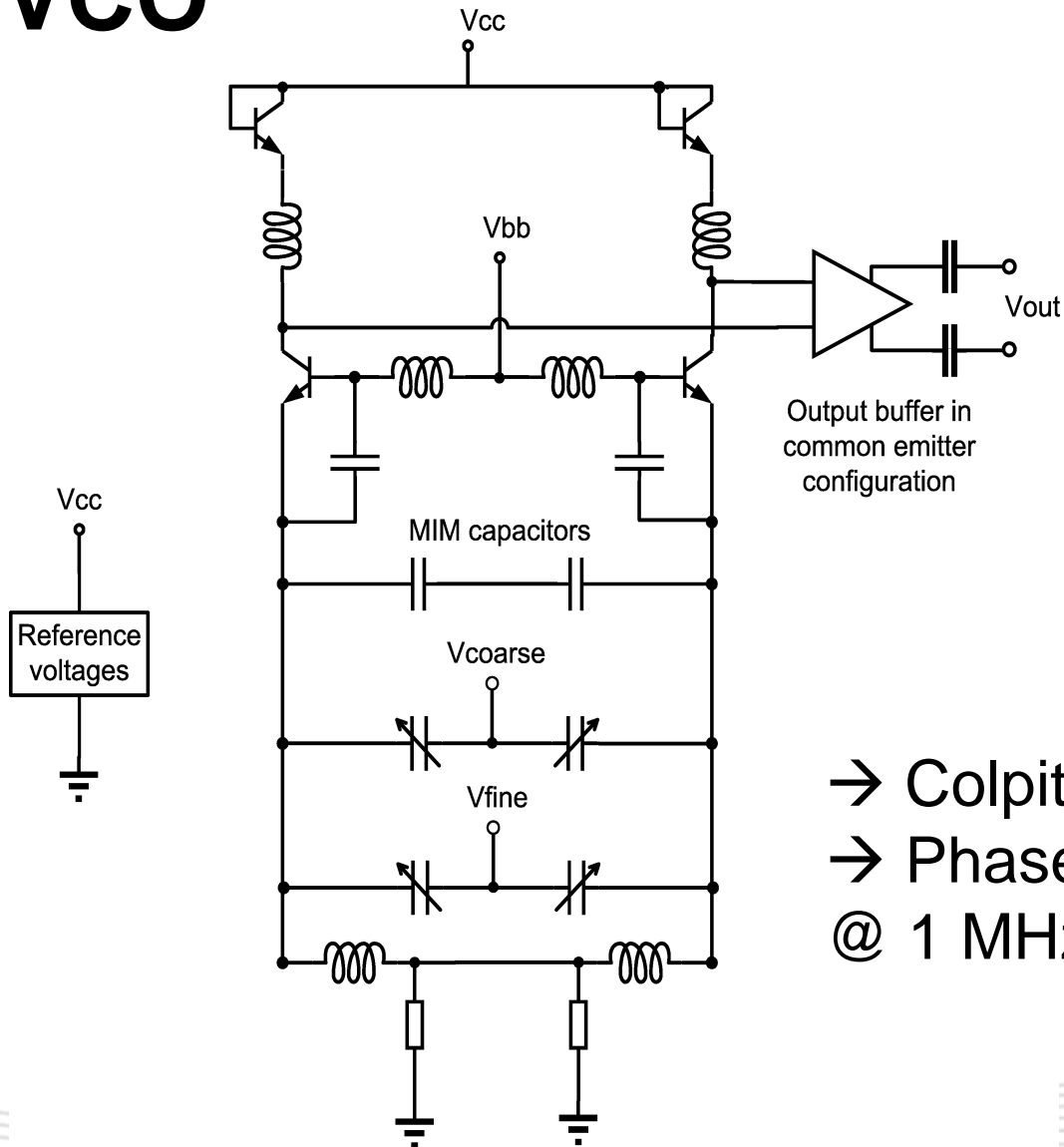
$$|S_{21}| = \frac{1}{G} = 1 - \frac{Q_L}{Q_0}$$

- G: Gain of active part  
F: Noise figure of active part  
Q<sub>L</sub>: Loaded Q of resonator  
f<sub>r</sub>: Resonance frequency  
f<sub>m</sub>: Offset frequency from carrier  
P: Output power of active part  
S<sub>21</sub>: Transmission coefficient of resonator at resonance

# VCO requirement

- High quality factor of the resonator
- Large voltage swing (high output power)
- High breakdown voltage for active part transistor technology
- Use a transistor with low  $1/f$  noise

# VCO



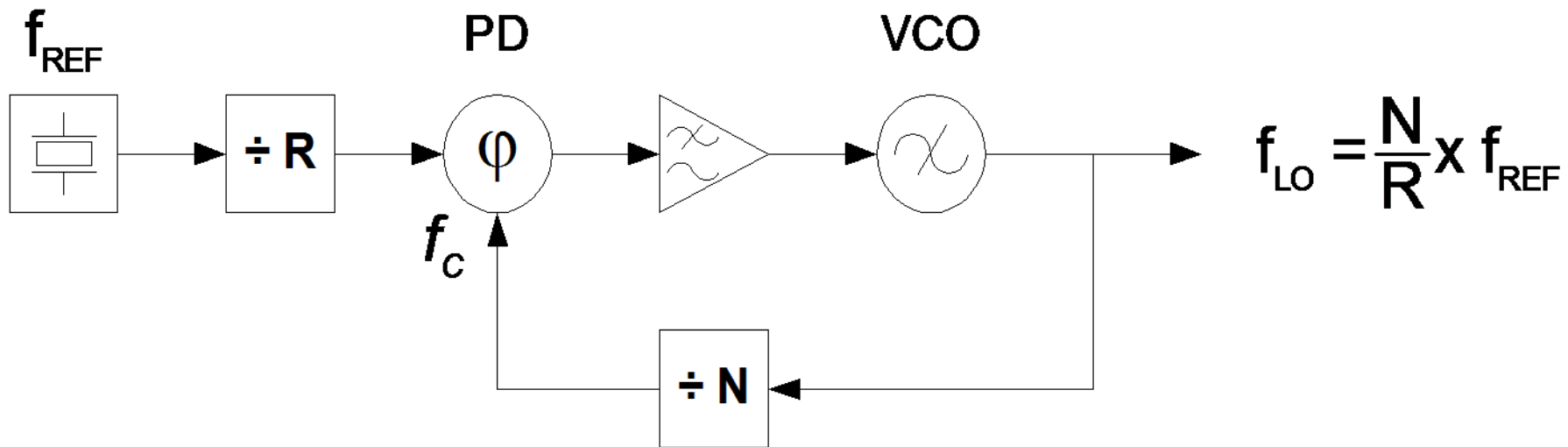
Output buffer in common emitter configuration

- Colpitts
- Phase noise:  $-115 \text{ dBc/Hz}$   
@ 1 MHz offset (20 GHz)

# PLLs

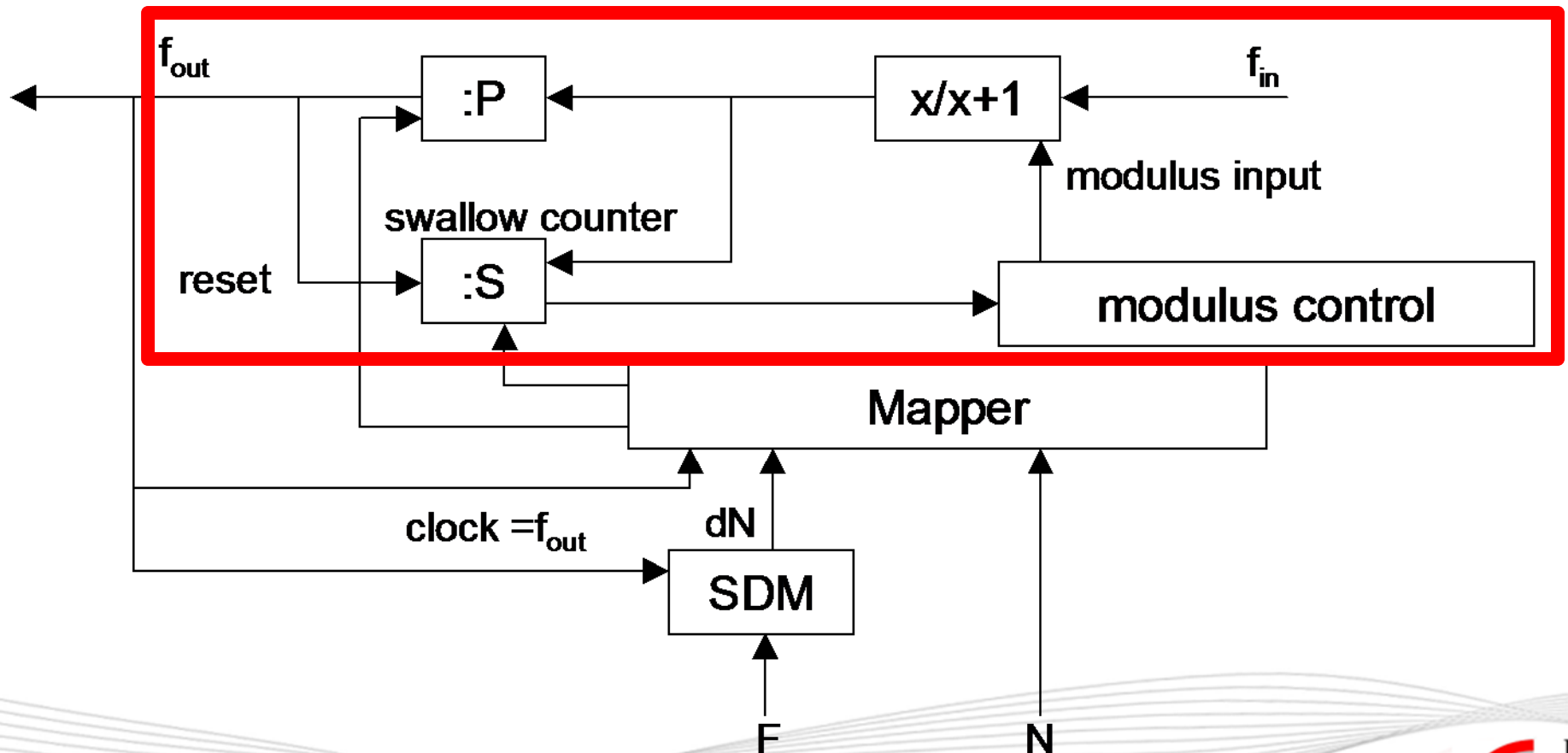
- Close to the carrier phase noise is determined by the reference crystal
- Inside PLL loop the phase noise of a synthesizer is determined by the PLL (phase detector). VCO noise is attenuated.
- Output PLL loop the phase noise of a synthesizer is determined by the VCO phase noise

# Integer-N PLL with reference divider



# How to generate arbitrary frequencies?

→ Build a programmable 1/N-divider



# Continuous division (example $x=8$ )

→ Divide  $S$  times by  $x+1$  and  $P-S$  times by  $x$

$$N=(x+1)*S+x*(P-S)=8*P+S, P>S$$

...

$P=6, S=0..6: N=8*6+0..8*6+7=48..54, 55$  not possible

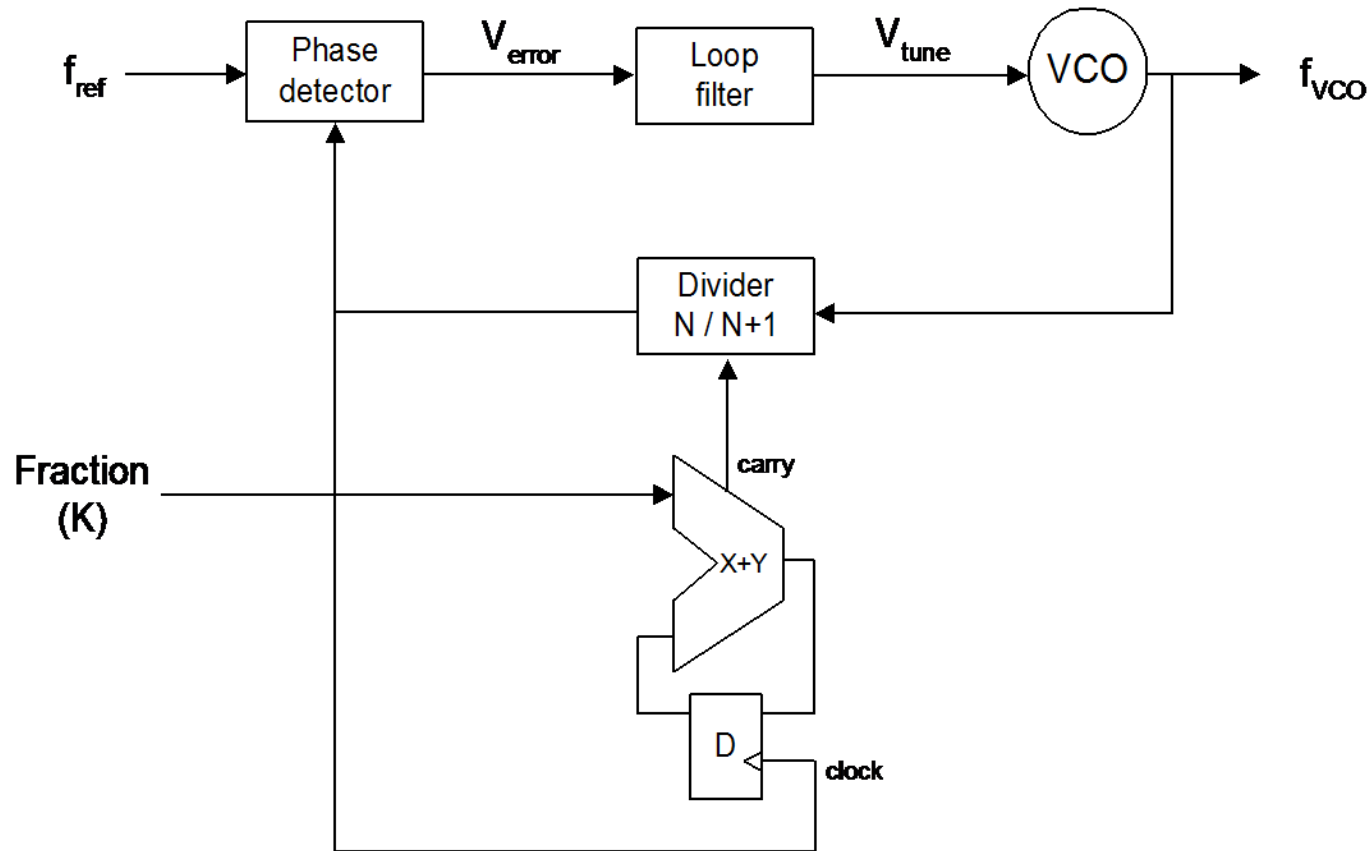
$P=7, S=0..7: N=8*7+0..8*7+7=56..63$

$P=8, S=0..7: N=8*8+0..8*8+7=64..71$

...

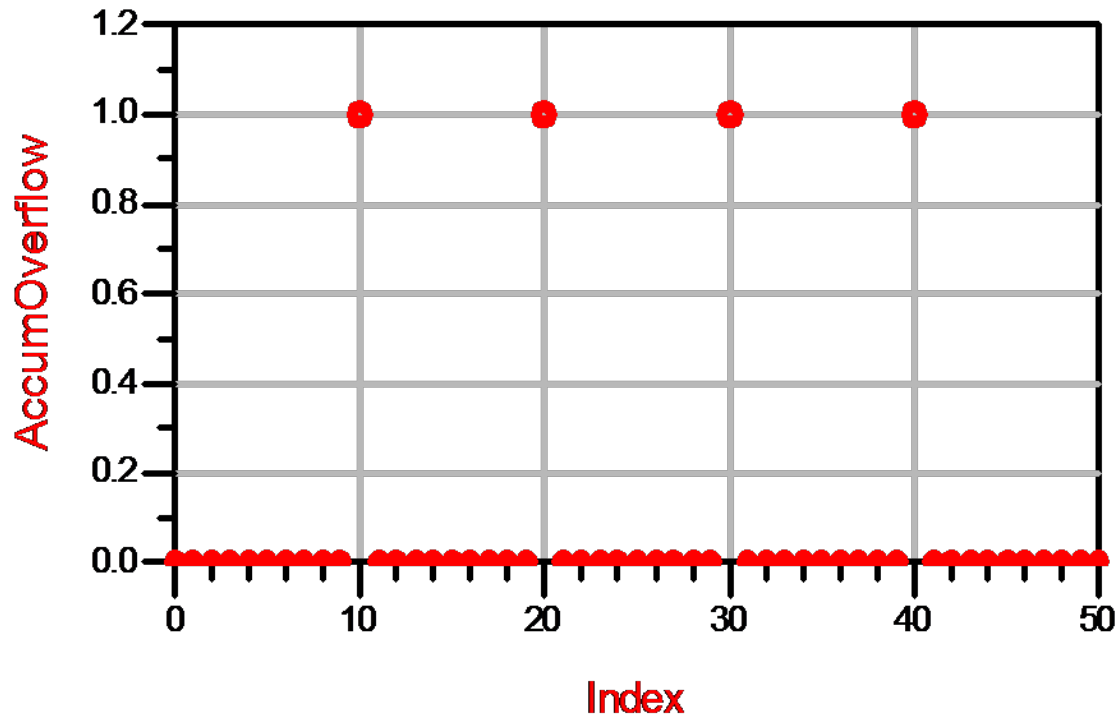


# Simplified fractional-N PLL example



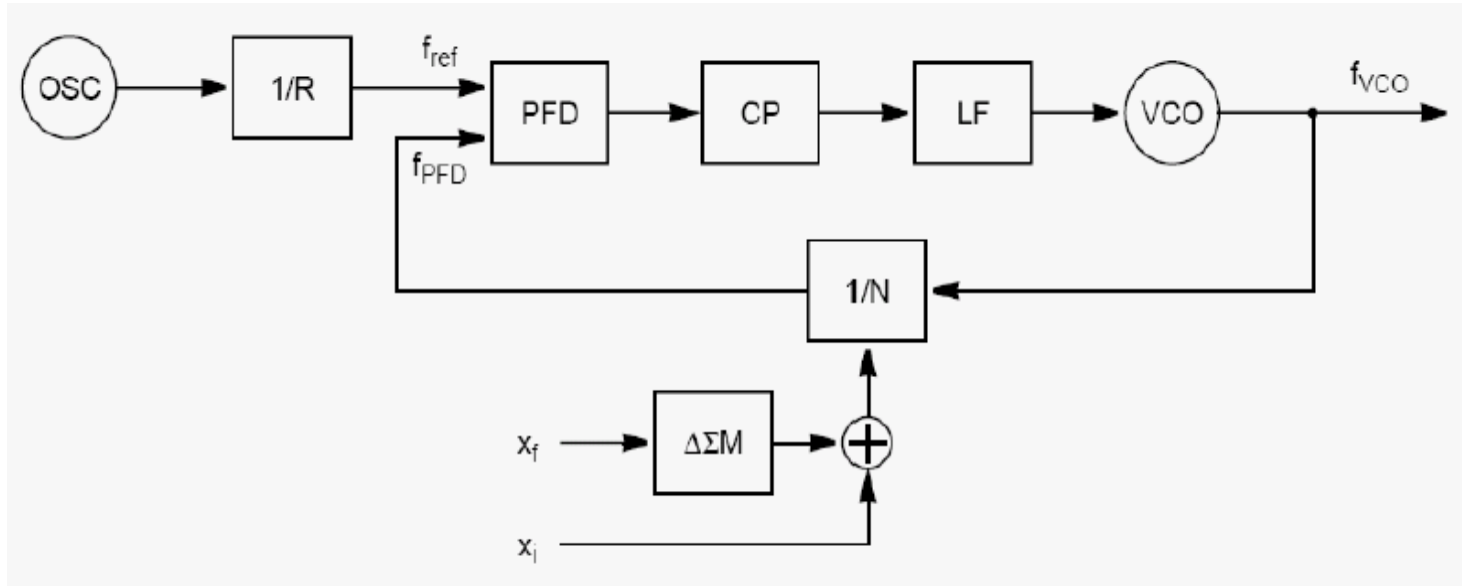
Ratio: 10.1: Divide 9 times by 10 and one time by 11 (next page)

# Accumulator



This division schema generates large spurs.

# Sigma Delta Modulator (SDM)



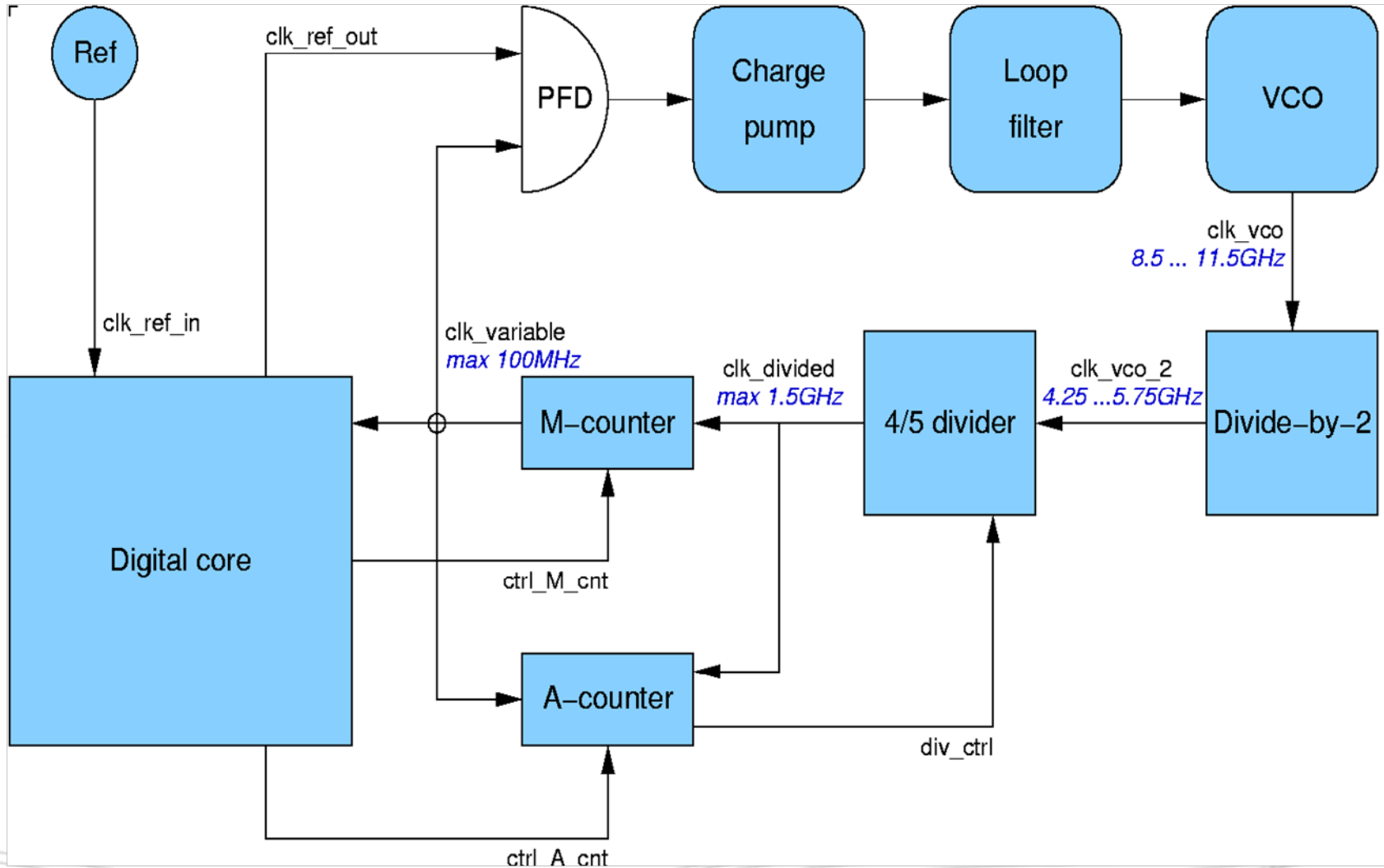
Modulator input: Only fractional part  $x_f$   
 SDM generates series of integer numbers  $n_i$   
 $n_i \in M$ ,  $2^M$  values are available for M

$$x_f = \bar{n}_i = \lim_{N \rightarrow \infty} \frac{1}{N} \sum_{i=1}^N n_i$$

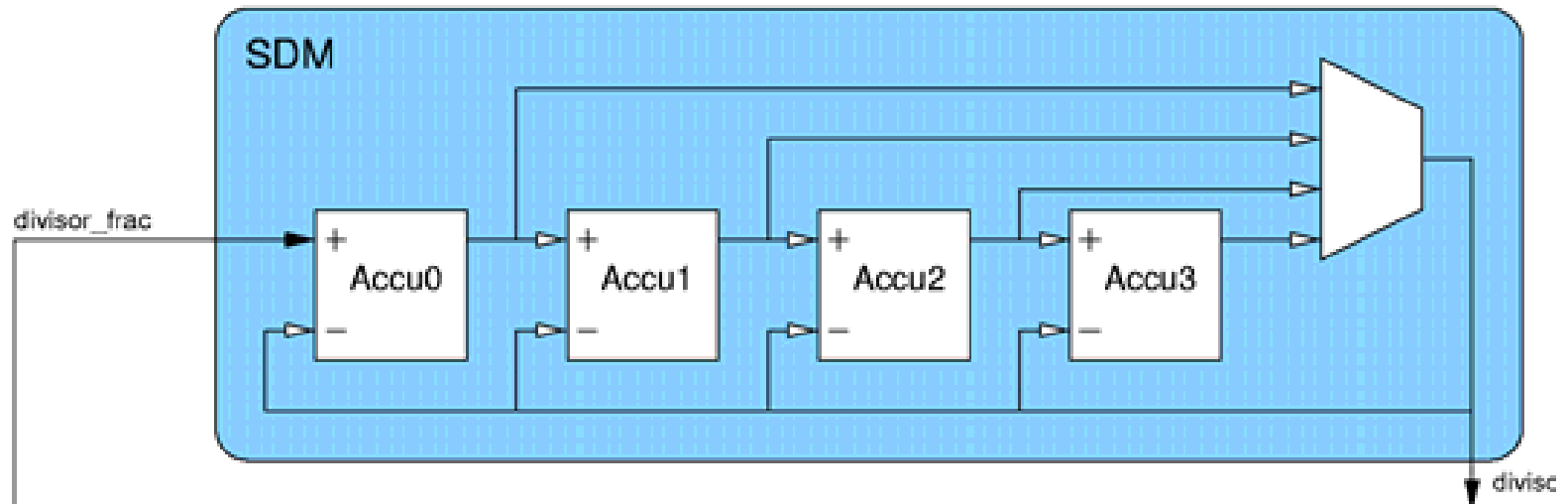
Time average value at SDM output

Example: 2, -4, -2, 3, 0, 3 -1, -3, 2, 1, ... for  $x_f = 0.1$

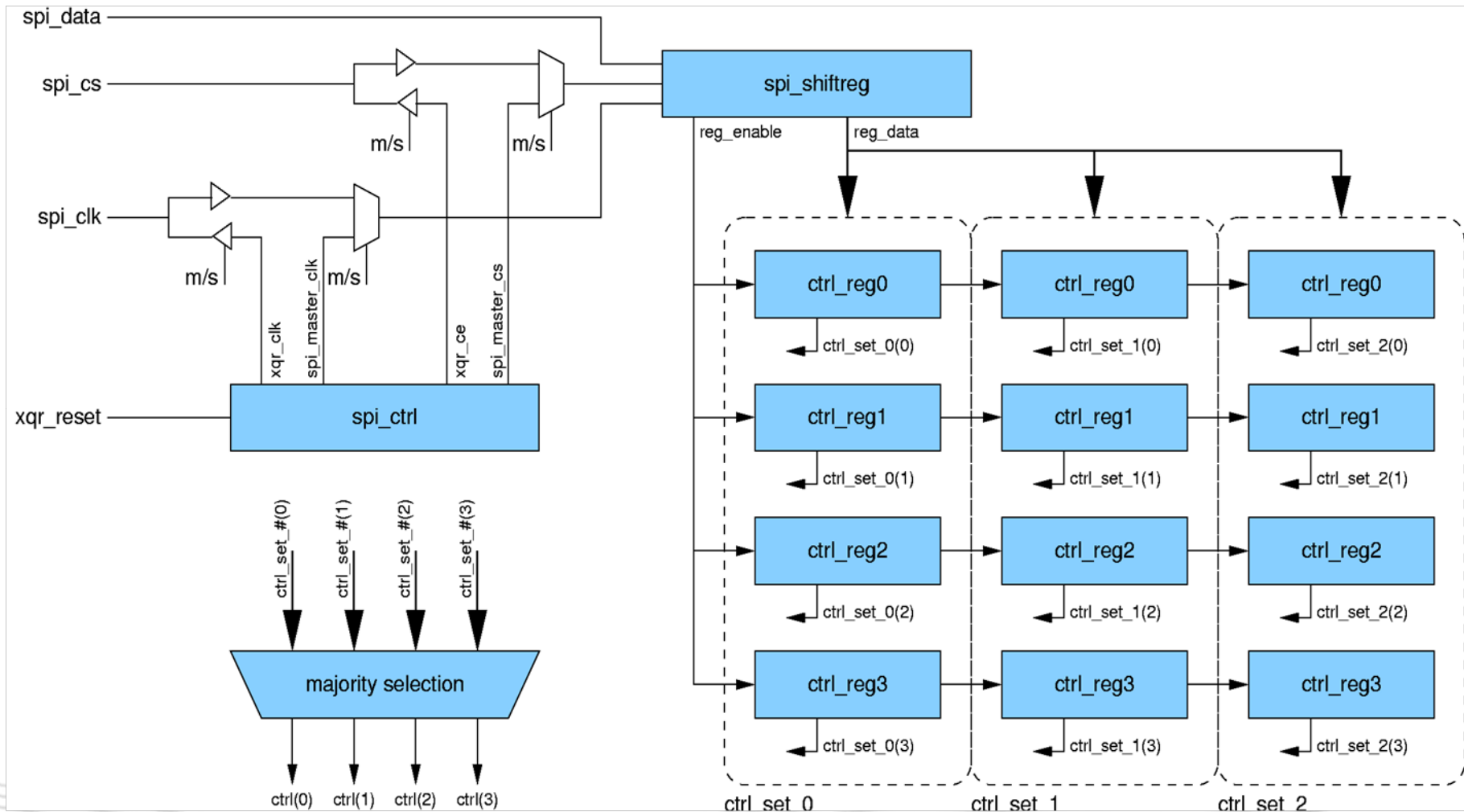
# Synthesizer architecture (1)



# Synthesizer architecture (2)

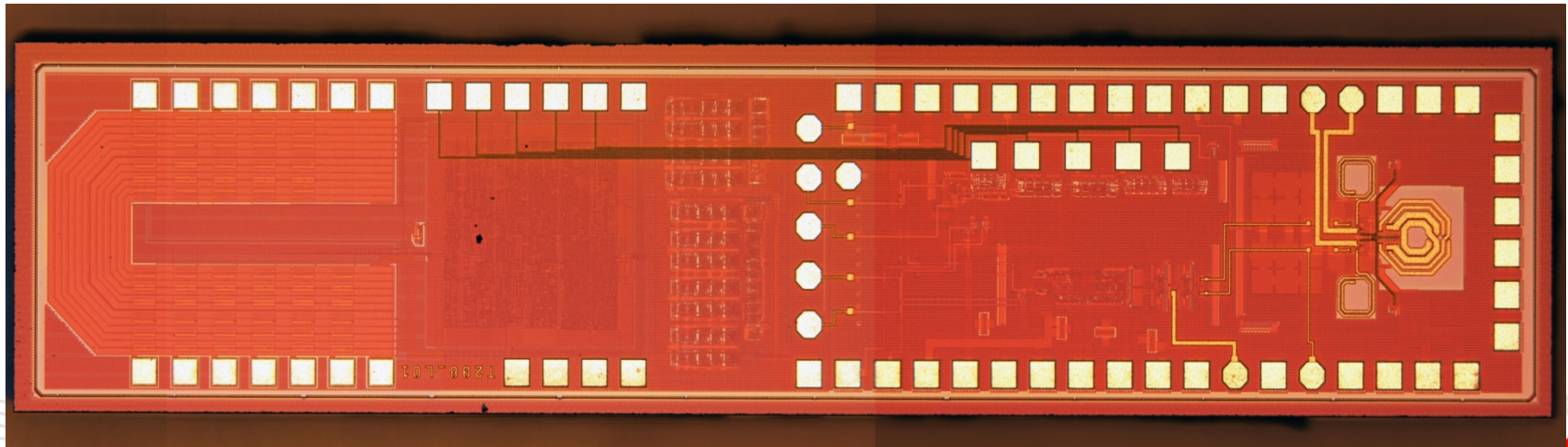


# Synthesizer architecture (3)

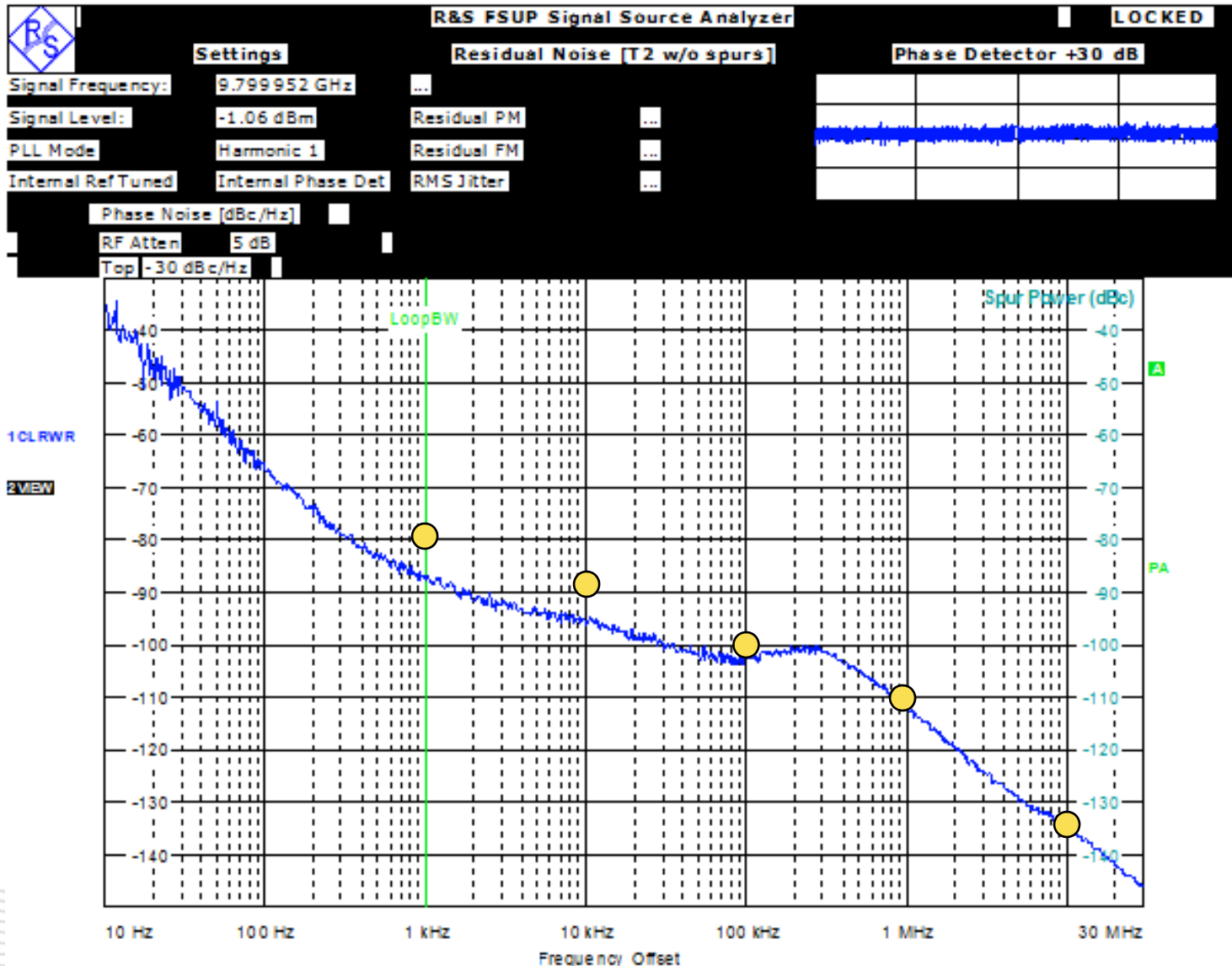


# SiGe Design

- World best 1-chip synthesizer
- 250 MHz-24 GHz PLL
- Integrated 17...20 GHz or 8...12 GHz VCO
- Fractional-N



# Measurement results

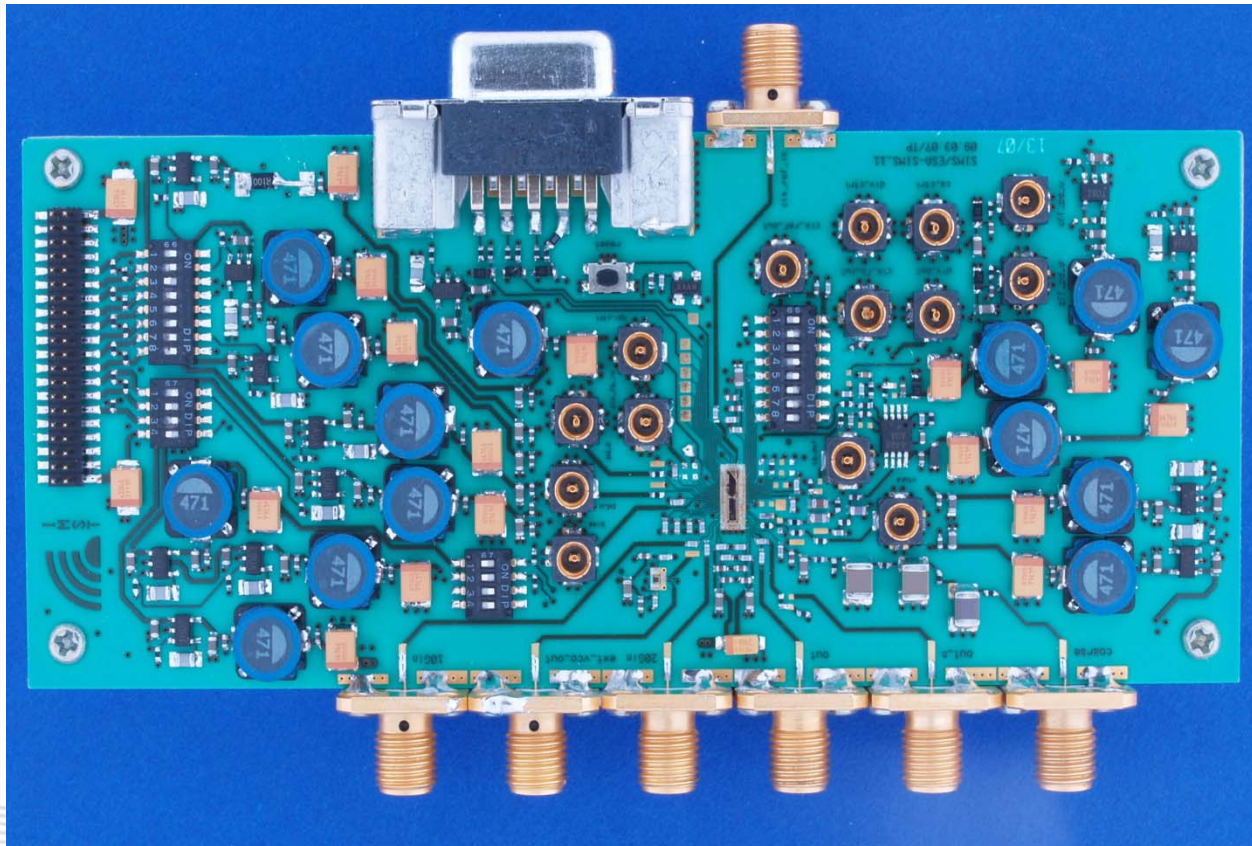




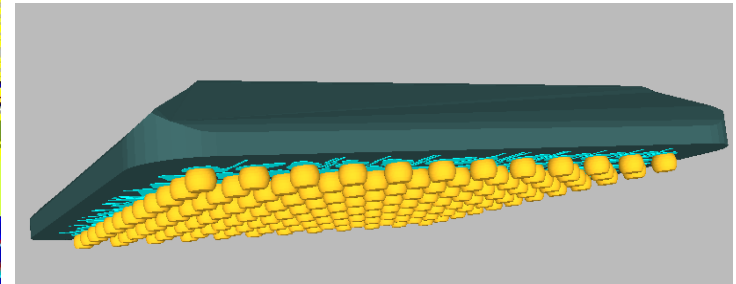
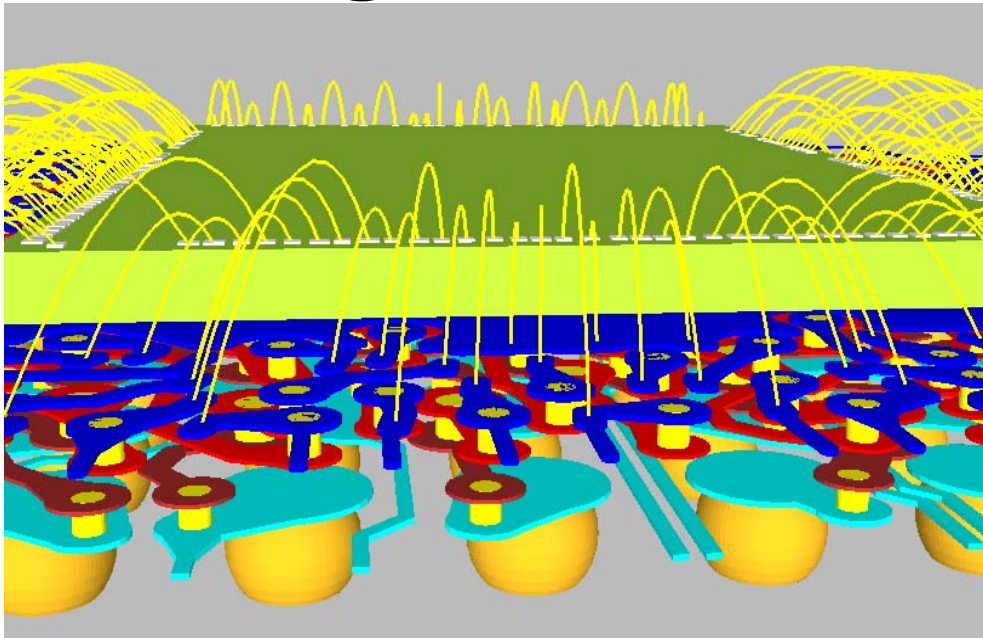
# Synthesizer application test board

→ PC interface

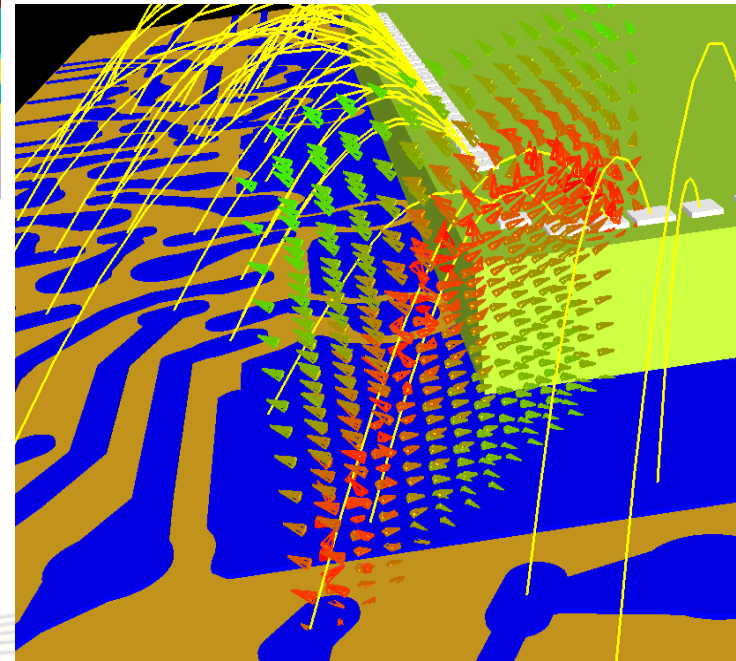
→ Many test ports



# Packages

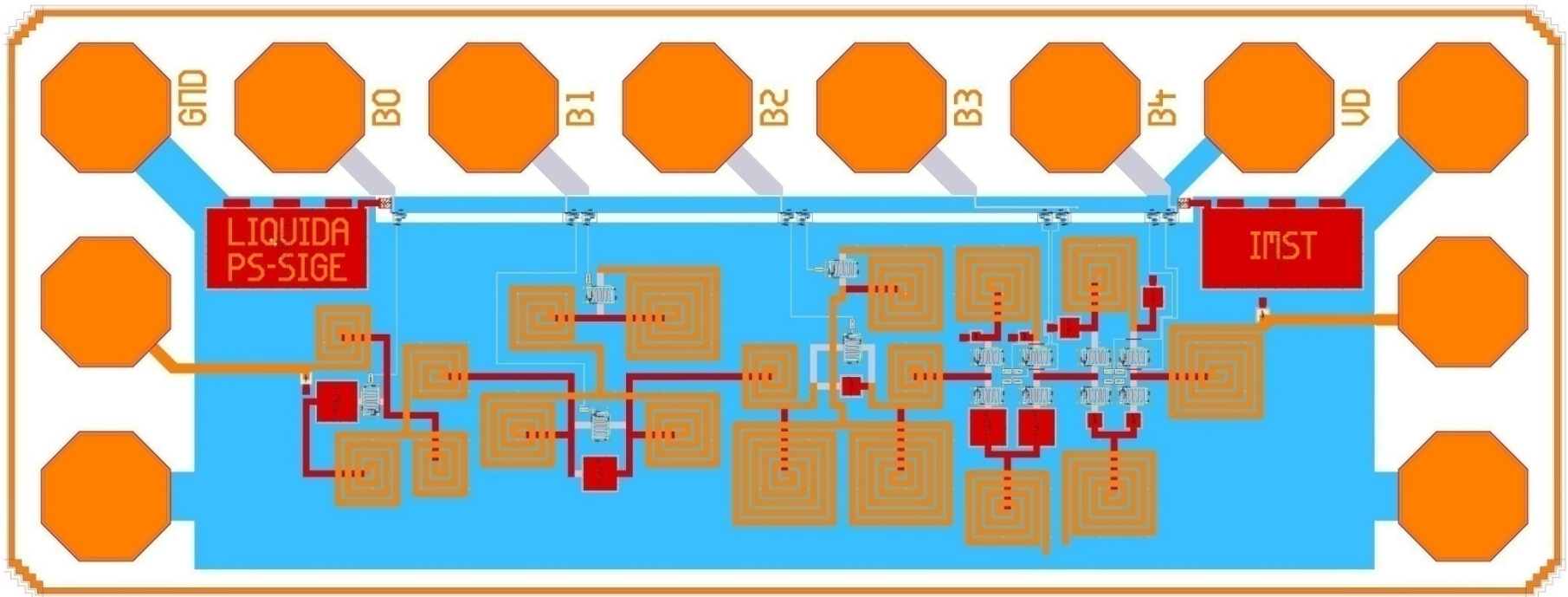


- BGA simulation
- Equivalent circuits
- S-parameter files
- Magnetic field



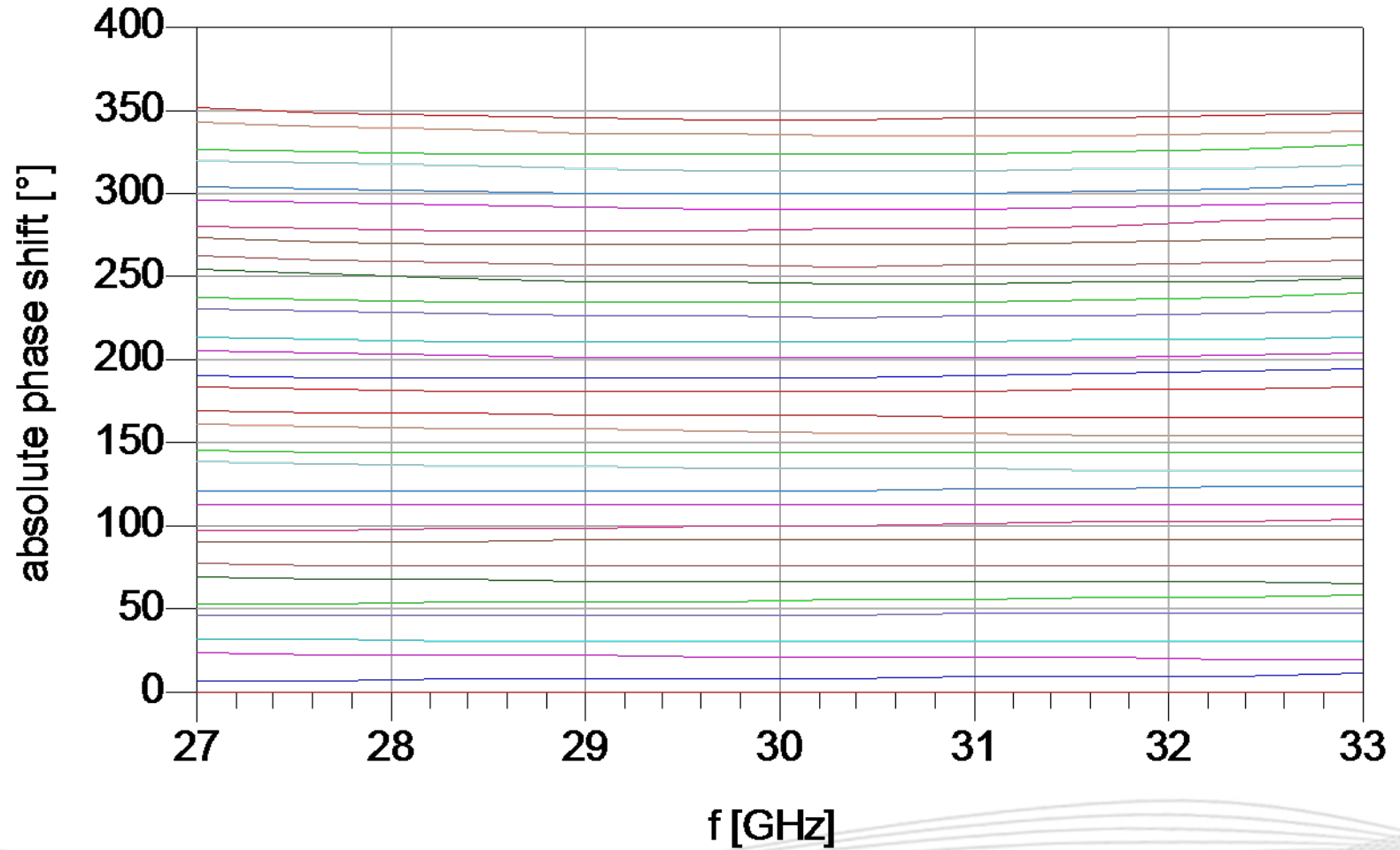
# World smallest phase shifter (ka)

Size 960 x 360  $\mu\text{m}^2$ , Core 620 x 210  $\mu\text{m}^2$



$V_D = 3 \text{ V}$ ,  $V_C (B0-B4) = 0 \text{ V} / 3 \text{ V}$  (active / not active)

# Phase diagram



# Any questions?

